

Berry DG15 Discrete/UMA Schematics Document

Arrandale

Intel PCH

2010-02-24

REV : X01

DY :None Installed
UMA:UMA platform installed
PARK:DIS PARK platform installed
M96:DIS M96 platform installed
*VRAM_1G:VRAM 128M*16 installed*
Colay :Manual modify BOM

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Cover Page

Size
A3

Document Number

Berry

Rev

X01

Date: Wednesday, February 24, 2010

Sheet 1 of 92

Berry Block Diagram (Discrete/UMA co-lay)

Project code : 91.4HH01.001

PCB P/N :

Revision :

CPU DC/DC		ISL62883	47
INPUTS	OUTPUTS		
+PWR_SRC	+VCC_CORE		
SYSTEM DC/DC		TPS51218	49
INPUTS	OUTPUTS		
+PWR_SRC	+1.05V_VTT		
SYSTEM DC/DC		RT8205B	46
INPUTS	OUTPUTS		
+PWR_SRC	+5V_ALW2 +3.3V_RTC_LDO +5V_ALW +3.3V_ALW +15V_ALW		
SYSTEM DC/DC		TPS51116	50
INPUTS	OUTPUTS		
+PWR_SRC	+1.5V_SUS +0.75V_DDR_VTT +V_DDR_REF		
SYSTEM DC/DC		TPS51611	53
INPUTS	OUTPUTS		
+PWR_SRC	+CPU_GFX_CORE		
VGA		RT8208B	89
INPUTS	OUTPUTS		
+PWR_SRC	+VGA_CORE		
TI CHARGER		BQ24745	45
INPUTS	OUTPUTS		
+DC_IN +PBATT	+PWR_SRC		
SYSTEM DC/DC		APL5930	51
INPUTS	OUTPUTS		
+3.3V_ALW	+1.8V_RUN +1.8V_RUN_VGA		
SYSTEM DC/DC		APL5930	90
INPUTS	OUTPUTS		
+1.5V_SUS +5V_ALW +3.3V_ALW	+1.0V_RUN_VGA +5V_RUN +3.3V_RUN		
Switches			
INPUTS	OUTPUTS		
+1.5V_SUS +5V_ALW +3.3V_ALW	+1.5V_RUN +5V_RUN +3.3V_RUN		
PCB LAYER			
L1:Top L2:VCC L3:Signal L4:Signal L5:GND L6:Bottom			

M96 LP; 1GB (64Mx16b*8)
VRAM Hynix 64M
Wistronl P/N:72.51G63.COU
VRAM Samsung 64M
Dell P/N:9TGTN\$AA
Wistronl P/N:72.41164.HOU

Clock Generator
SLG8SP585 7

AMD Graphic
M96-LP
(Discrete only)
80, 81, 82, 83, 84

Intel CPU
Arrandale
8, 9, 10, 11, 12, 13, 14

DDRIII 800/1066 Channel A

DDRIII Slot 0
800/1066 18

DDRIII 800/1066 Channel B

DDRIII Slot 1
800/1066 19

Discreet/UMA Co-lay

FDI x4x2
(UMA only)

DMI x4

HDMI 57
LCD 54

HDMI Level shifter 57
LVDS(Dual Channel)
RGB CRT

CRT
Left Side:
USB x 2

Bluetooth 73
CAMERA 54

Intel PCH HM57
14 USB 2.0/1.1 ports
ETHERNET (10/100/1000Mb)
High Definition Audio
SATA ports (6)
PCIe ports (8)
LPC I/F
ACPI 1.1
PCI/PCI BRIDGE
20, 21, 22, 23, 24, 25, 26, 27, 28

I/O Board Connector
76

Mini-Card
802.11a/b/g

10/100 NIC
Realtek RTL8103T-VB
RJ45 CONN

ESATA/USB
Combo

Mini-Card
WWAN
SIM

Right Side:
USB x 1

CardReader
Realtek RTS5159 78

SD/MMC+/MS/
MS Pro/xD

Azalia CODEC
IDT 92HD79B1 30
Internal Analog MIC
HP1
MIC IN

2CH SPEAKER

Flash ROM
4MB 62

LPC debug port 70

HDD 59

ODD 59

KBC
NUVOTON NPCE781BA0DX 37

Flash ROM
256kB 62

Touch PAD 55

Int. KB 6

Thermal
Main:G7922
Sec:EM62102 3

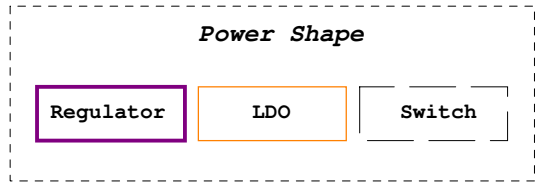
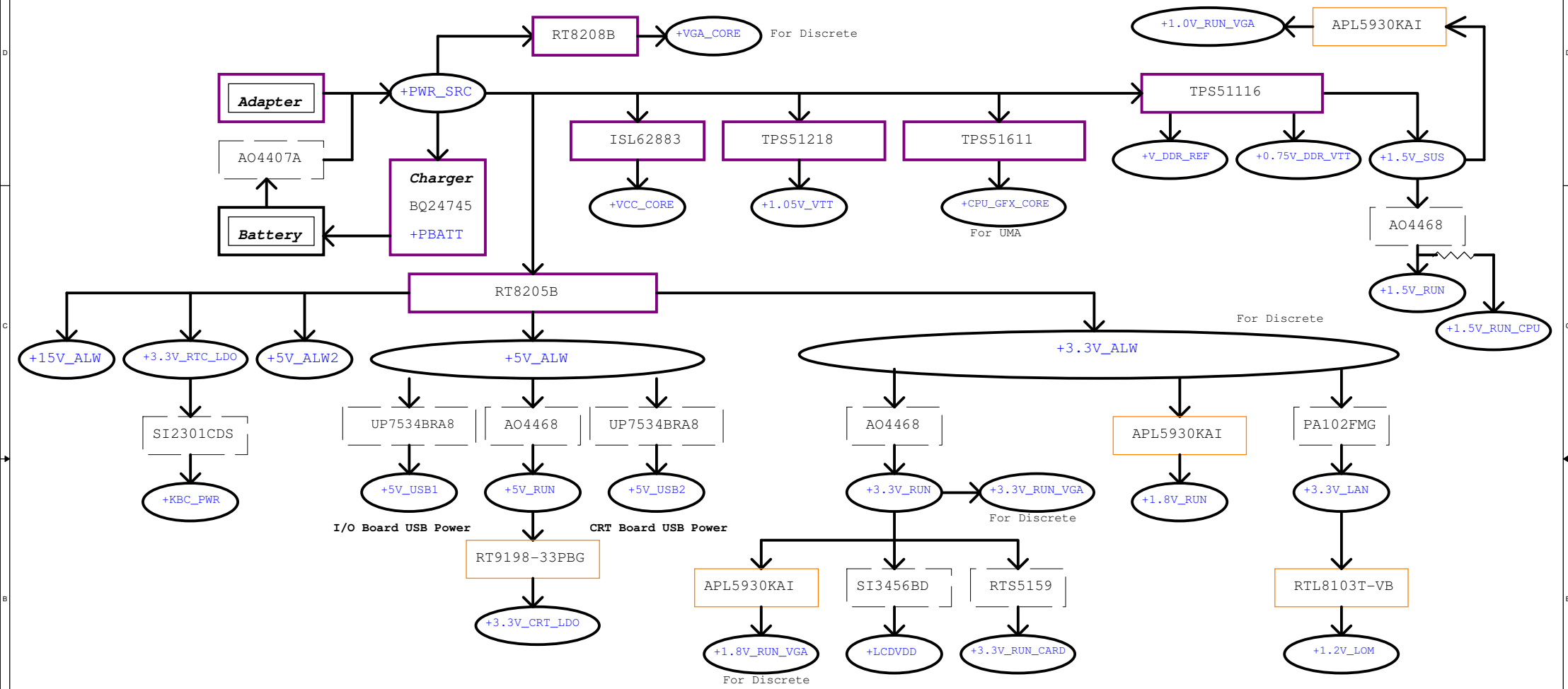
Fan 58

<Core Design>

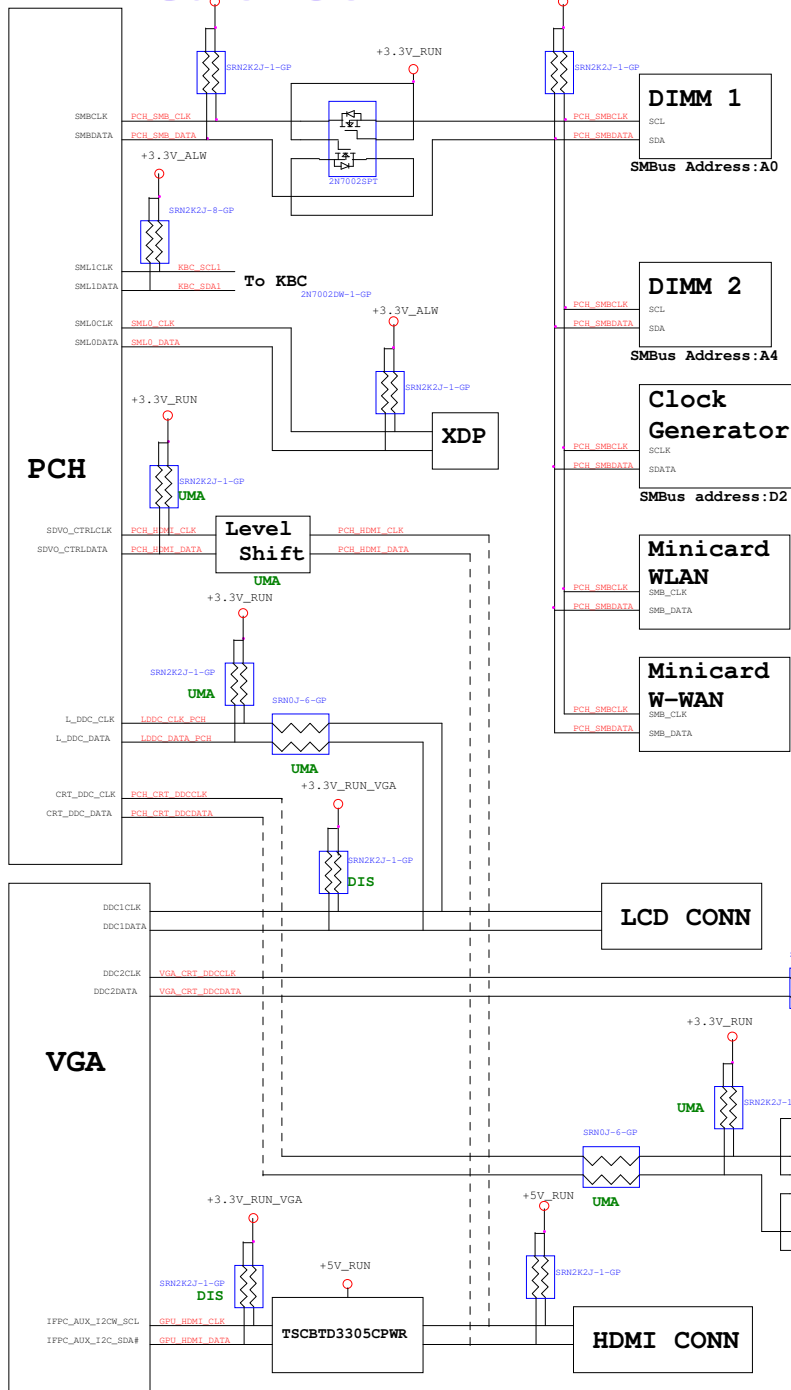
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Title Block Diagram

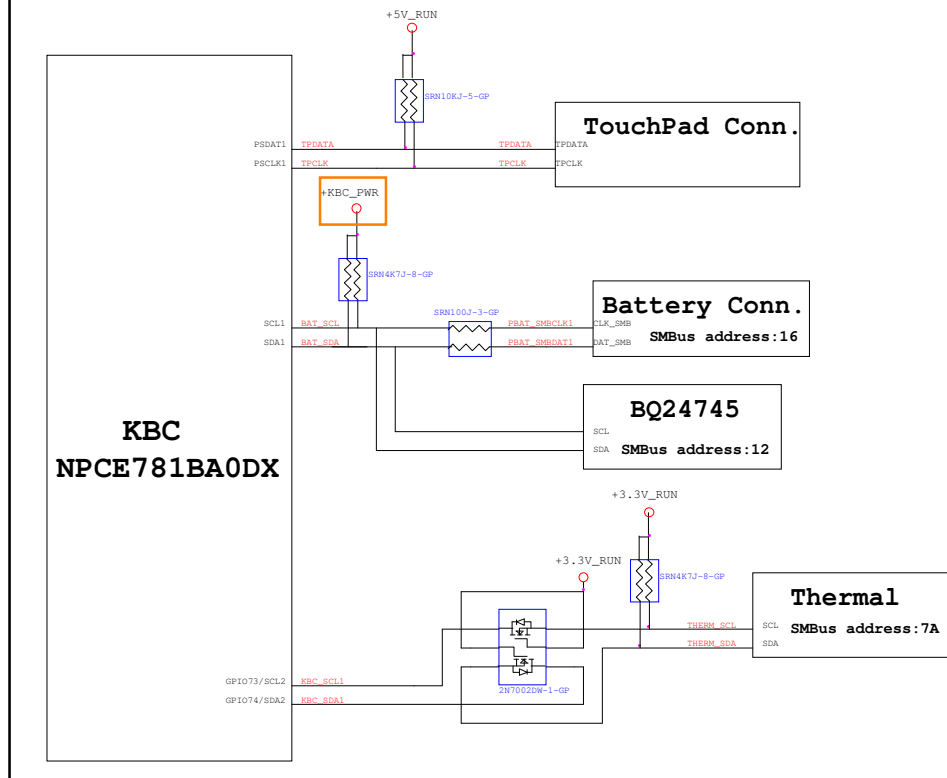
Size A3 Document Number Berry Rev X01
Date: Wednesday, February 24, 2010 Sheet 2 of 92



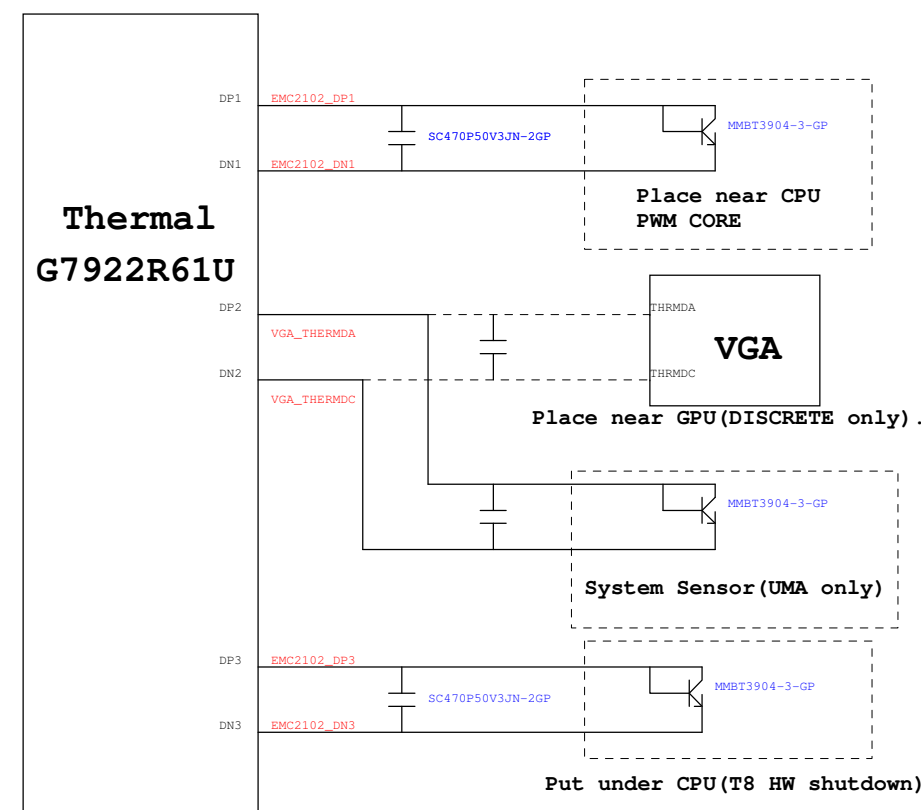
PCH SMBus Block Diagram



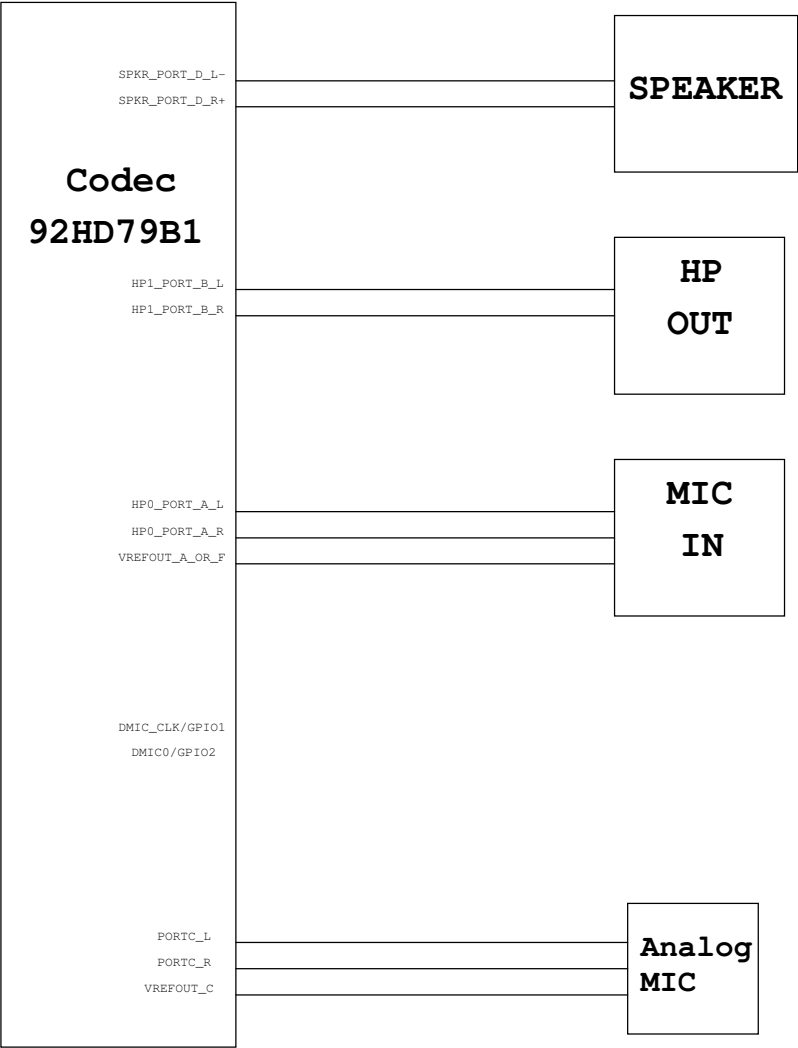
KBC SMBus Block Diagram



Thermal Block Diagram



Audio Block Diagram



Calpella Schematic Checklist Rev.0_7

Name	Schematics Notes
SPKR	Reboot option at power-up Default Mode: Internal weak Pull-down. No Reboot Mode with TCO Disabled: Connect to Vcc3_3 with 8.2-kΩ - 10-kΩ weak pull-up resistor.
INIT3_3V#	Weak internal pull-down. Do not pull high.
GNT3#/GPIO55	Default Mode: Internal pull-up. Low (0) = Top Block Swap Mode (Connect to ground with 4.7-kΩ weak pull-down resistor).
INTVRMEN	High (1) = Integrated VRM is enabled Low (0) = Integrated VRM is disabled
GNT0#, GNT1#/GPIO51	Default (SPI): Left both GNT0# and GNT1# floating. No pull up required. Boot from PCI: Connect GNT1# to ground with 1-kΩ pull-down resistor. Leave GNT0# Floating. Boot from LPC: Connect both GNT0# and GNT1# to ground with 1-kΩ pull-down resistor.
GNT2#/GPIO53	Default - Internal pull-up. Low (0) = Configures DMI for ESI compatible operation (for servers only. Not for mobile/desktops).
GPIO33	Default: Do not pull low. Disable ME in Manufacturing Mode: Connect to ground with 1-kΩ pull-down resistor.
SPI_MOSI	Enable iTPM: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable iTPM: Left floating, no pull-down required.
NV_ALE	Enable Danbury: Connect to Vcc3_3 with 8.2-kΩ weak pull-up resistor. Disable Danbury: Connect to ground with 4.7-kΩ weak pull-down resistor.
NC_CLE	Weak internal pull-up. Do not pull low.
HAD_DOCK_EN#/GPIO[33]	Low (0): Flash Descriptor Security will be overridden. High (1) : Flash Descriptor Security will be in effect.
HDA_SDO	Weak internal pull-down. Do not pull high.
HDA_SYNC	Weak internal pull-down. Do not pull high.
GPIO15	Weak internal pull-down. Do not pull high.
GPIO8	Weak internal pull-up. Do not pull low.
GPIO27	Default = Do not connect (floating) High(1) = Enables the internal VccVRM to have a clean supply for analog rails. No need to use on-board filter circuit. Low (0) = Disables the VccVRM. Need to use on-board filter circuits for analog rails.

PCIE Routing

LANE1	RESERVED
LANE2	MiniCard WLAN
LANE3	LAN
LANE4	W-WAN
LANE5	RESERVED
LANE6	RESERVED
LANE7	H55/HM55 no support
LANE8	H55/HM55 no support

USB Table

USB	
Pair	Device
0	USB2 (CRT Board)
1	USB3 (CRT Board)
2	WLAN (I/O Board)
3	RESERVED
4	CARD READER
5	BLUETOOTH
6	HM55 no support
7	HM55 no support
8	USB1 (I/O Board)
9	USB0 (I/O Board ESATA)
10	RESERVED
11	W-WAN (I/O Board)
12	RESERVED
13	CAMERA

SATA Table

SATA	
Pair	Device
0	HDD
1	ODD
2	HM55 no support
3	HM55 no support
4	ESATA
5	RESERVED

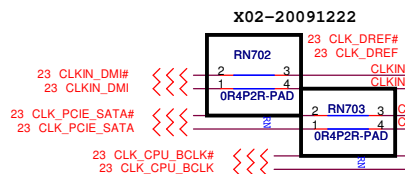
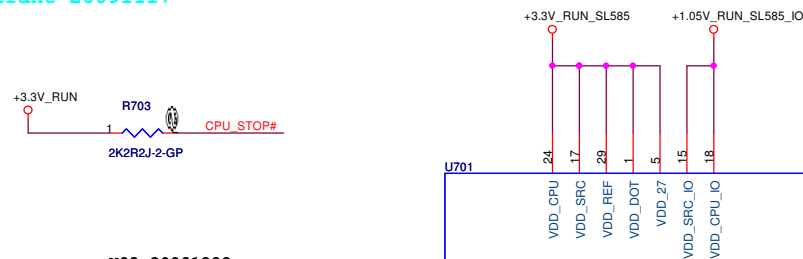
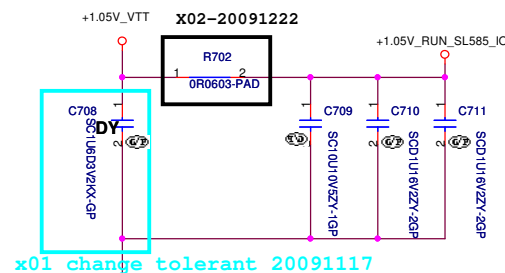
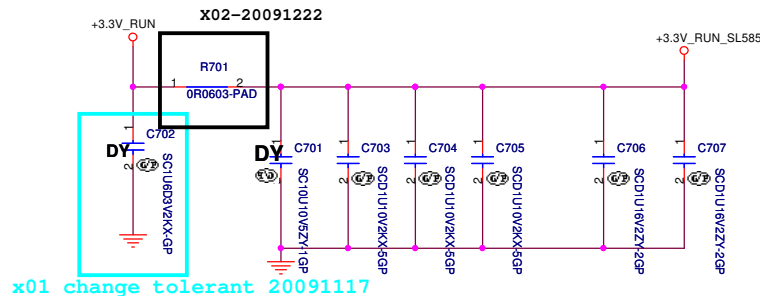
Processor Strapping

Calpella Schematic Checklist Rev.0_7

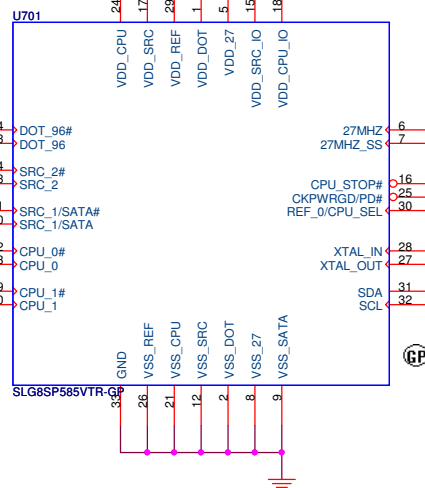
Pin Name	Strap Description	Configuration (Default value for each bit is 1 unless specified otherwise)	Default Value
CFG[4]	Embedded DisplayPort Presence	1: Disabled - No Physical Display Port attached to Embedded DisplayPort. 0: Enabled - An external Display Port device is connected to the Embedded Display Port.	1
CFG[3]	PCI-Express Static Lane Reversal	1: Normal Operation. 0: Lane Numbers Reversed 15 -> 0, 14 -> 1, ...	1
CFG[0]	PCI-Express Configuration Select	1: Single PCI-Express Graphics 0: Bifurcation enabled	1
CFG[7]	Reserved - Temporarily used for early Clarksfield samples.	Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor Note: Only temporary for early CFD samples (rPGA/BGA) [For details please refer to the WW33 MoW and sighting report]. For a common motherboard design (for AUB and CFD), the pull-down resistor should be used. Does not impact AUB functionality.	0

<Core Design>

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Title			
Table of Content			
Size A3	Document Number Berry	Sheet 6	Rev X0
Date: Wednesday, February 24, 2010		of	92



FSC	0	1
SPEED	133MHz (Default)	100MHz



M96_X01_20100224

DIS

R708 0R2J-2-GP

R709 33R2J-2-GP

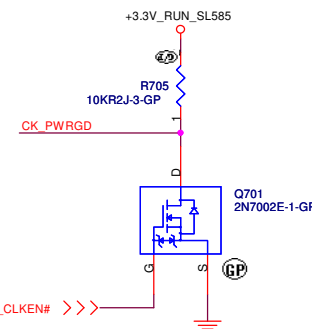
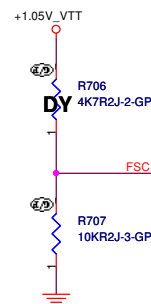
R704 33R2J-2-GP

EC701 SC4D7P50V2CN-1GP

EC702 SC4D7P50V2CN-1GP

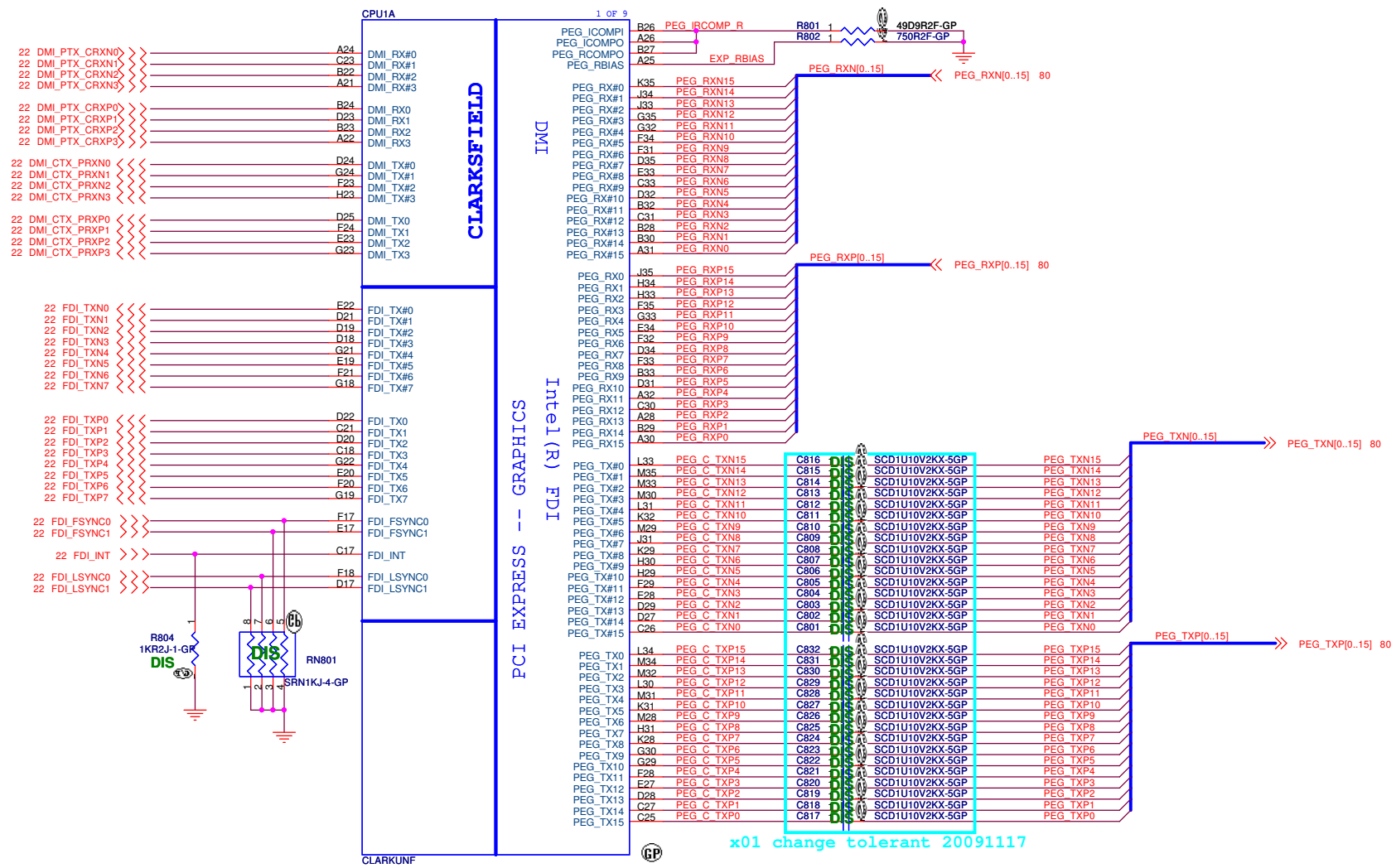
EC703 SC4D7P50V2CN-1GP

47 VR_CLKEN#



SSID = CPU

WWW.AliSaler.Com



62.10055.341
SEC. 62.10053.561

WWW.AliSaler.Com

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DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
CPU (PCIE/DMI/FDI)

Size Document Number
Berry

Date: Wednesday, February 24, 2010 Sheet 8 of 92

Rev
X01

18 M_A_DQ[63..0] <<>> M_A_DQ[63..0]

M_A_DQ0 A10 SA_DQ0
M_A_DQ1 C10 SA_DQ1
M_A_DQ2 A7 SA_DQ2
M_A_DQ3 B10 SA_DQ3
M_A_DQ4 B10 SA_DQ4
M_A_DQ5 D10 SA_DQ5
M_A_DQ6 E10 SA_DQ6
M_A_DQ7 A8 SA_DQ7
M_A_DQ8 D8 SA_DQ8
M_A_DQ9 F10 SA_DQ9
M_A_DQ10 E6 SA_DQ10
M_A_DQ11 F7 SA_DQ11
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M_A_DQ27 L9 SA_DQ27
M_A_DQ28 L6 SA_DQ28
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M_A_DQ30 N8 SA_DQ30
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M_A_DQ40 AJ10 SA_DQ40
M_A_DQ41 AJ9 SA_DQ41
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M_A_DQ44 AK8 SA_DQ44
M_A_DQ45 AL7 SA_DQ45
M_A_DQ46 AK11 SA_DQ46
M_A_DQ47 AL8 SA_DQ47
M_A_DQ48 AN8 SA_DQ48
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M_A_DQ54 AT11 SA_DQ54
M_A_DQ55 AP12 SA_DQ55
M_A_DQ56 AM12 SA_DQ56
M_A_DQ57 AN12 SA_DQ57
M_A_DQ58 AM13 SA_DQ58
M_A_DQ59 AT14 SA_DQ59
M_A_DQ60 AT12 SA_DQ60
M_A_DQ61 AL13 SA_DQ61
M_A_DQ62 AP14 SA_DQ62
M_A_DQ63 AP14 SA_DQ63

CLARKSFIELD

DDR SYSTEM MEMORY A

SA_CK0 AA6 <>>> M_CLK_DDR0 18
SA_CK#0 AA7 <>>> M_CLK_DDR#0 18
SA_CKE0 P7 <>>> M_CKE0 18

SA_CK1 Y6 <>>> M_CLK_DDR1 18
SA_CK#1 Y5 <>>> M_CLK_DDR#1 18
SA_CKE1 P6 <>>> M_CKE1 18

SA_CS#0 AE2 <>>> M_CS#0 18
SA_CS#1 AE8 <>>> M_CS#1 18

SA_ODT0 AD8 <>>> M_ODT0 18
SA_ODT1 AF9 <>>> M_ODT1 18

SA_DM0 B9 M_A_DM0
SA_DM1 D7 M_A_DM1
SA_DM2 H7 M_A_DM2
SA_DM3 M7 M_A_DM3
SA_DM4 AG6 M_A_DM4
SA_DM5 AM7 M_A_DM5
SA_DM6 AN10 M_A_DM6
SA_DM7 AN13 M_A_DM7

<<>> M_A_DM[7..0] 18
<<>> M_A_DQS#[7..0] 18
<<>> M_A_DQS[7..0] 18
<<>> M_A_A[15..0] 18

SA_DQS#0 C8 M_A_DQS#0
SA_DQS#1 F8 M_A_DQS#1
SA_DQS#2 J9 M_A_DQS#2
SA_DQS#3 AN9 M_A_DQS#3
SA_DQS#4 AH7 M_A_DQS#4
SA_DQS#5 AK9 M_A_DQS#5
SA_DQS#6 AP11 M_A_DQS#6
SA_DQS#7 AT13 M_A_DQS#7

SA_DQS0 C8 M_A_DQS0
SA_DQS1 F9 M_A_DQS1
SA_DQS2 H9 M_A_DQS2
SA_DQS3 M9 M_A_DQS3
SA_DQS4 AH8 M_A_DQS4
SA_DQS5 AK10 M_A_DQS5
SA_DQS6 AN11 M_A_DQS6
SA_DQS7 AR13 M_A_DQS7

SA_MA0 Y3 M_A_A0
SA_MA1 W1 M_A_A1
SA_MA2 AA8 M_A_A2
SA_MA3 AA9 M_A_A3
SA_MA4 V1 M_A_A4
SA_MA5 AA9 M_A_A5
SA_MA6 V8 M_A_A6
SA_MA7 T1 M_A_A7
SA_MA8 Y9 M_A_A8
SA_MA9 U6 M_A_A9
SA_MA10 AD4 M_A_A10
SA_MA11 T2 M_A_A11
SA_MA12 U3 M_A_A12
SA_MA13 AG8 M_A_A13
SA_MA14 T3 M_A_A14
SA_MA15 V9 M_A_A15

18 M_A_BS0 <>>> AC3 SA_BS0
18 M_A_BS1 <>>> AB2 SA_BS1
18 M_A_BS2 <>>> U7 SA_BS2

18 M_A_CAS# <>>> AE1C SA_CAS#
18 M_A_RAS# <>>> AB3C SA_RAS#
18 M_A_WE# <>>> AE3C SA_WE#

CLARKUNF



CPU1D

4 OF 9

CLARKSFIELD

DDR SYSTEM MEMORY - B

SB_CK0 W8 <>>> M_CLK_DDR2 19
SB_CK#0 W9 <>>> M_CLK_DDR#2 19
SB_CKE0 M3 <>>> M_CKE2 19

SB_CK1 V7 <>>> M_CLK_DDR3 19
SB_CK#1 V6 <>>> M_CLK_DDR#3 19
SB_CKE1 M2 <>>> M_CKE3 19

SB_CS#0 AB8 <>>> M_CS#2 19
SB_CS#1 AD6 <>>> M_CS#3 19

SB_ODT0 AC7 <>>> M_ODT2 19
SB_ODT1 AD1 <>>> M_ODT3 19

SB_DM0 D4 M_B_DM0
SB_DM1 E1 M_B_DM1
SB_DM2 H3 M_B_DM2
SB_DM3 K1 M_B_DM3
SB_DM4 AH1 M_B_DM4
SB_DM5 AL2 M_B_DM5
SB_DM6 AR4 M_B_DM6
SB_DM7 AT8 M_B_DM7

<<>> M_B_DM[7..0] 19
<<>> M_B_DQS#[7..0] 19
<<>> M_B_DQS[7..0] 19
<<>> M_B_A[15..0] 19

SB_DQS#0 D5 M_B_DQS#0
SB_DQS#1 F4 M_B_DQS#1
SB_DQS#2 J4 M_B_DQS#2
SB_DQS#3 L4 M_B_DQS#3
SB_DQS#4 AH2 M_B_DQS#4
SB_DQS#5 AL4 M_B_DQS#5
SB_DQS#6 AR5 M_B_DQS#6
SB_DQS#7 AR8 M_B_DQS#7

SB_DQS0 C5 M_B_DQS0
SB_DQS1 E3 M_B_DQS1
SB_DQS2 H4 M_B_DQS2
SB_DQS3 M5 M_B_DQS3
SB_DQS4 AG2 M_B_DQS4
SB_DQS5 AL5 M_B_DQS5
SB_DQS6 AP5 M_B_DQS6
SB_DQS7 AR7 M_B_DQS7

SB_MA0 U5 M_B_A0
SB_MA1 V2 M_B_A1
SB_MA2 T5 M_B_A2
SB_MA3 V3 M_B_A3
SB_MA4 R1 M_B_A4
SB_MA5 T8 M_B_A5
SB_MA6 R2 M_B_A6
SB_MA7 R6 M_B_A7
SB_MA8 R4 M_B_A8
SB_MA9 R5 M_B_A9
SB_MA10 AB5 M_B_A10
SB_MA11 P3 M_B_A11
SB_MA12 R3 M_B_A12
SB_MA13 AE7 M_B_A13
SB_MA14 P5 M_B_A14
SB_MA15 N1 M_B_A15

M_B_DQ0 B5 SB_DQ0
M_B_DQ1 A5 SB_DQ1
M_B_DQ2 C3 SB_DQ2
M_B_DQ3 B3 SB_DQ3
M_B_DQ4 E4 SB_DQ4
M_B_DQ5 A4 SB_DQ5
M_B_DQ6 A4 SB_DQ6
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M_B_DQ8 D1 SB_DQ8
M_B_DQ9 D2 SB_DQ9
M_B_DQ10 F2 SB_DQ10
M_B_DQ11 F1 SB_DQ11
M_B_DQ12 C2 SB_DQ12
M_B_DQ13 F5 SB_DQ13
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M_B_DQ15 G4 SB_DQ15
M_B_DQ16 H6 SB_DQ16
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M_B_DQ42 AM6 SB_DQ42
M_B_DQ43 AN2 SB_DQ43
M_B_DQ44 AK5 SB_DQ44
M_B_DQ45 AK2 SB_DQ45
M_B_DQ46 AM4 SB_DQ46
M_B_DQ47 AM3 SB_DQ47
M_B_DQ48 AP3 SB_DQ48
M_B_DQ49 AN5 SB_DQ49
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M_B_DQ56 AN7 SB_DQ56
M_B_DQ57 AP6 SB_DQ57
M_B_DQ58 AP8 SB_DQ58
M_B_DQ59 AT9 SB_DQ59
M_B_DQ60 AT7 SB_DQ60
M_B_DQ61 AP9 SB_DQ61
M_B_DQ62 AR10 SB_DQ62
M_B_DQ63 AT10 SB_DQ63

19 M_B_BS0 <>>> AB1 SB_BS0
19 M_B_BS1 <>>> W5 SB_BS1
19 M_B_BS2 <>>> R7 SB_BS2

19 M_B_CAS# <>>> AC5 SB_CAS#
19 M_B_RAS# <>>> Y7 SB_RAS#
19 M_B_WE# <>>> AC6 SB_WE#

CLARKUNF



<Core Design>

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21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

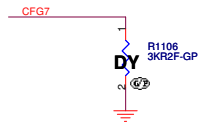
Size Document Number

Date: Wednesday, February 24, 2010

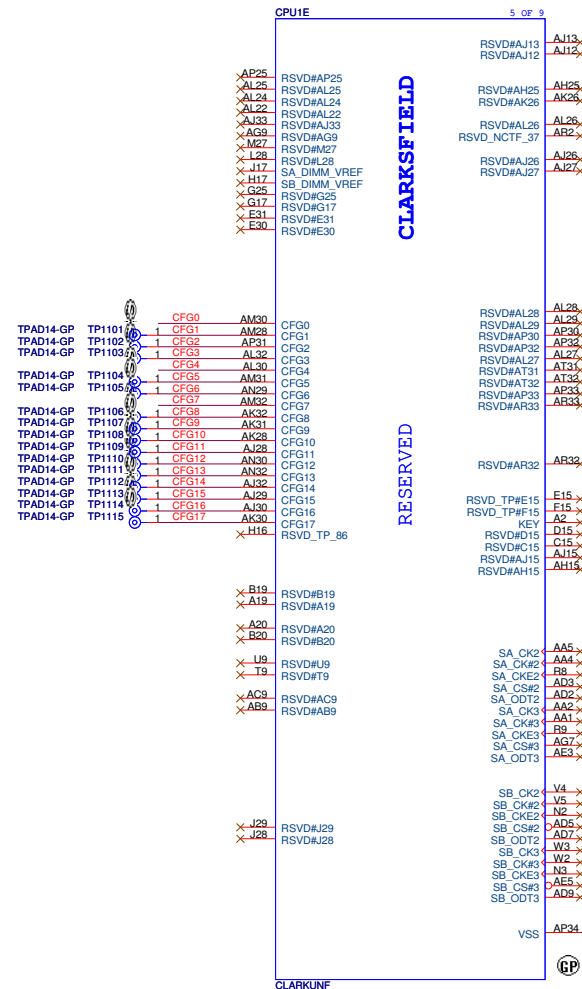
Rev

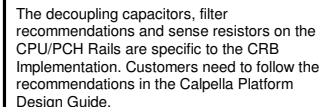
X01

Sheet 10 of 92

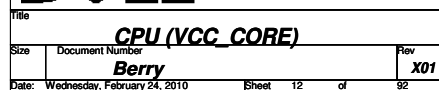


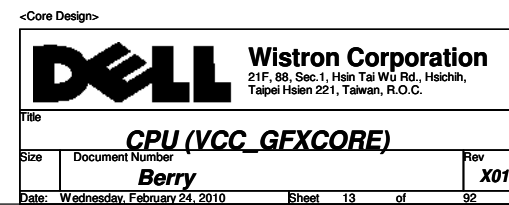
CFG7(Reserved) - Temporarily used for early Clarksfield samples.	
CFG7	<p>Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor.</p> <p>Note: Only temporary for early CFD sample (rPGA/BGA) [For details please refer to the WW33 MoW and sighting report]. For a common M/B design (for AUB and CFD), the pull-down resistor should be used. Does not impact AUB functionality.</p>

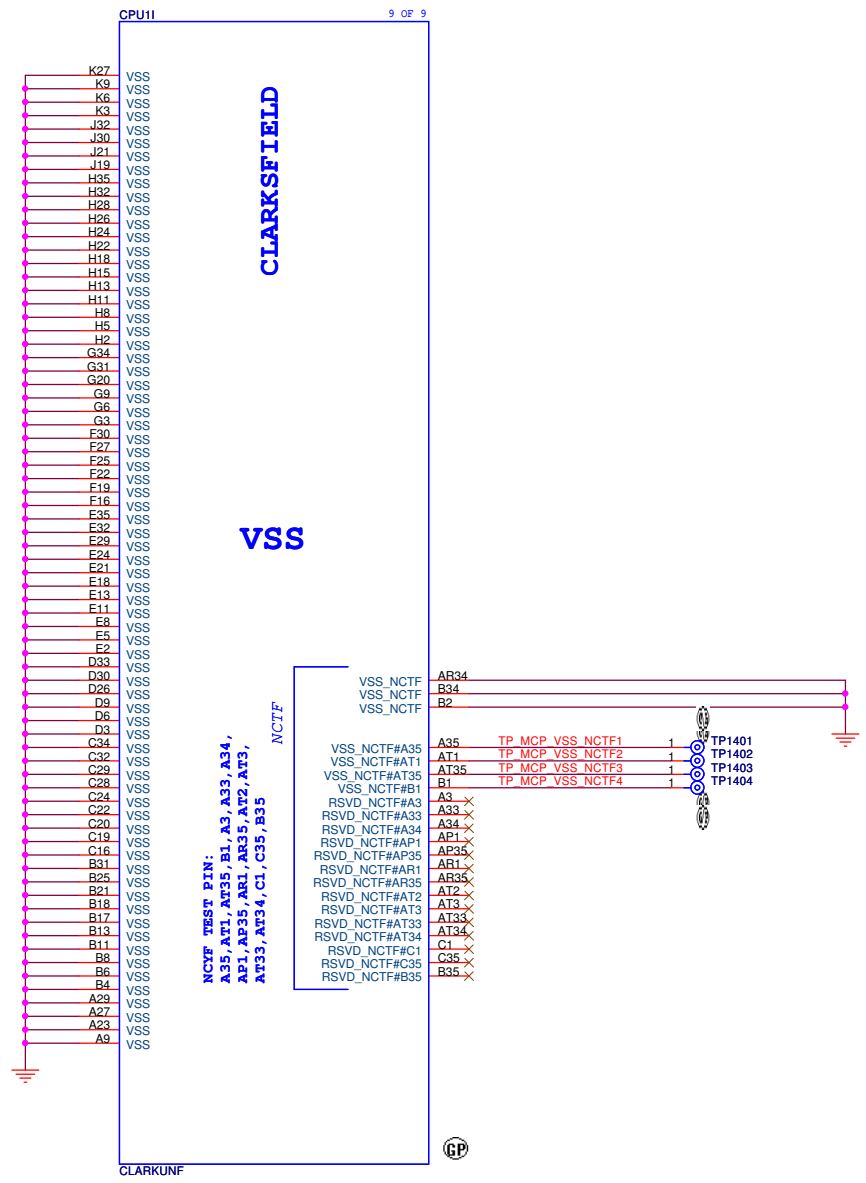
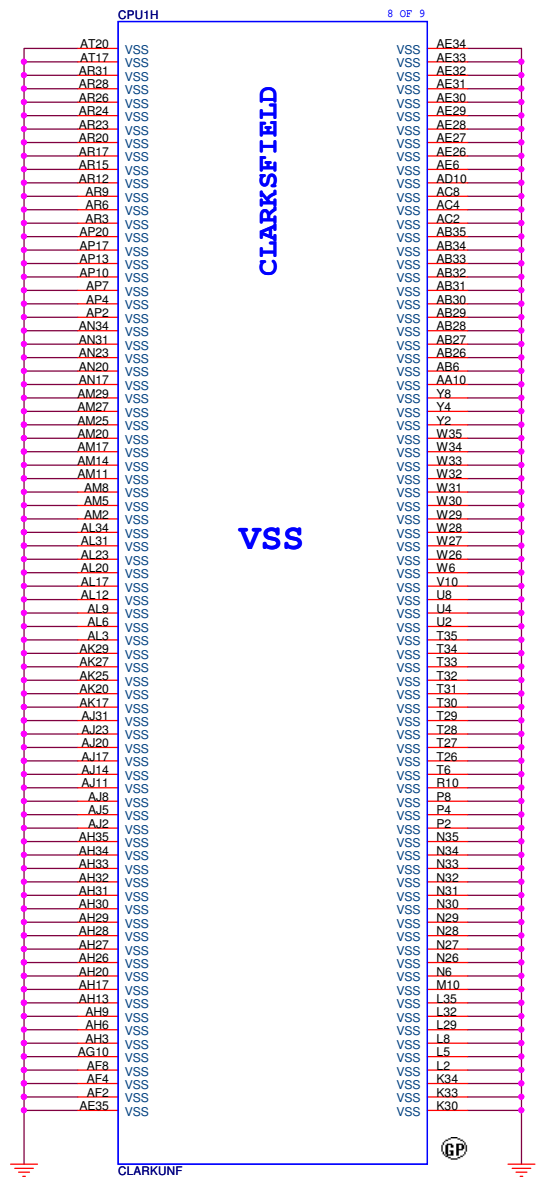




Please note that the VTT Rail Values are Auburndale
VTT=1.05V; Clarksfield
VTT=1.1V








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Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010


Reserved

Rev
X01

Sheet 15 of 92

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Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010


Reserved

Rev
X01

Sheet 16 of 92

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Title

Size
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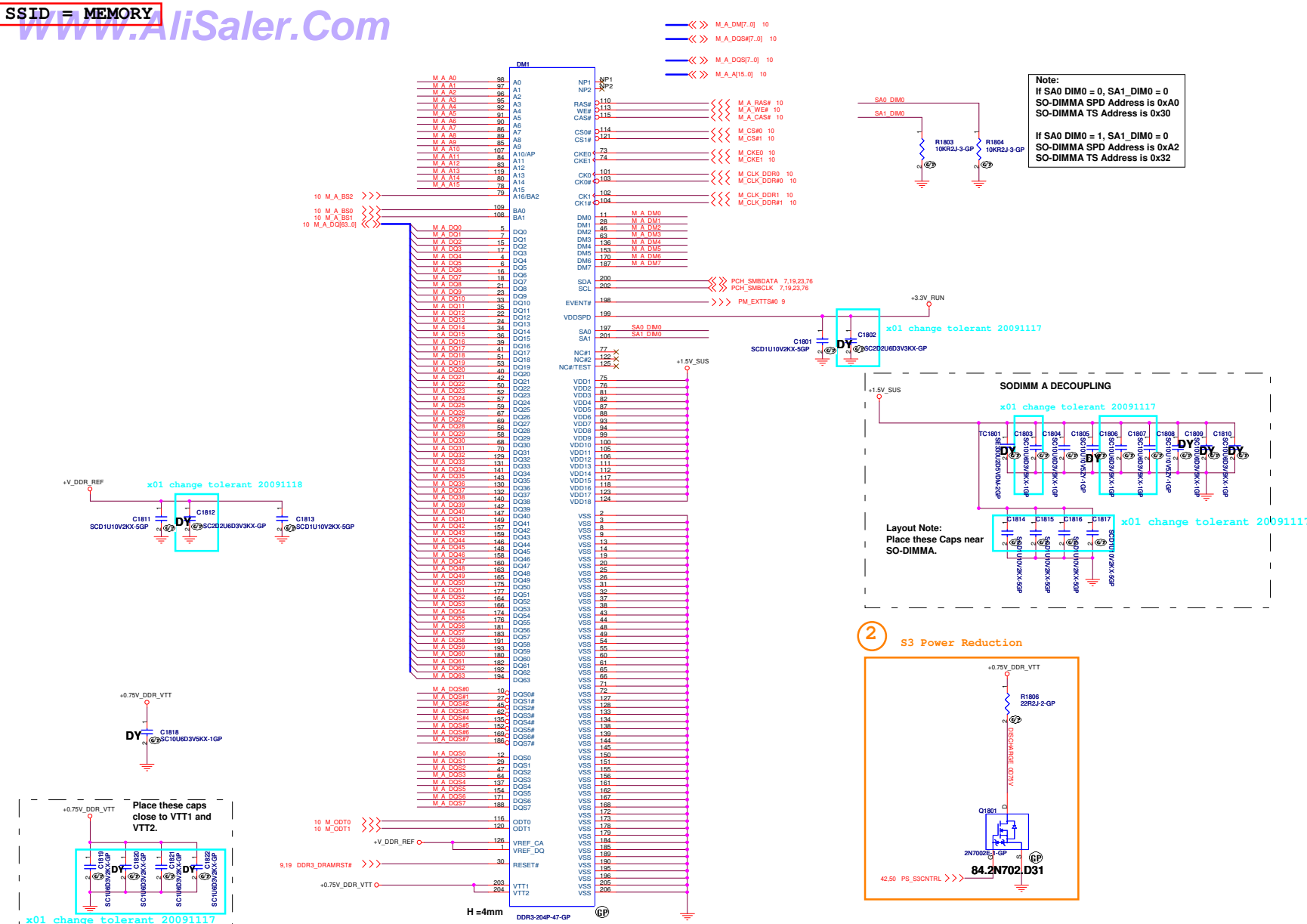
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Berry

Date: Wednesday, February 24, 2010

Rev
X01

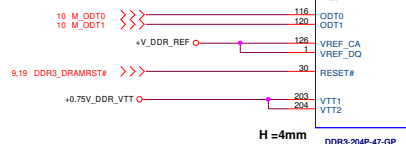
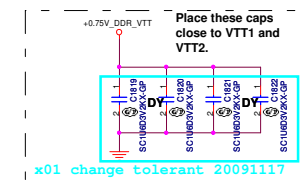
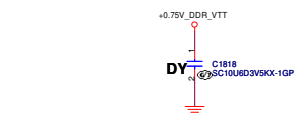
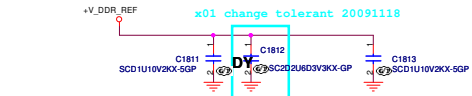
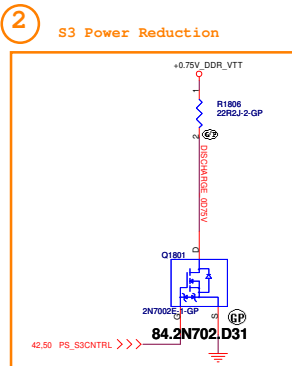
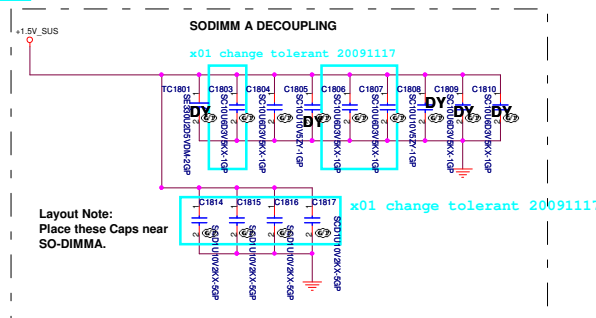
Sheet 17 of 92

Reserved

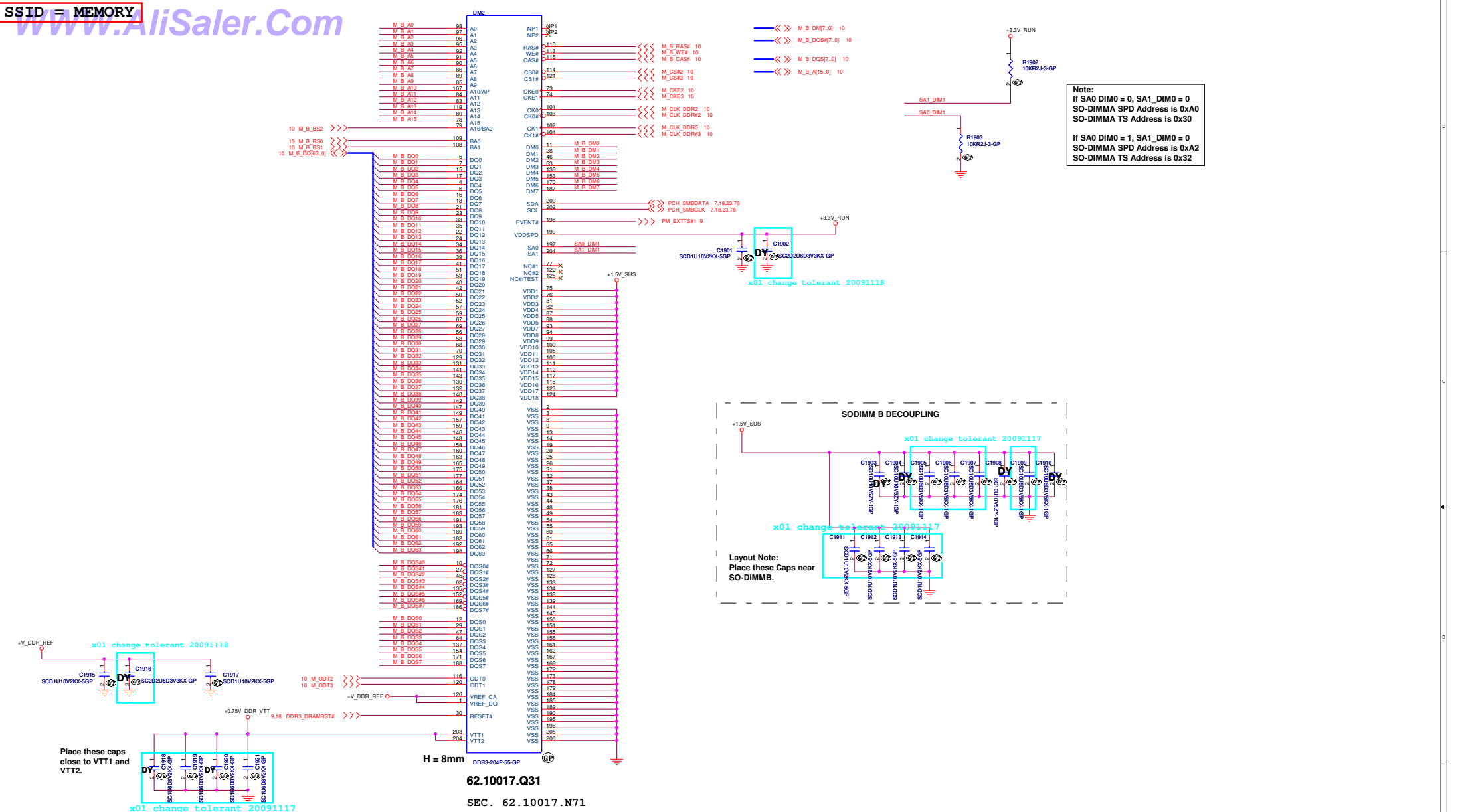


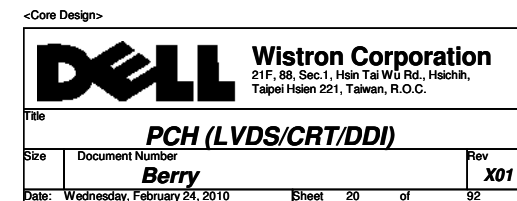
Note:
If SA0_DIM0 = 0, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA0
SO-DIMMA TS Address is 0x30

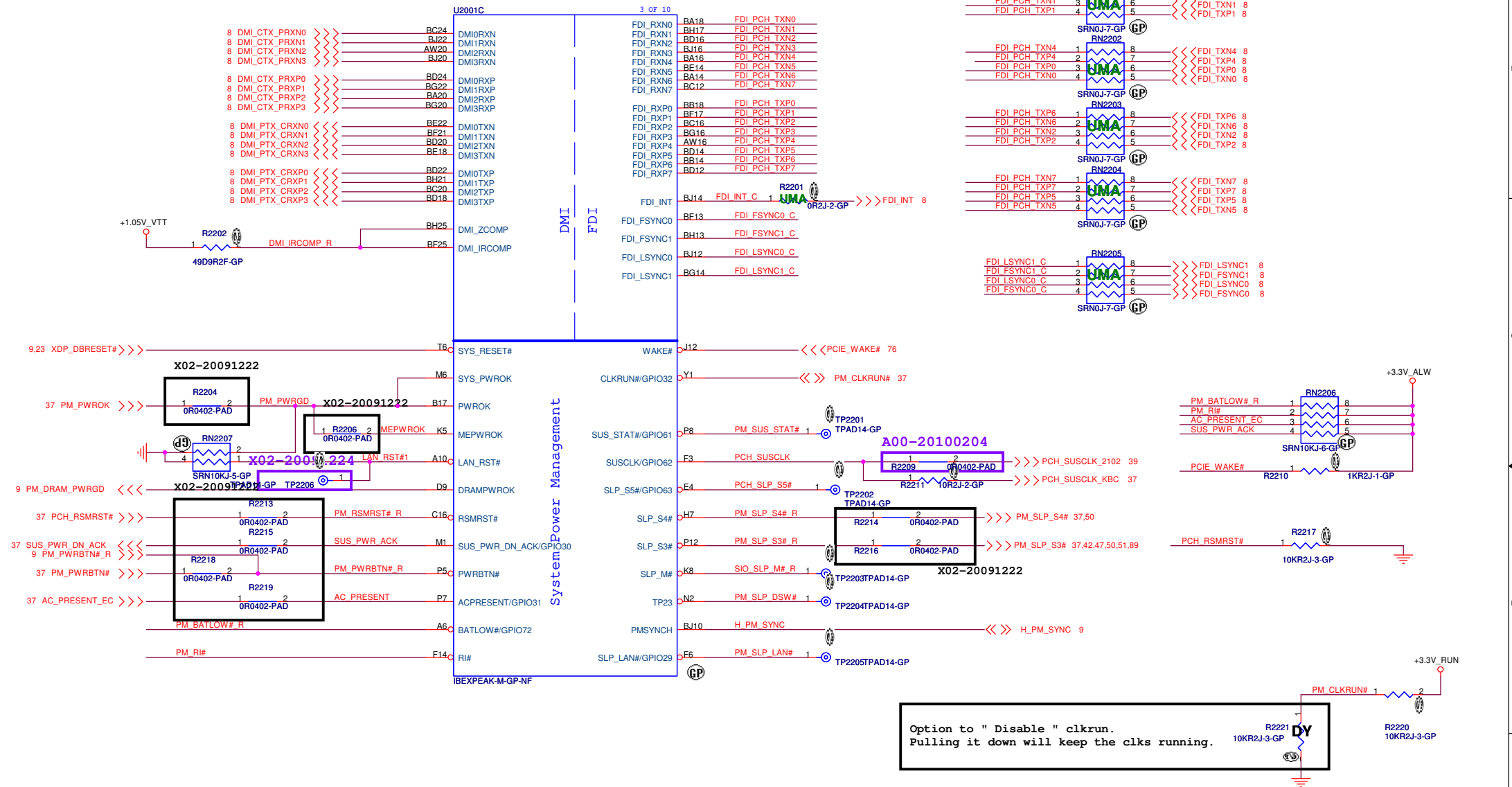
If SA0_DIM0 = 1, SA1_DIM0 = 0
SO-DIMMA SPD Address is 0xA2
SO-DIMMA TS Address is 0x32

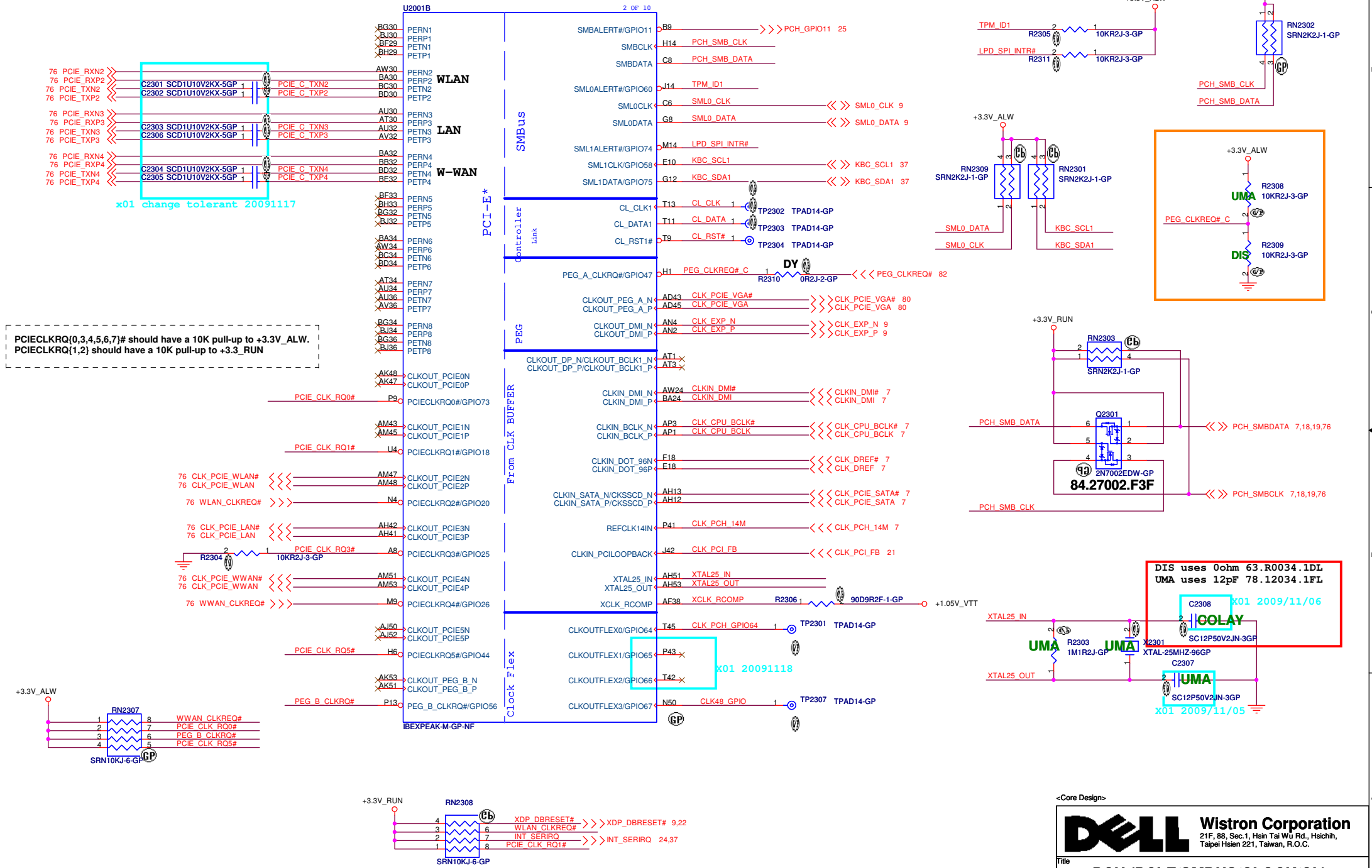


62.10017.P31
SEC. 62.10017.P11

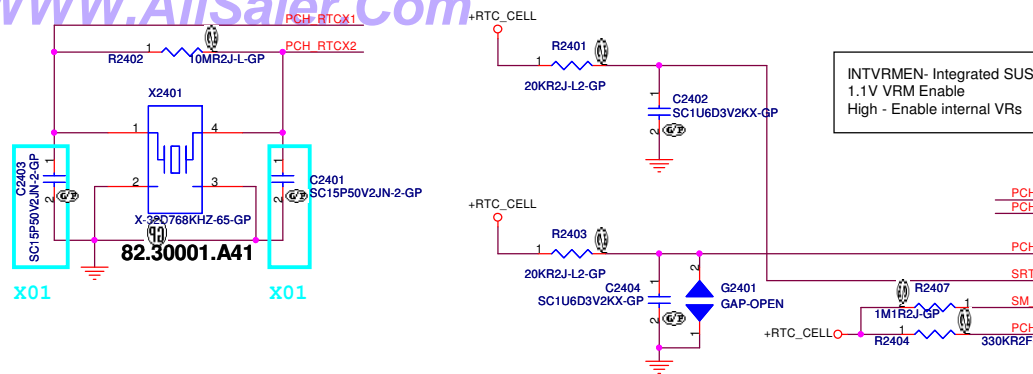




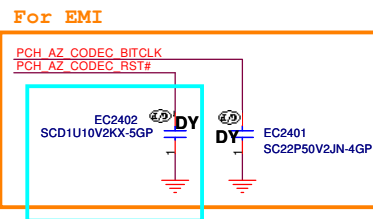
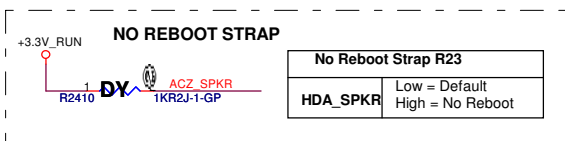
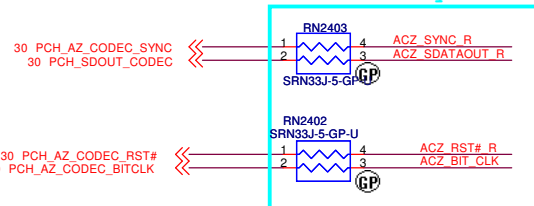




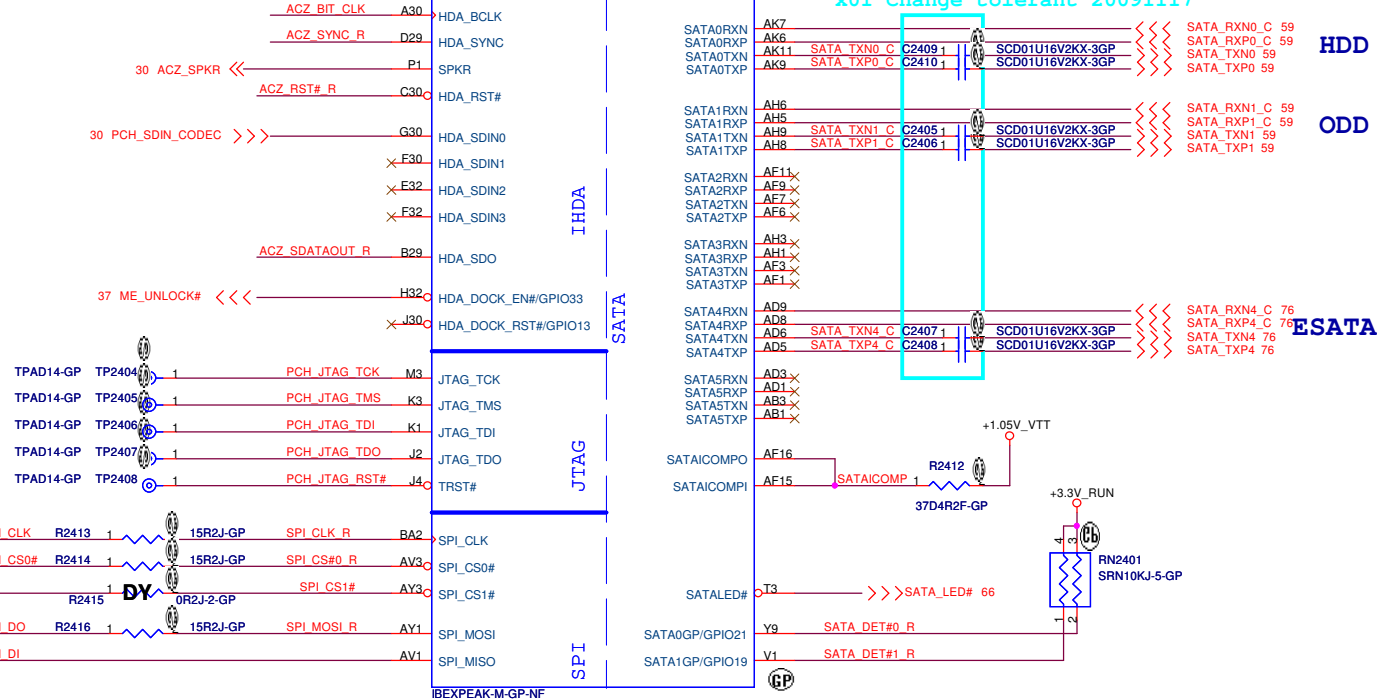
SSID = PCH



x01 20091118 layout swap



x01 Change tolerant 20091117



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Title			
PCH (SPI/RTC/LPC/SATA/IHDA)			
Size	Document Number		Rev
	Berry		X01
Date:	Wednesday, February 24, 2010	Sheet 24 of	92

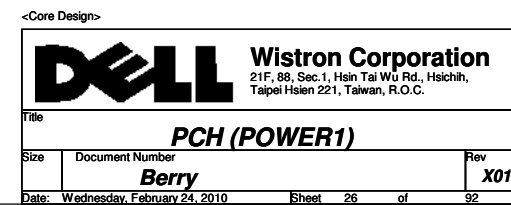


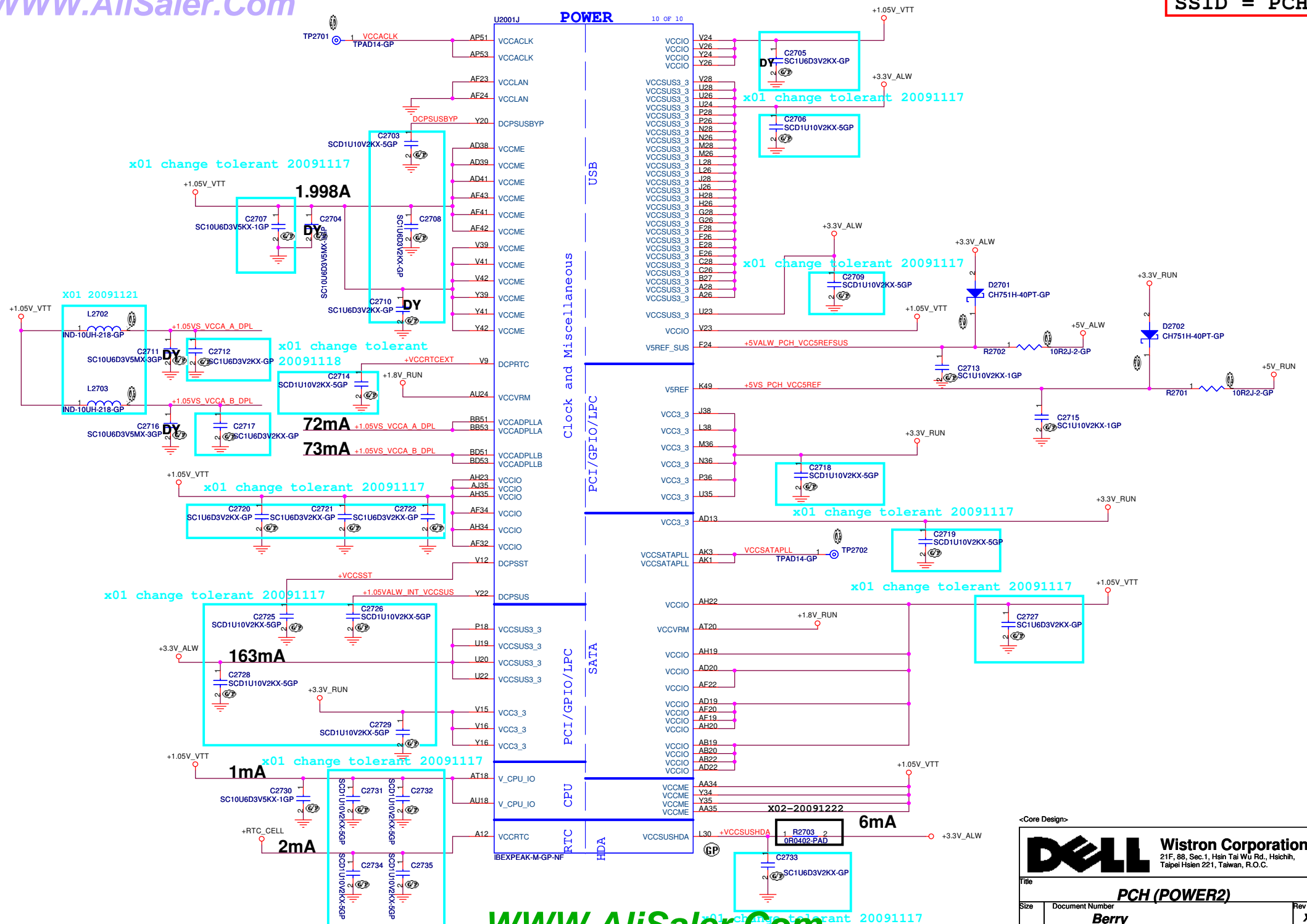
PCH (GPIO/CPU)

Rev

X01

Sheet 25 of 92







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Title

PCH (VSS)

Size	Document Number
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Berry


Date: Wednesday, February 24, 2010

Sheet	28
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Rev	X01
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Title

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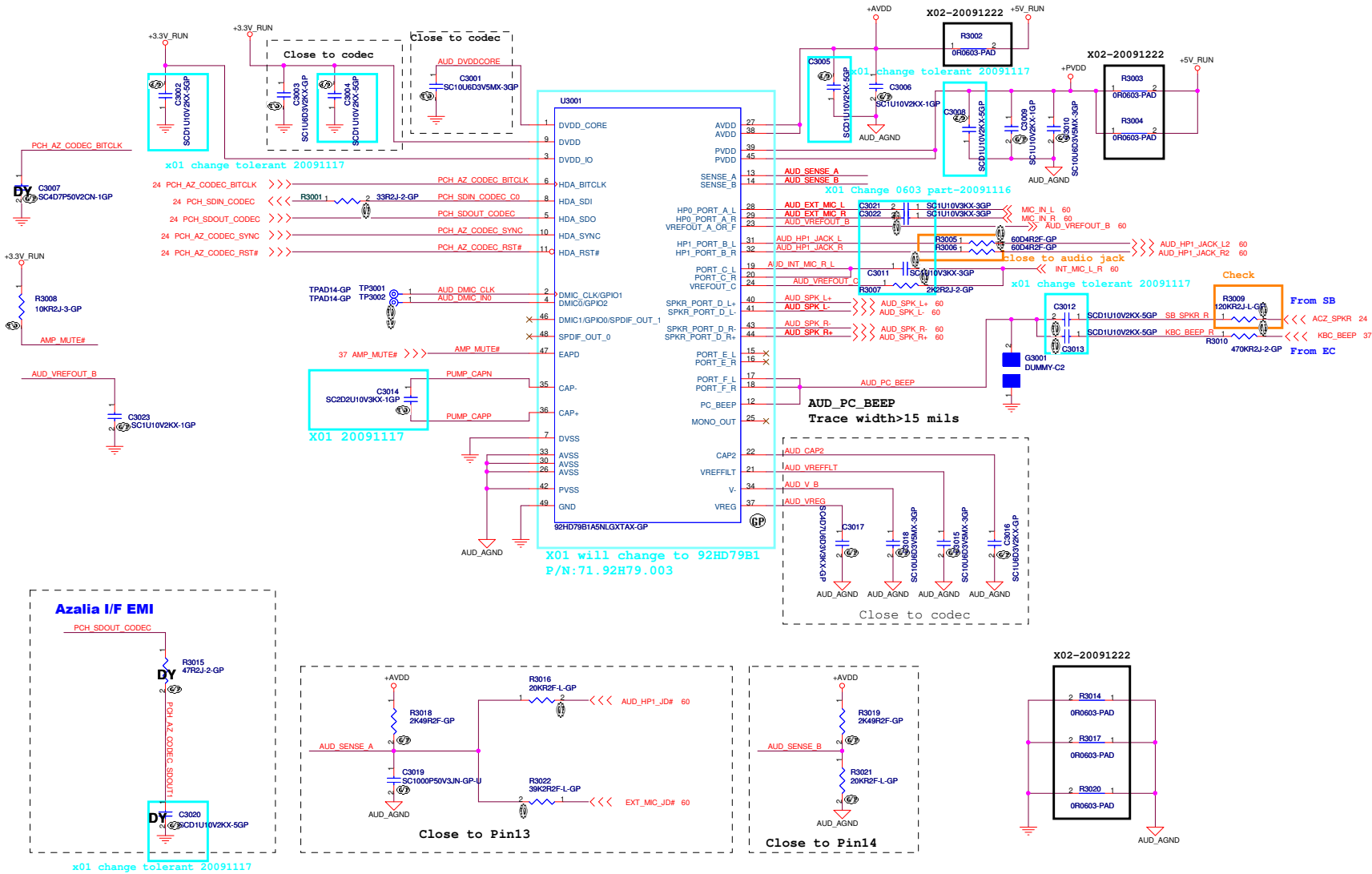
Document Number
Berry

Date: Wednesday, February 24, 2010

Rev
X01

Sheet 29 of 92


Reserved



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Title

Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010

Rev
X01


Sheet 31 of 92

Reserved

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Title

Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010


Reserved

Rev
X01

Sheet 33 of 92

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Title

Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010


Reserved

Rev
X01

Sheet 34 of 92

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Title

Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010


Rev
X01

Sheet 35 of 92

Reserved

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Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010

Reserved


Rev
X01

Sheet 36 of 92



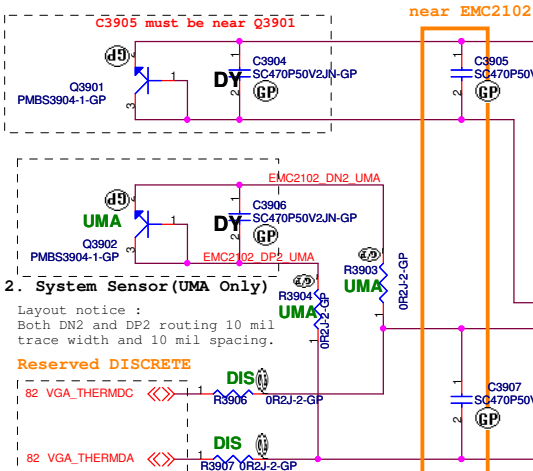
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Title			
Reserved			
Size A4	Document Number Berry		Rev X01
Date: Wednesday, February 24, 2010		Sheet 38	of 92

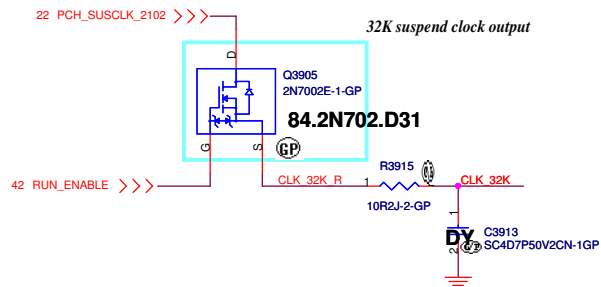
1. Place near CPU PWM CORE and PCH.

Layout notice :
Both DN1 and DP1 routing 10 mil
trace width and 10 mil spacing.



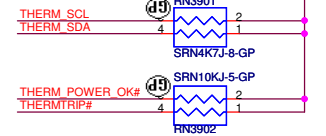
GND = Channel 1
OPEN = Channel 3
+3.3V = Disabled

GND = Fan is OFF
OPEN = Fan is at 60% full-scale
+3.3V = Fan is at 75% full-scale



EMC2102_FAN_TACH <<< EMC2102_FAN_TACH 58
EMC2102_FAN_DRIVE >>> EMC2102_FAN_DRIVE 58

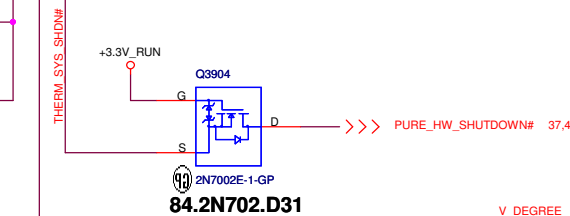
THERM_SCL 37
THERM_SDA 37



GND = Internal Oscillator Selected
+3.3V = External 32.768kHz Clock Selected

Main G7922R61U for GMT P/N:74.07922.0B3
SEC. EMC2102 for SMSC P/N:74.02102.A73


THERM_POWER_OK#
THERMTRIP#



x01 change tolerant 20091117
T8 shutdown is set 88 deg-C.

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Size A3	Document Number Berry	Rev X01
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Date: Wednesday, February 24, 2010	Sheet 40 of 92
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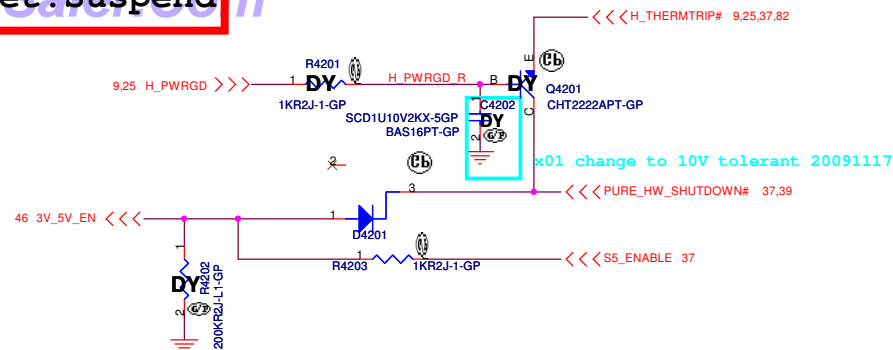
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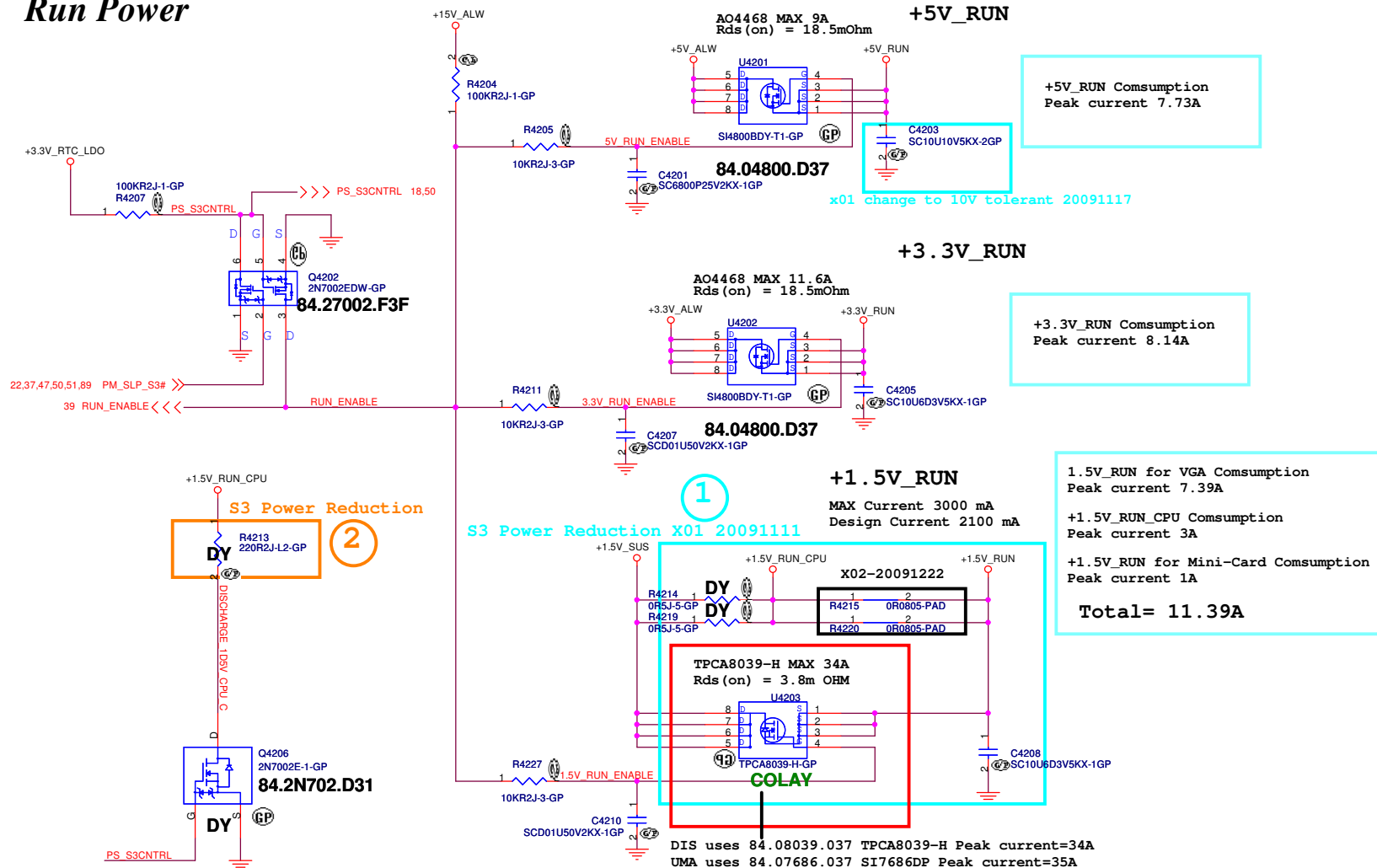
Rev
X01

Sheet 41 of 92

Reserved



Run Power



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Title			
Power Plane Enable			
Size	Document Number	Rev	
A3	Berry	X01	
Date:	Wednesday, February 24, 2010	Sheet	42 of 92

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Taipei Hsien 221, Taiwan, R.O.C.

Title

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Berry

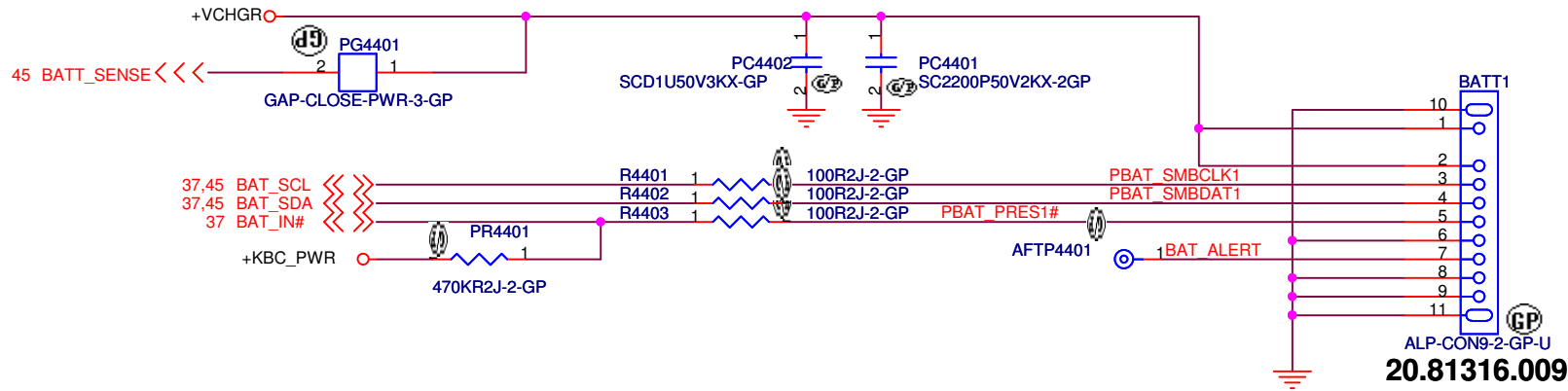
Date: Wednesday, February 24, 2010

Reserved

Rev
X01

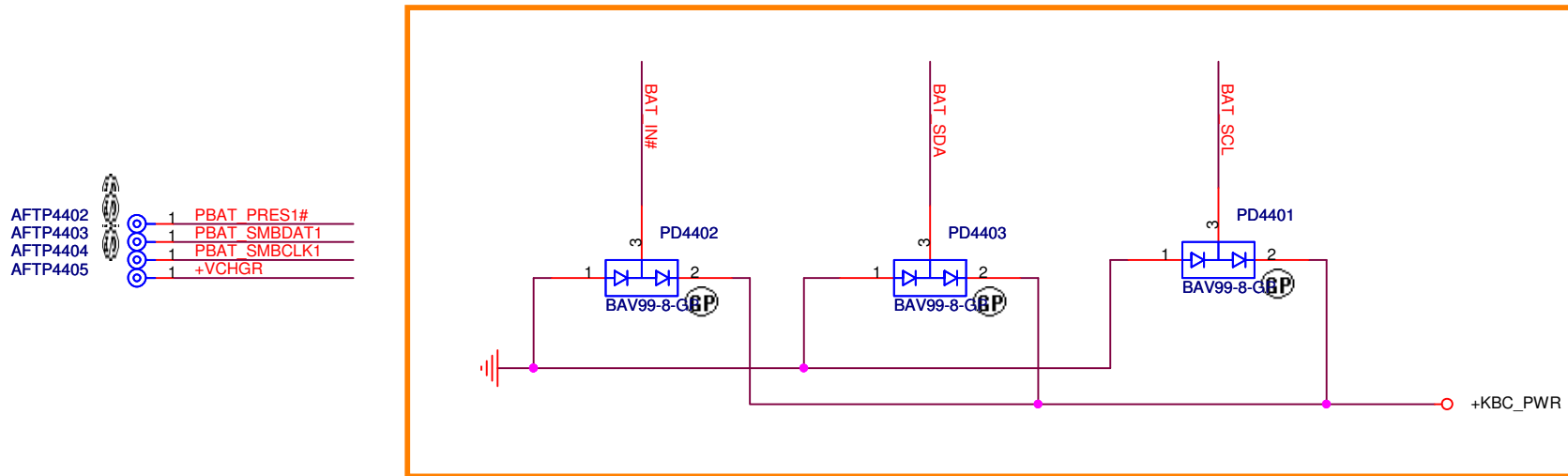
Sheet 43 of 92

Batt Connector



For actual location, need to be swap all pin

Close to Batt Connector



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Title

BATT CONN

Size
A4

Document Number

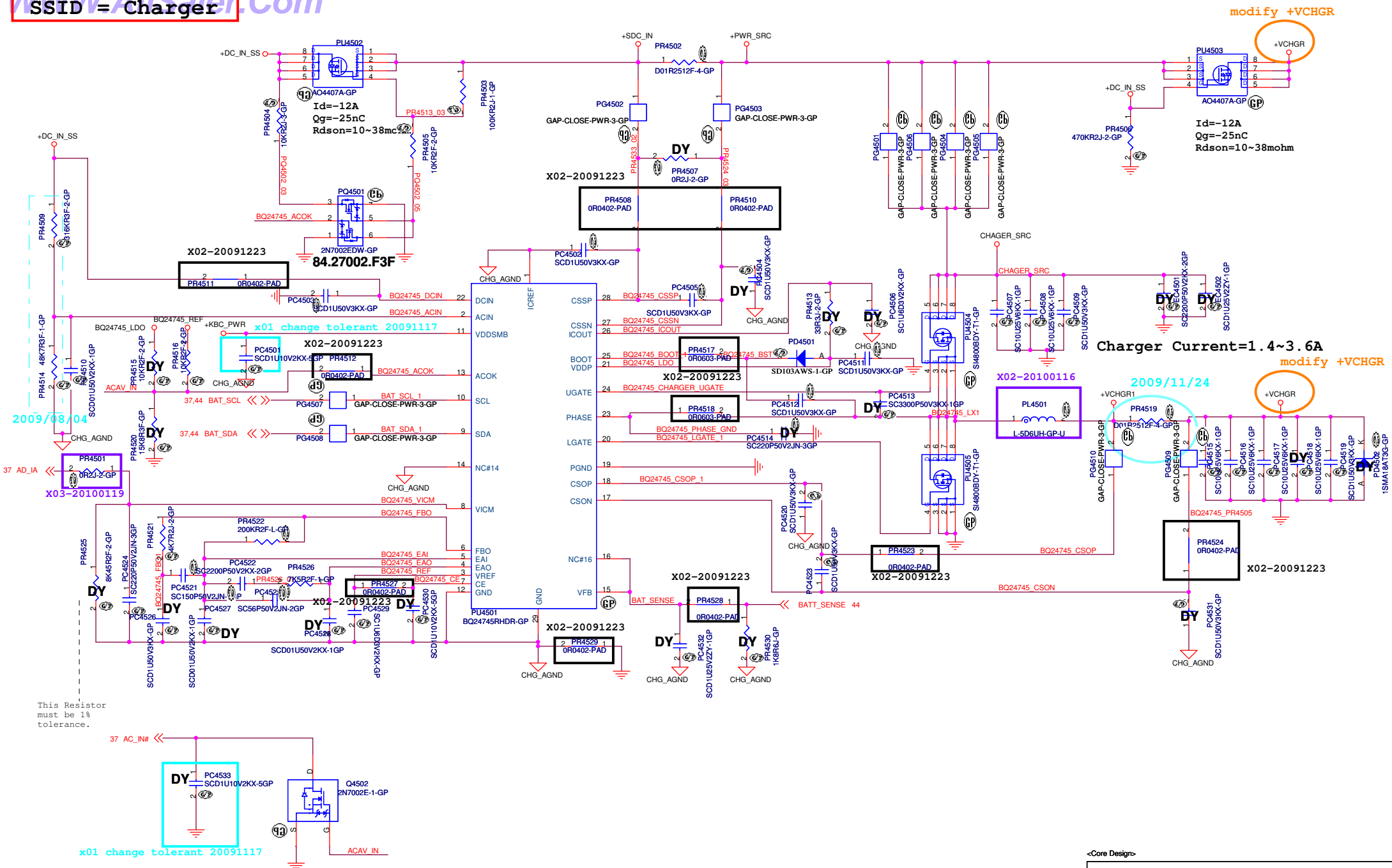
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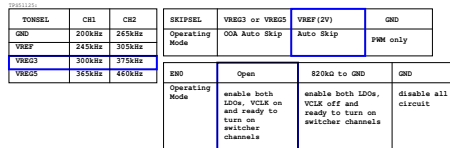
Rev

X01

Date: Wednesday, February 24, 2010

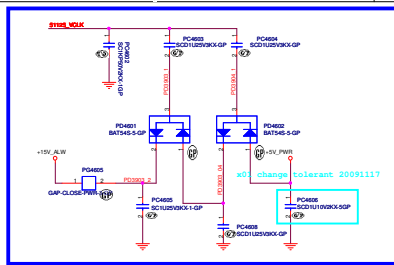
Sheet 44 of 92

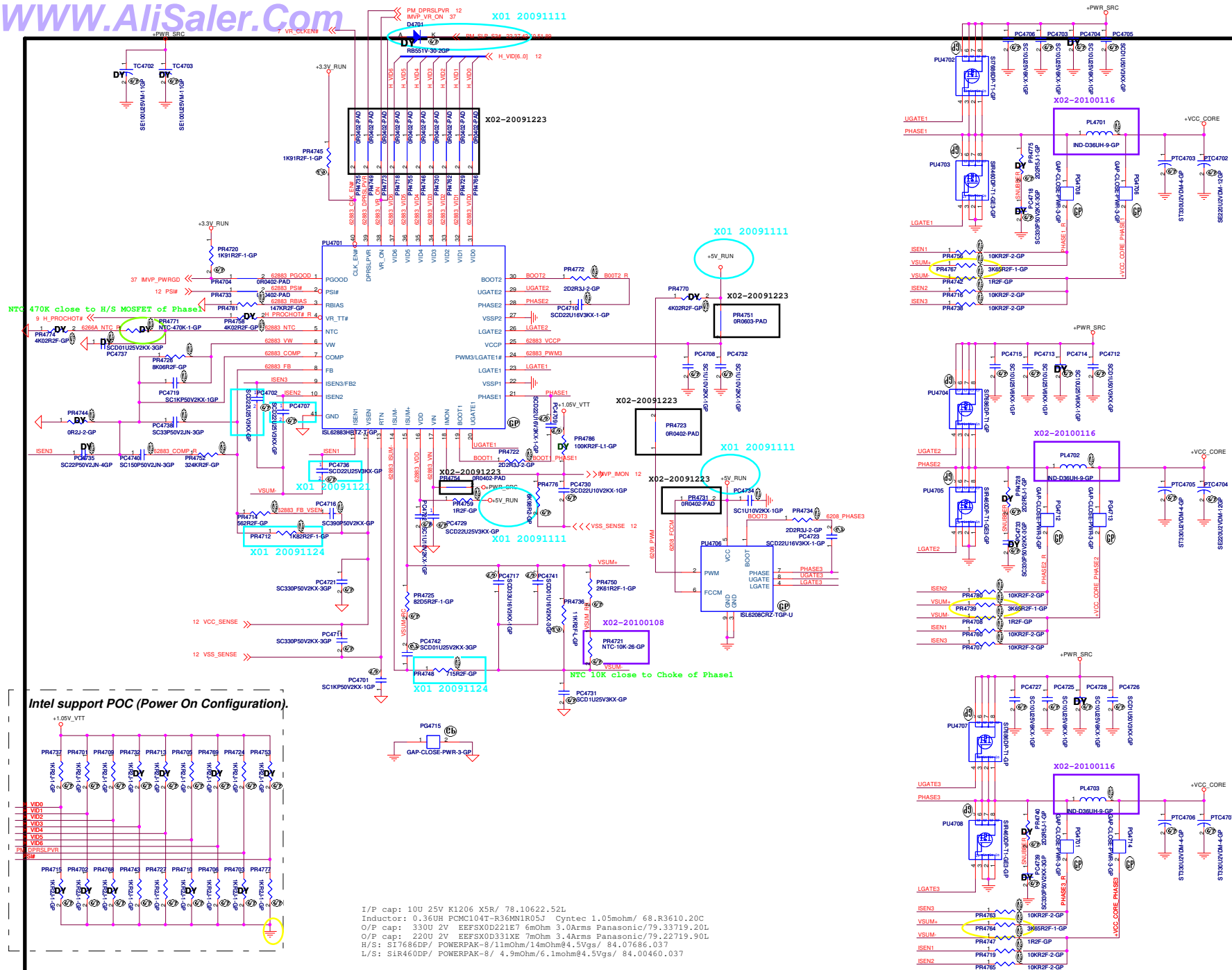




TENSEL	CH1	CH2
GND	200kHz	250kHz
VREF	300kHz	375kHz
VREG3	365kHz	460kHz
VREG5	365kHz	460kHz

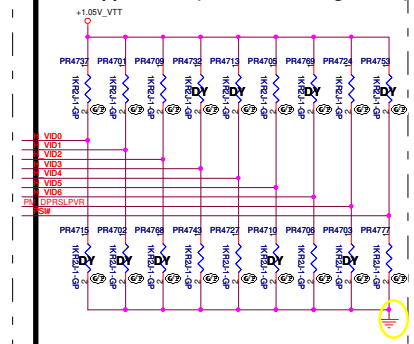
```
I/F cap: 10U 25V K1206 X5R/ 78.10622.52L
Inductor: 2.2uH PFCM063T-2R22NM Cynotec 18mohm/20mohm Isat -14Arms 68.2R210.20B
O/F cap: 220U 6.3V PS1V0J22M(25) 25mohm 2.236Arms NEC_TOKIN/77.C2271.00L
O/F cap: 100U 6.3V TEPSLE20J107M(45)8R 45mohm 1.374Arms NEC_TOKIN/77.C1071.08I
H/S: FDS8880 9.6mohm/12mohm@4.5Vgs/ 84.08880.037
L/S: FDS6676AS 5.9mohm/7.25mohm@4.5Vgs/ 84.06676.A37
```





Design Current = 48A
52.8A<OCP<67.2A

Intel support POC (Power On Configuration).




I/P cap: 100 25V K1206 X5R/ 78.10622.52L
Inductor: 0.36UH PCMC104T-R36MN1R05J Cynotec 1.05mohm/ 68.R3610.20C
O/P cap: 330U 2V EEPKX0D221E7 6mOhm 3.0Arms Panasonic/79.33719.20L
O/P cap: 220U 2V EEPKX0D331XE 7mOhm 3.4Arms Panasonic/79.22719.90L
H/S: SI7686DP/ POWERPAK-8/11mOhm/14mOhm@4.5Vgs/ 84.07686.037
L/S: SI4460DP/ POWERPAK-8/ 4.9mOhm/6.1mohm@4.5Vgs/ 84.00460.037

Core Design

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<Core Design>



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Title

Size
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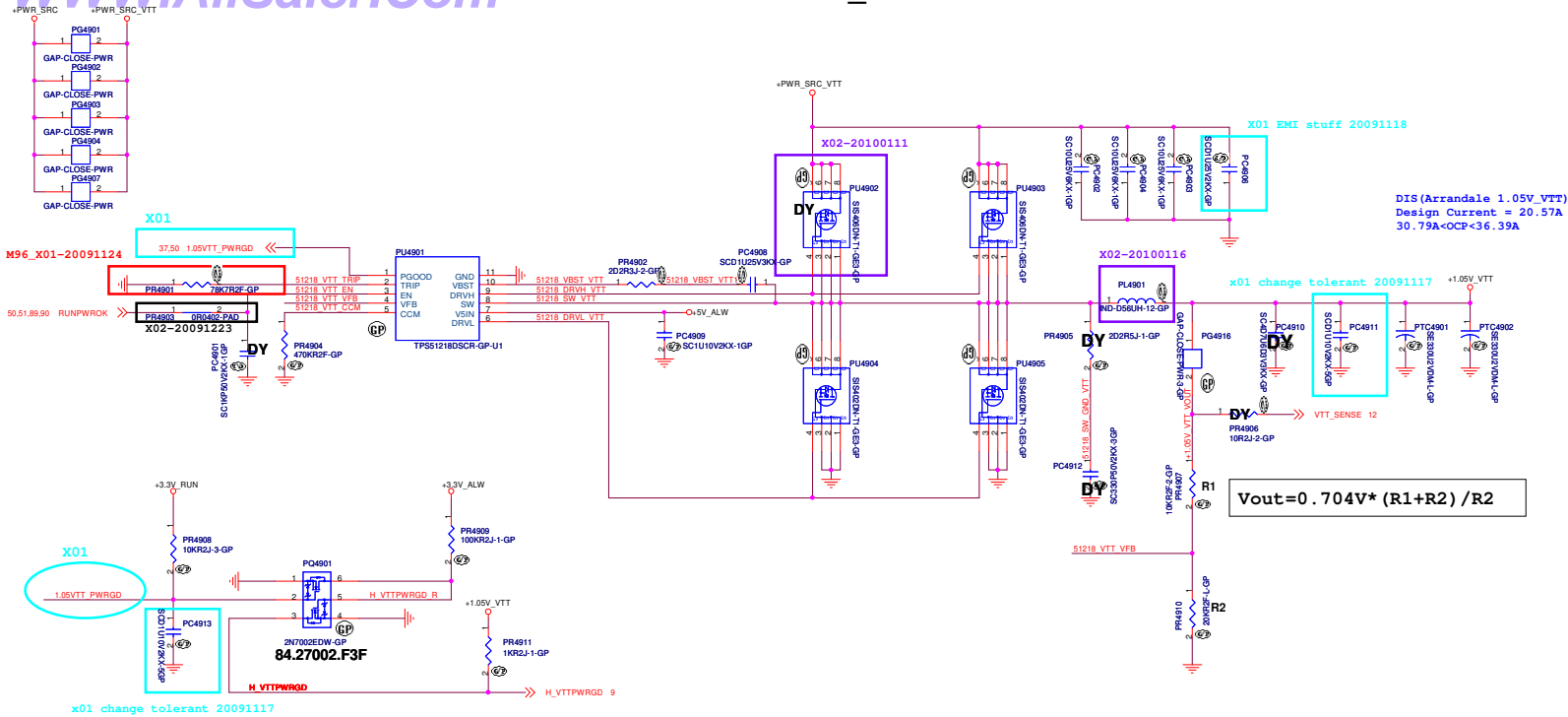
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Berry

Date: Wednesday, February 24, 2010

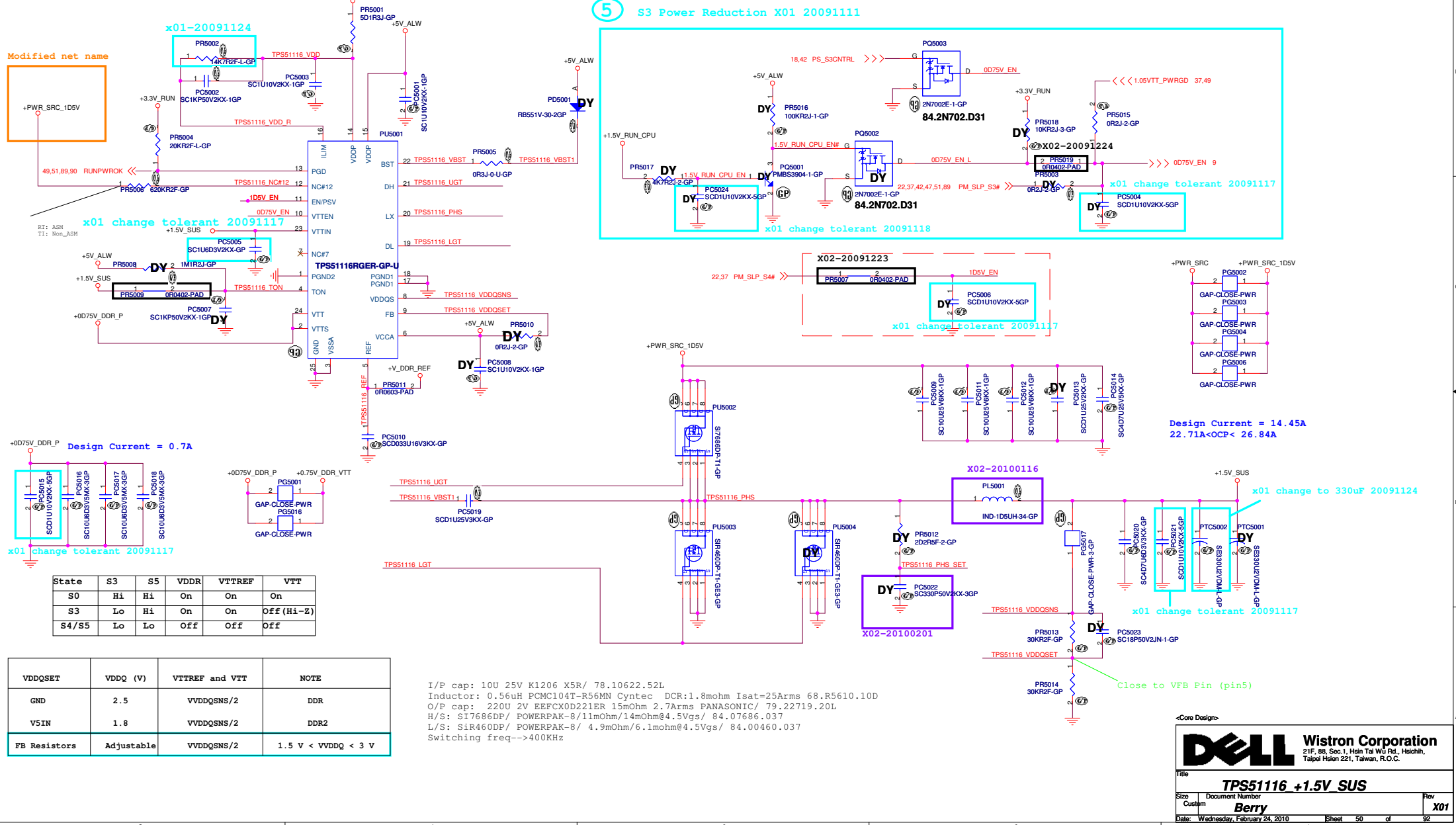
Reserved

Rev
X01

Sheet 48 of 92

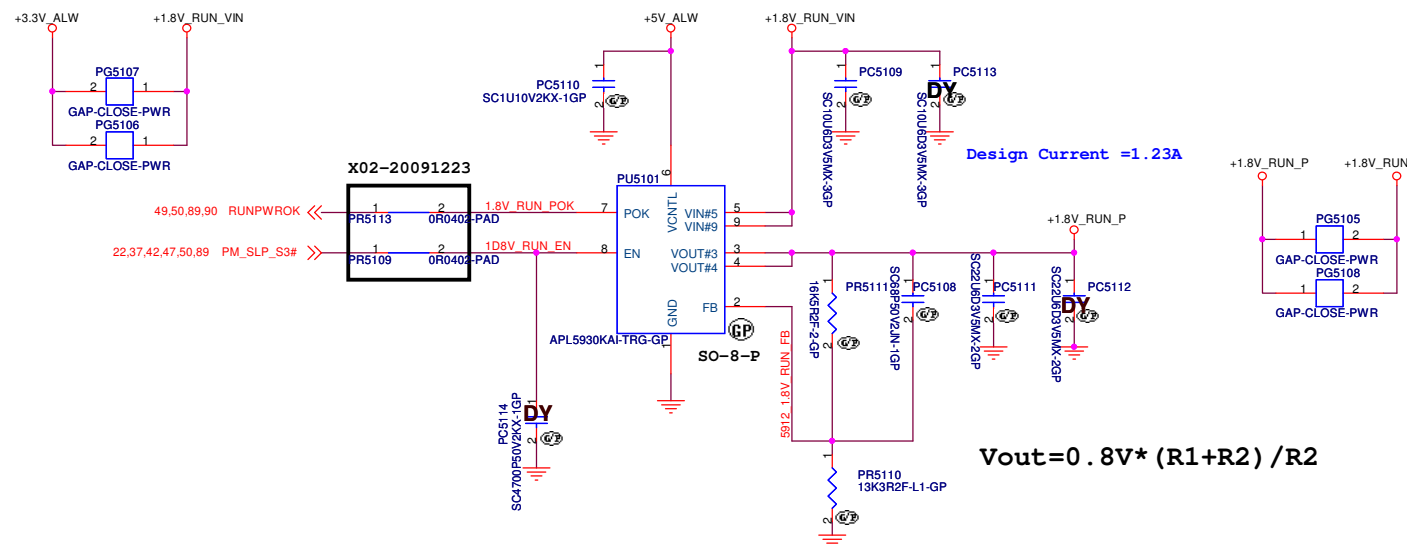


I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
 Inductor: 0.56uH PCMC104T-R56MM Cyntec DCR:1.6mohm/1.8mohm Isat=25Arms 68.R5610.10D
 O/P cap: 330U 2.5V EEFSX0D331ER 9mOhm 3Arms PANASONIC/ 79.33719.L01
 H/S: SIS406DN/ POWERPAK-8/ 11.5mOhm/14.5mOhm @4.5Vgs/ 84.00406.037
 L/S: SIS402DN/ POWERPAK-8/ 6.4mOhm/8mohm@4.5Vgs/ 84.00402.037



SSID = PWR.Plane.Regulator_1p8v

APL5930 for +1.8V_RUN




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DELL		Wistron Corporation	
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Title			
APL5930 +1.8V RUN			
Size	Document Number	Rev	
A3	Berry	X01	
Date: Wednesday, February 24, 2010		Sheet	51 of 92

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Title

Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010

Reserved

Rev
X01

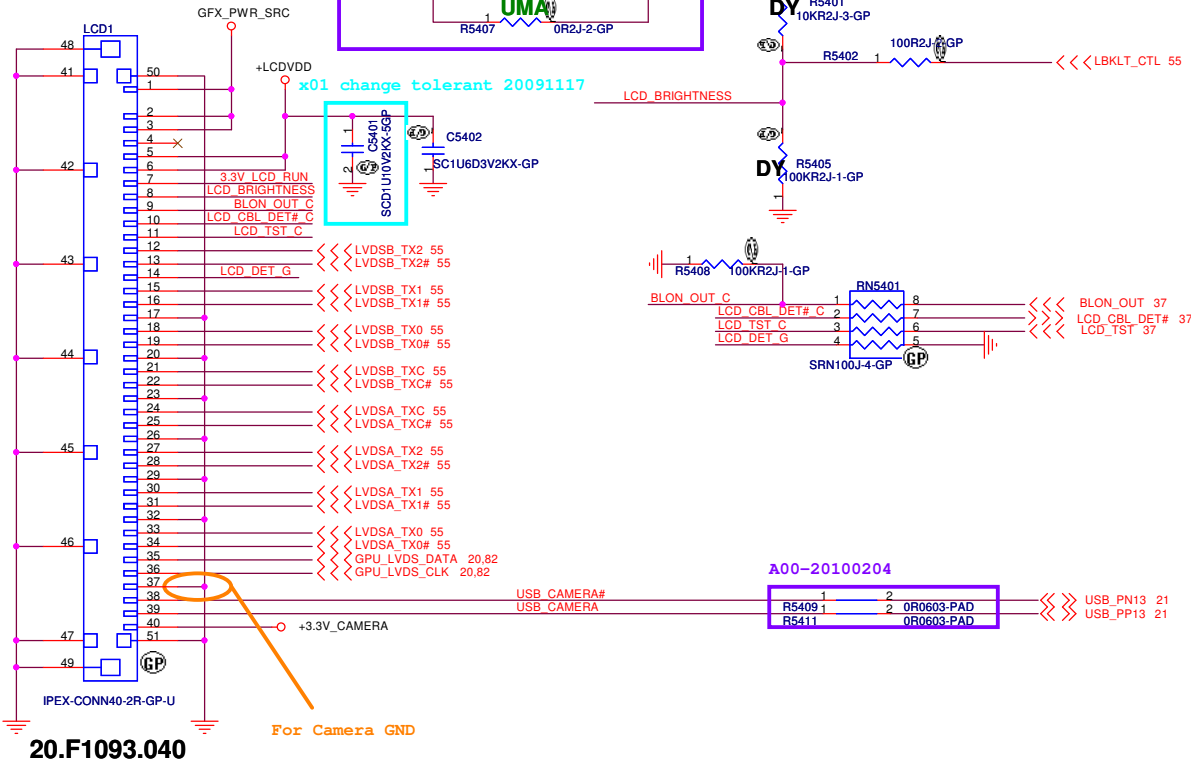
Sheet 52 of 92



SSID = VIDEO

x02-20091208

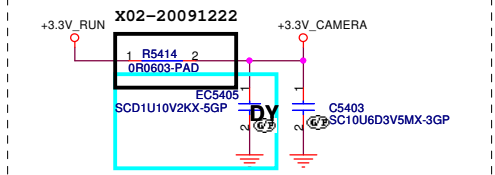
LVDS CONNECTOR



20.F1093.040

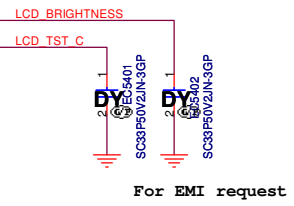
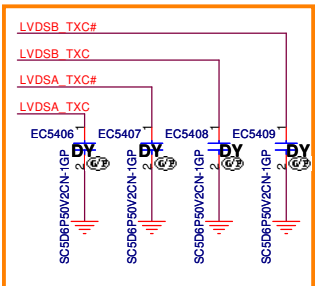
For Camera GND

Camera Power



x01 change tolerant 20091117

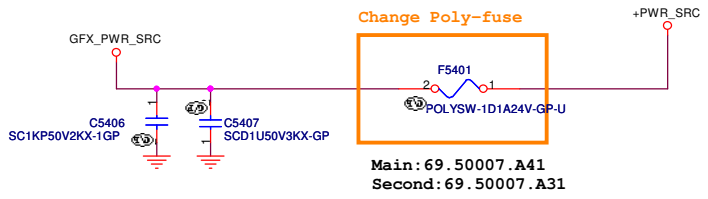
Close to LVDS connector



For EMI request

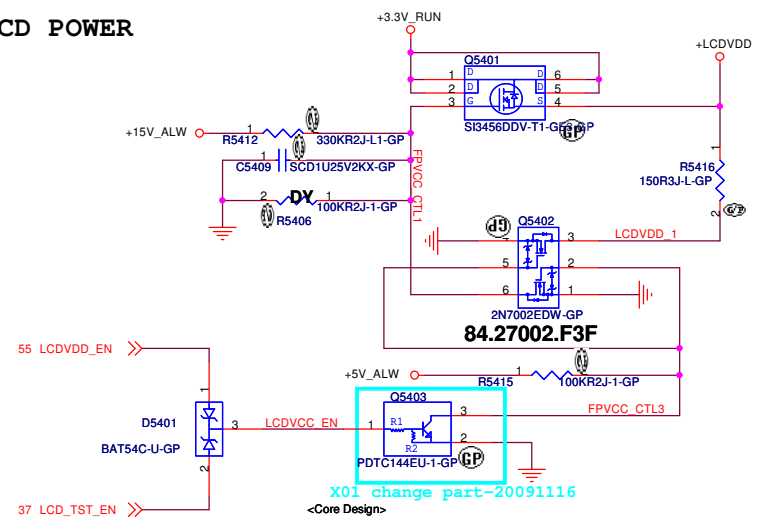
SSID = Inverter

INVERTER POWER



SSID = VIDEO

LCD POWER



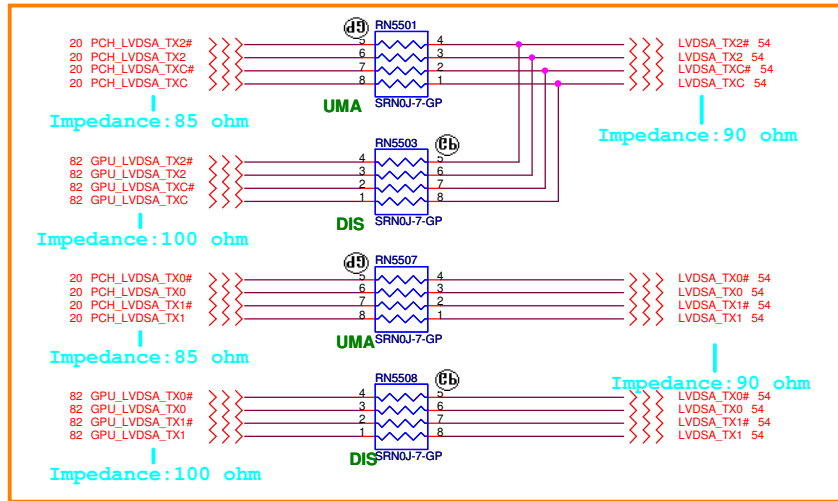
DELL Wistron Corporation
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Taipei Hsien 221, Taiwan, R.O.C.

Title: **LCD/Inverter Connector**

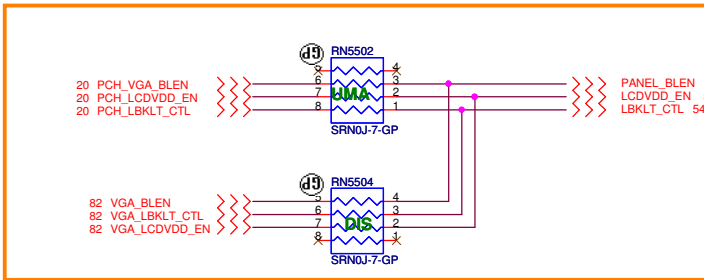
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Date: Wednesday, February 24, 2010 Sheet: 54 of 92

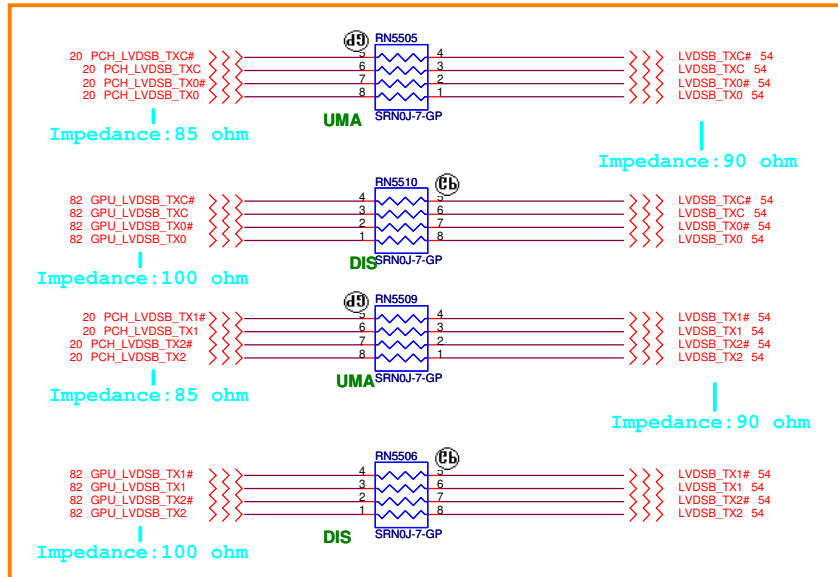
LVDS Channel A



Panel BL brightness/Power En/BL En



LVDS Channel B




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Title			
LVDS Switch			
Size	Document Number	Rev	
	Berry	X01	
Date:	Wednesday, February 24, 2010	Sheet	55 of 92

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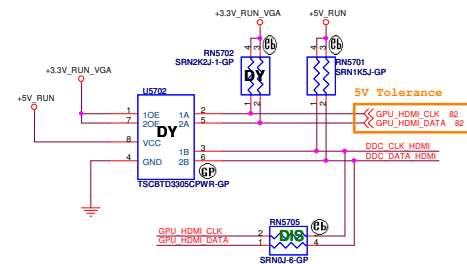
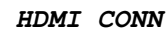
Title

LVDS Switch

Size	Document Number	Rev
A3	Berry	X01

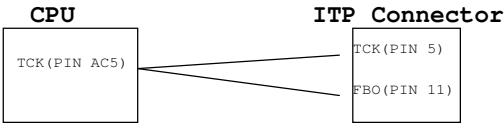
Date: Wednesday, February 24, 2010	Sheet 56 of 92
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HDMI Level Shifter & CONNECTOR



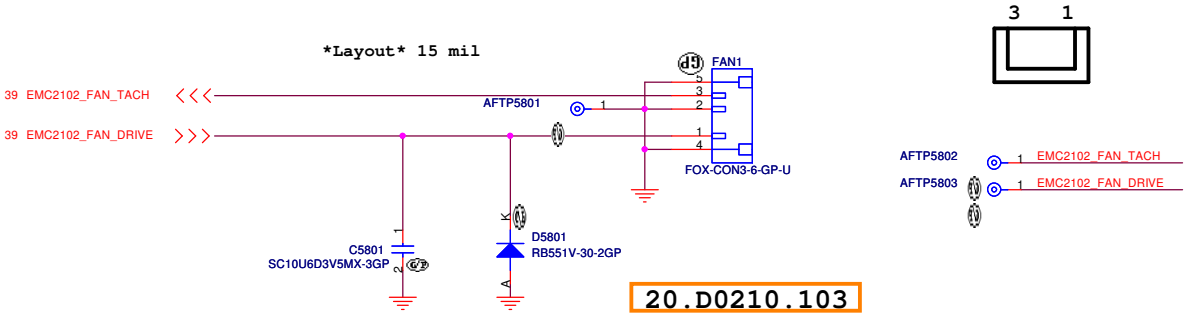
ITP Connector

H_CPURST# use pull-up Resistor close
ITP connector 500 mil (max),
others place near CPU side.

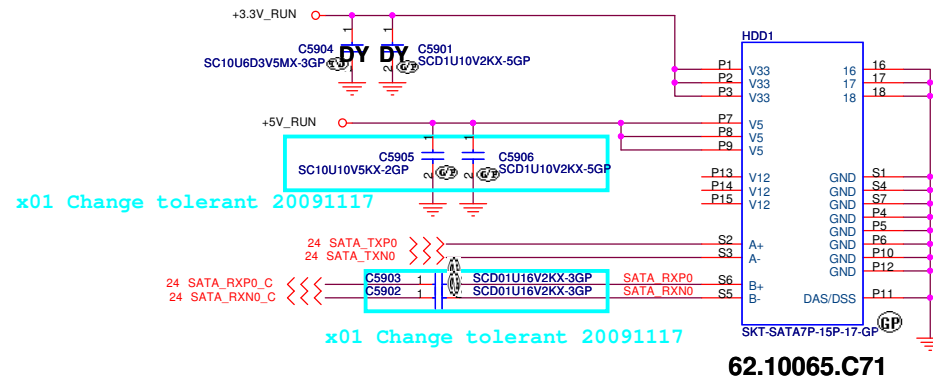


SSID = Thermal

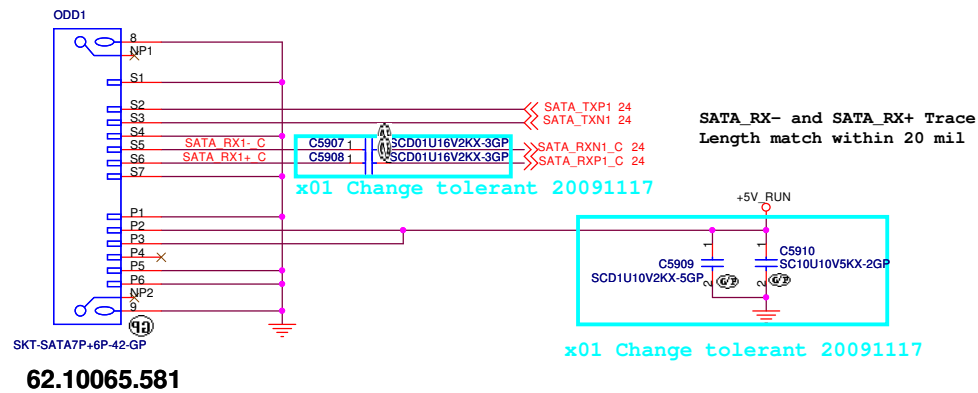
Fan Connector



SATA HDD Connector



ODD Connector



<Core Design>

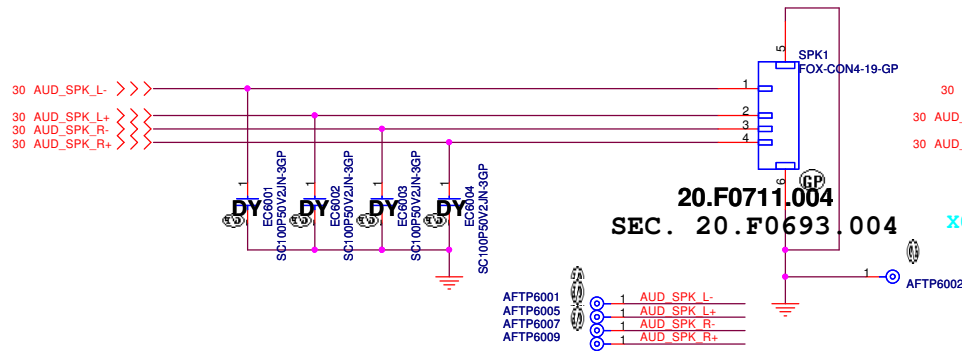


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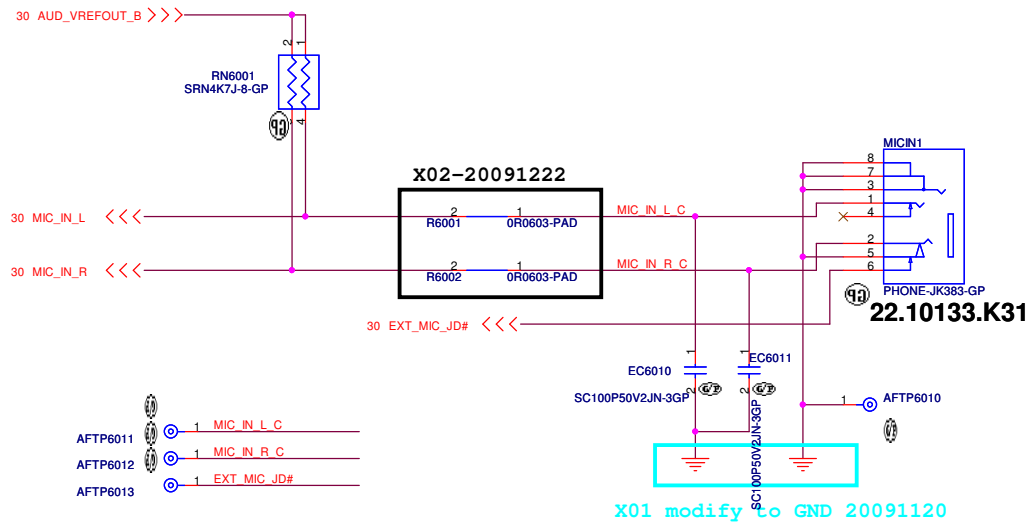
Title			
HDD/ODD			
Size A3	Document Number Berry	Rev X01	
Date: Wednesday, February 24, 2010	Sheet 59	of	92

SSID = AUDIO

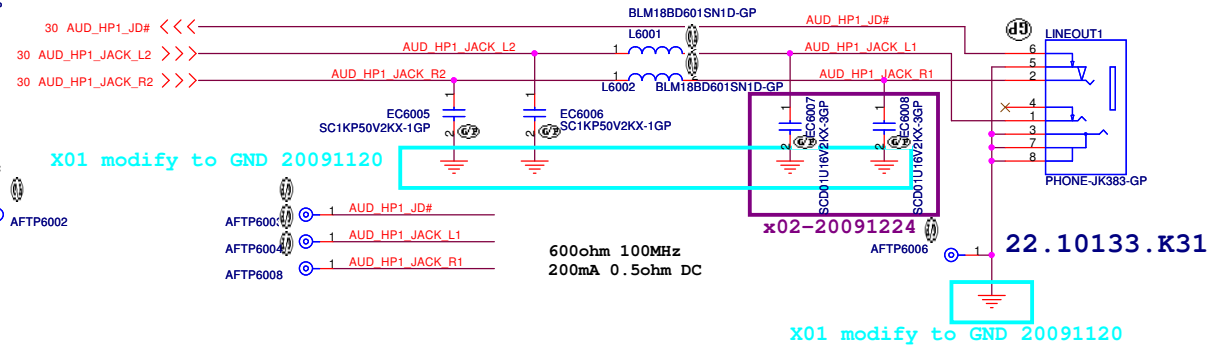
Speaker Connector



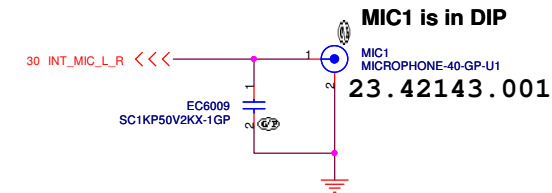
MIC IN



LINE1 OUT



Internal Microphone



X02-20100206

<Core Design>


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Title			Audio Jack	
Size	Document Number			Rev
A3	Berry			X01
Date: Wednesday, February 24, 2010		Sheet	60	of 92

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Title

Size
A3

Document Number
Berry

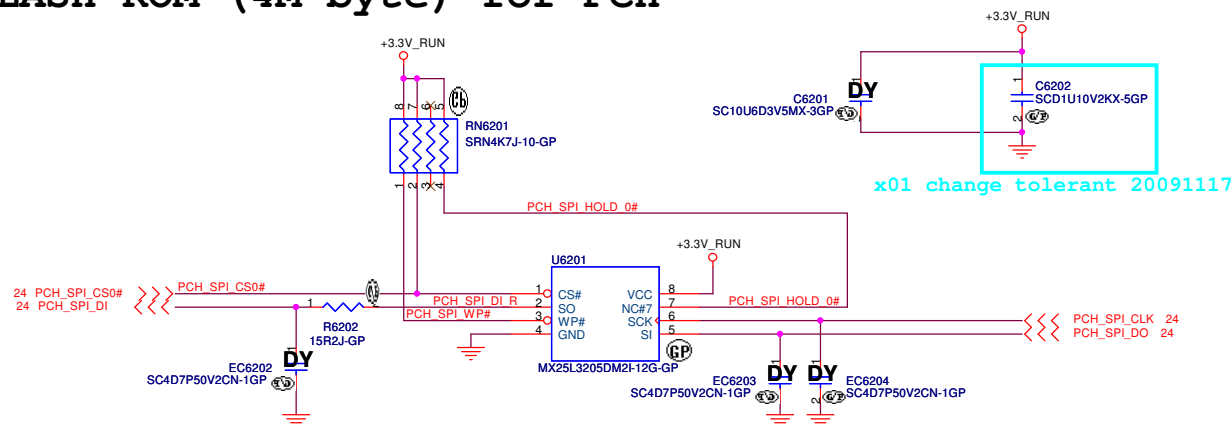
Date: Wednesday, February 24, 2010

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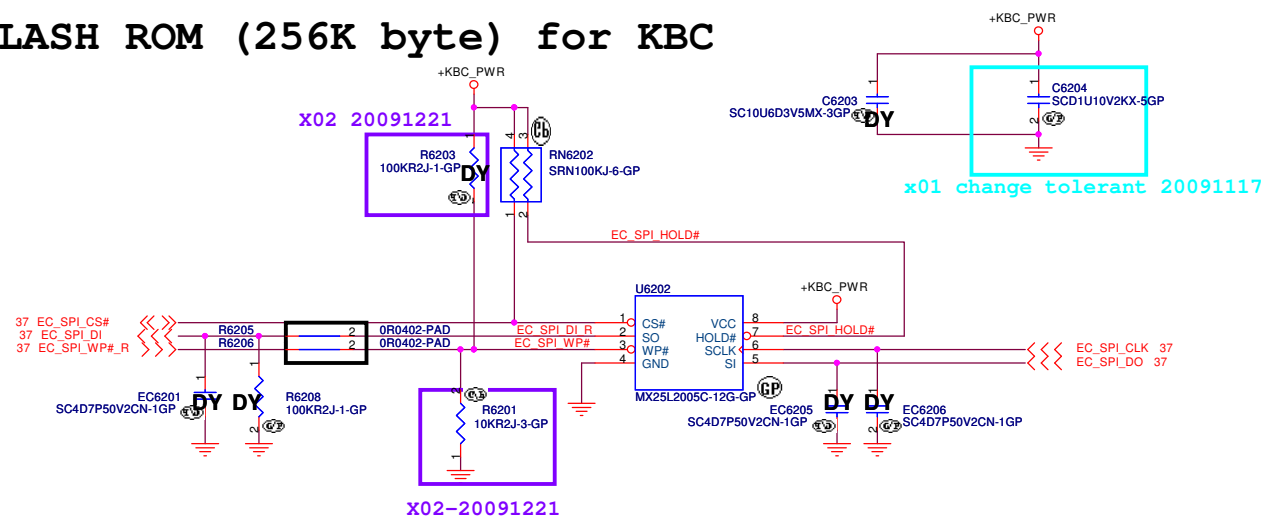
Rev
X01

Sheet 61 of 92

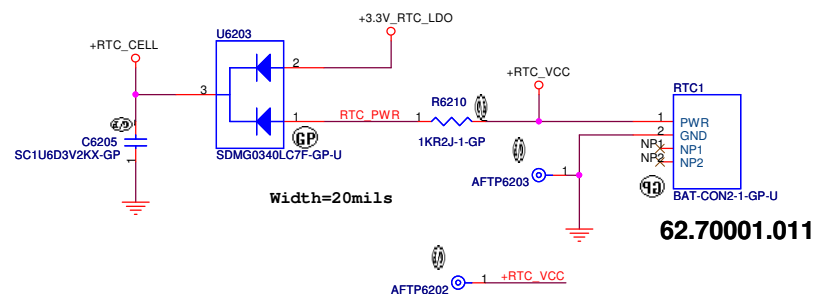
SPI FLASH ROM (4M byte) for PCH



SPI FLASH ROM (256K byte) for KBC



SSID = RBATT



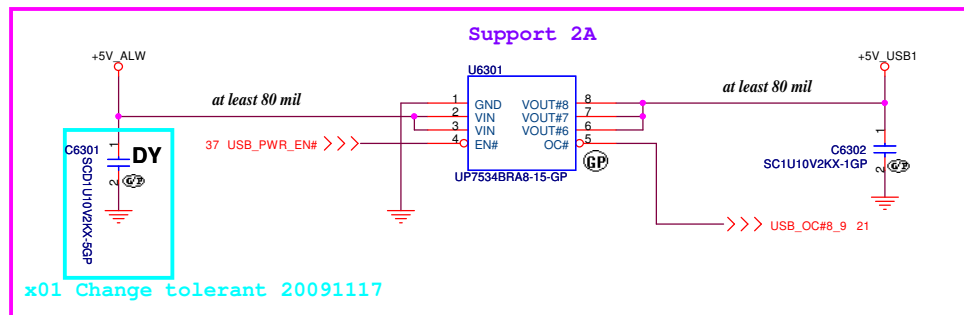
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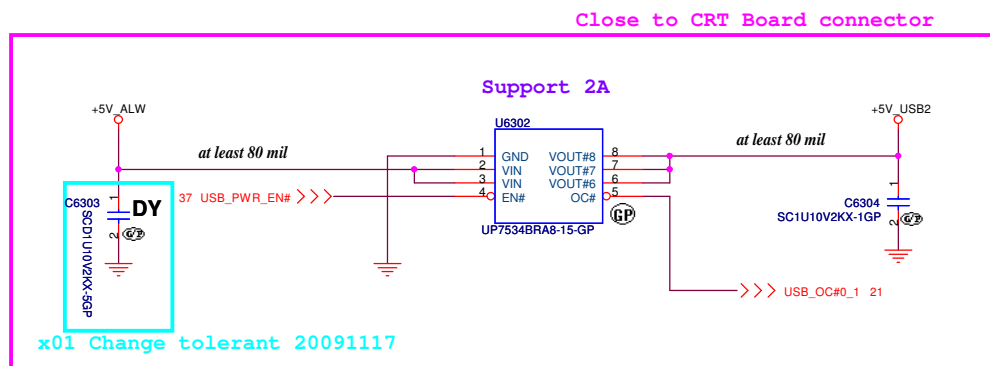
Title			Flash/RTC	
Size	Document Number	Rev		
A3	Berry	X01		
Date:	Wednesday, February 24, 2010	Sheet	62	of 92

IO Board USB Power

USB POWER SW
Main UP7534BRA8-15 P/N:74.07534.079
SEC AP2101MPG-13 P/N: 74.02101.079



CRT Board USB Power



<Core Design>



Title			Rev
USB Power SW			X01
Size	Document Number	Berry	
Date: Wednesday, February 24, 2010	Sheet 63	of 92	

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Title

Reserved

Size
A4

Document Number
Berry


Rev
X01

Date: Wednesday, February 24, 2010

Sheet 64 of 92

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<Core Design>



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Taipei Hsien 221, Taiwan, R.O.C.

Title

Size
A3

Document Number
Berry

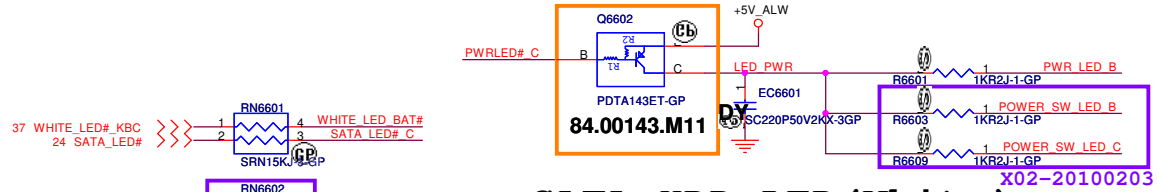
Date: Wednesday, February 24, 2010

Rev
X01

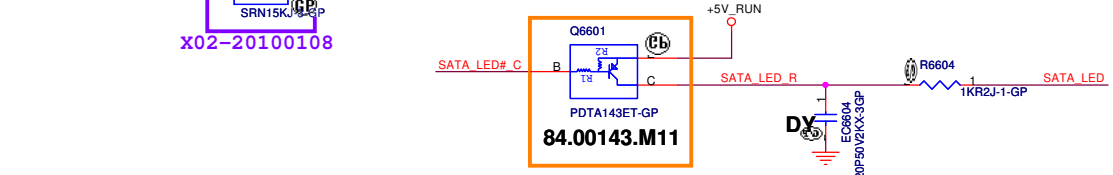
Sheet 65 of 92

Reserved

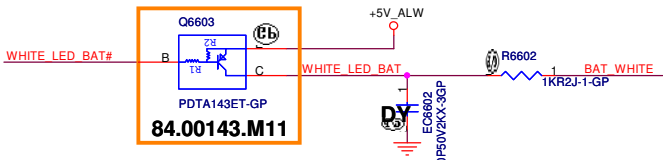
Power LED (White)



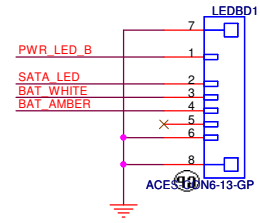
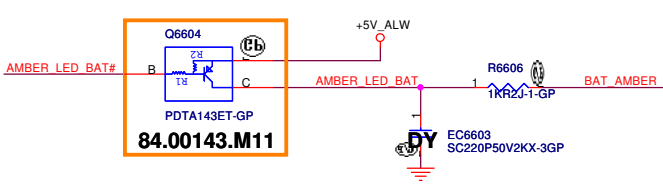
SATA HDD LED (White)



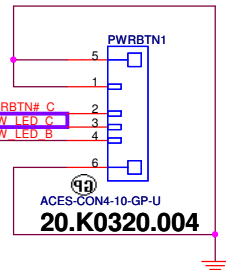
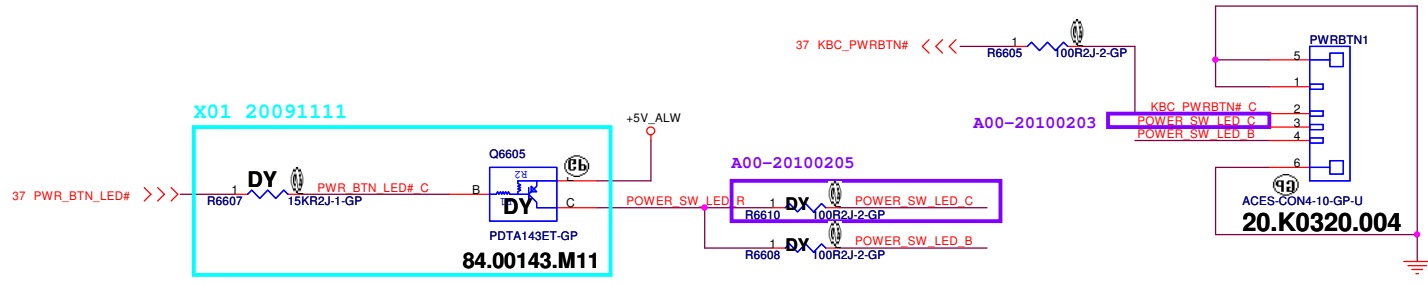
Battery LED1 (White)



Battery LED2 (Amber)




Power button LED (White)



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<Core Design>



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Title

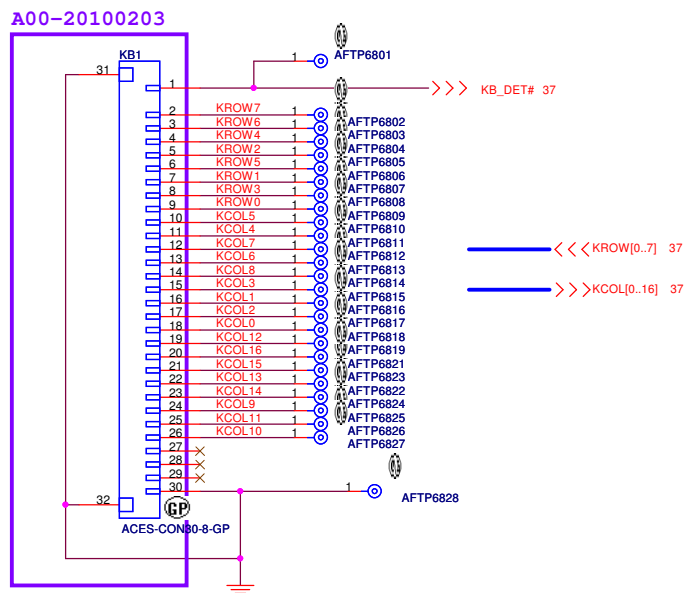
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Size A3	Document Number Berry	Rev X01
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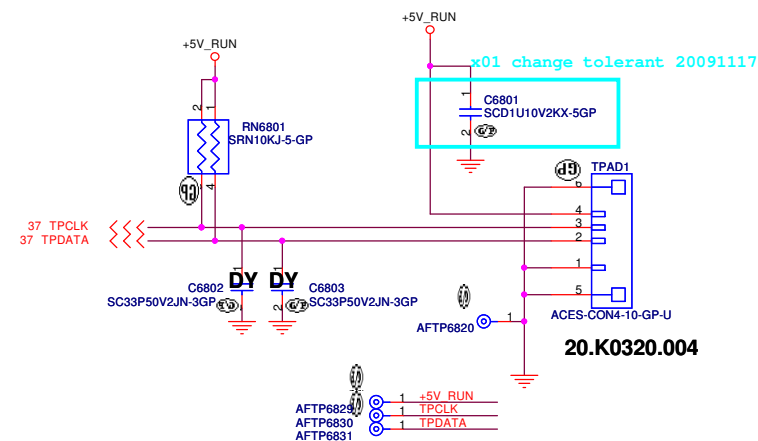
Date: Wednesday, February 24, 2010	Sheet 67 of 92
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```
SSID = Touch.Pad
```

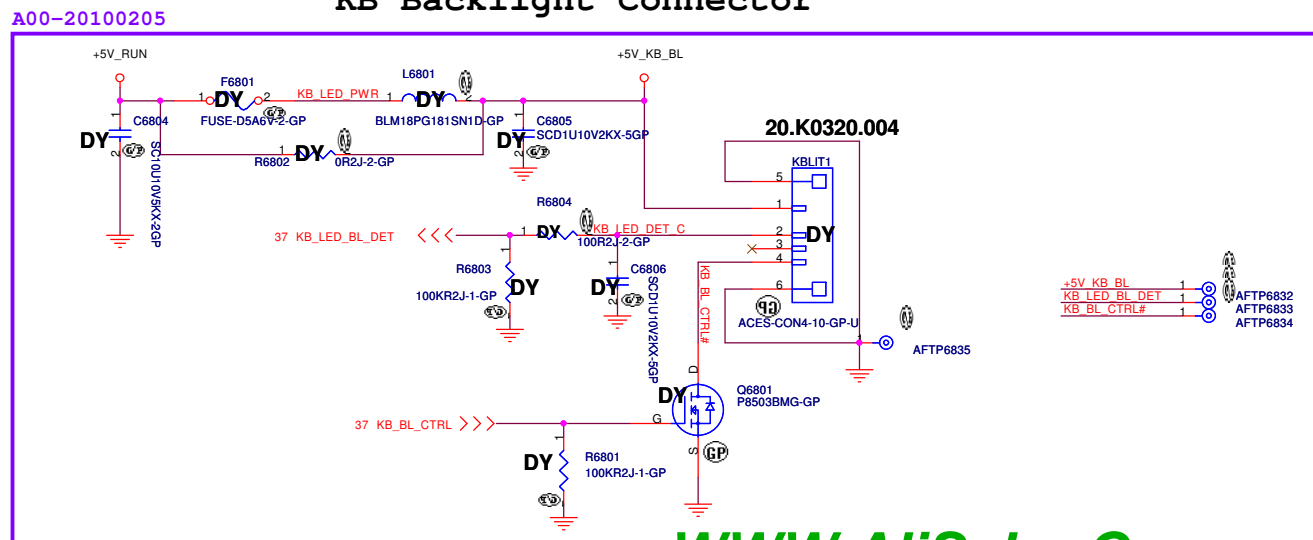
Internal KeyBoard Connector



TouchPad Connector



KB Backlight Connector



<Core Design>

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Title

Key Board/Touch Pad

Size
A

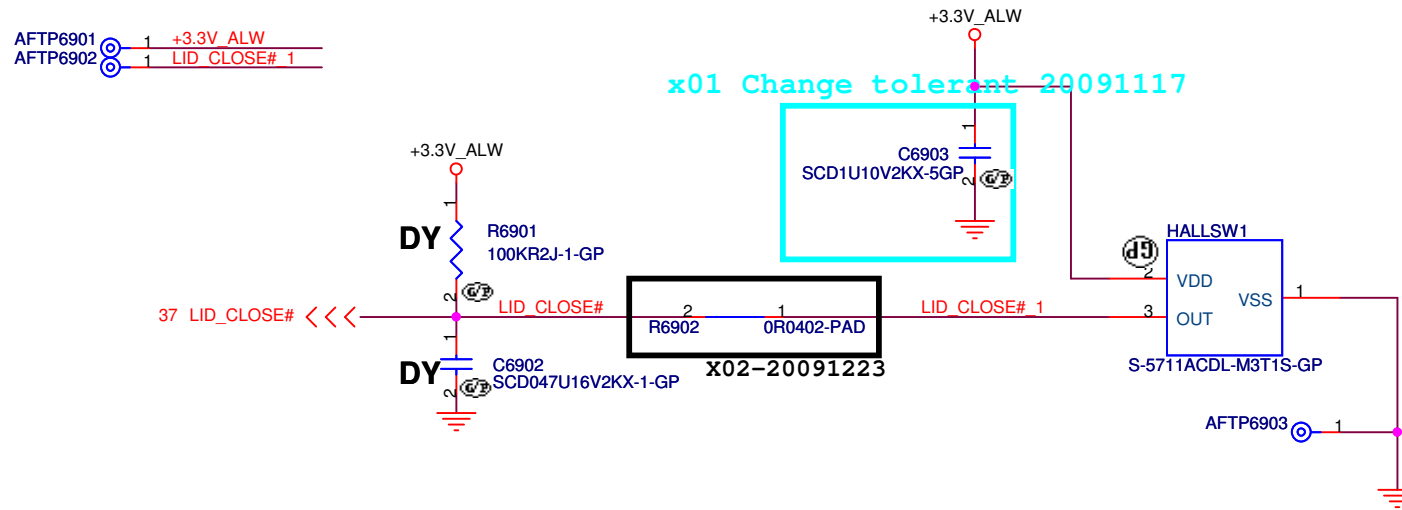
Document Number
Berry

Rev	X01
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Date: Wednesday, February 24, 2010

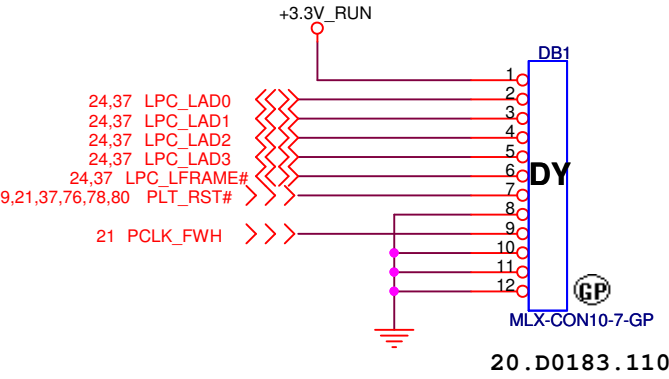
Sheet 68 of 9

9




<Core Design>

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Title Hall Sensor			
Size A4	Document Number Berry		Rev X01
Date: Wednesday, February 24, 2010		Sheet 69 of 92	



<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Dubug connector			
Size A4	Document Number Berry		Rev X01
Date: Wednesday, February 24, 2010		Sheet 70 of 92	

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<Core Design>



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Title

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Size
A4

Document Number
Berry


Rev
X01

Date: Wednesday, February 24, 2010

Sheet 71 of 92

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<Core Design>



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Taipei Hsien 221, Taiwan, R.O.C.

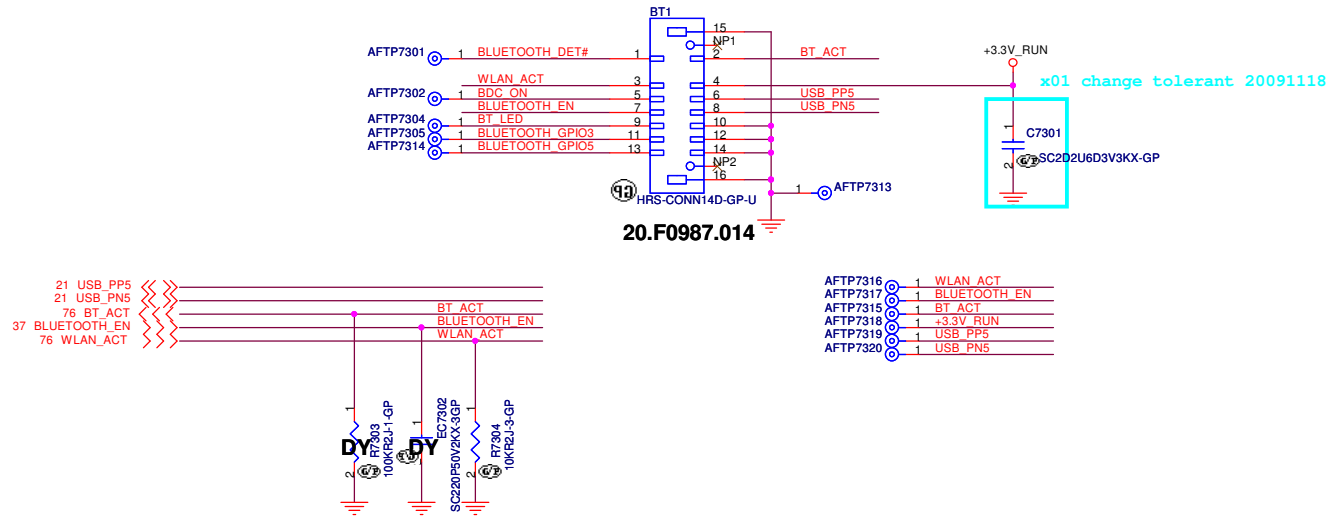
Title

RESERVED

Size A3	Document Number Berry	Rev X01
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Date: Wednesday, February 24, 2010	Sheet 72 of 92
------------------------------------	----------------

Bluetooth Module conn.



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Title

Bluetooth

Size
A3

Document Number

Berry

Rev


X01

Date: Wednesday, February 24, 2010

Sheet 73 of 92

(Blanking)

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Title

Size
A3

Document Number
Berry

Date: Wednesday, February 24, 2010

Reserved

Rev
X01

Sheet 74 of 92

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<Core Design>



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Title

Reserved

Size
A4

Document Number

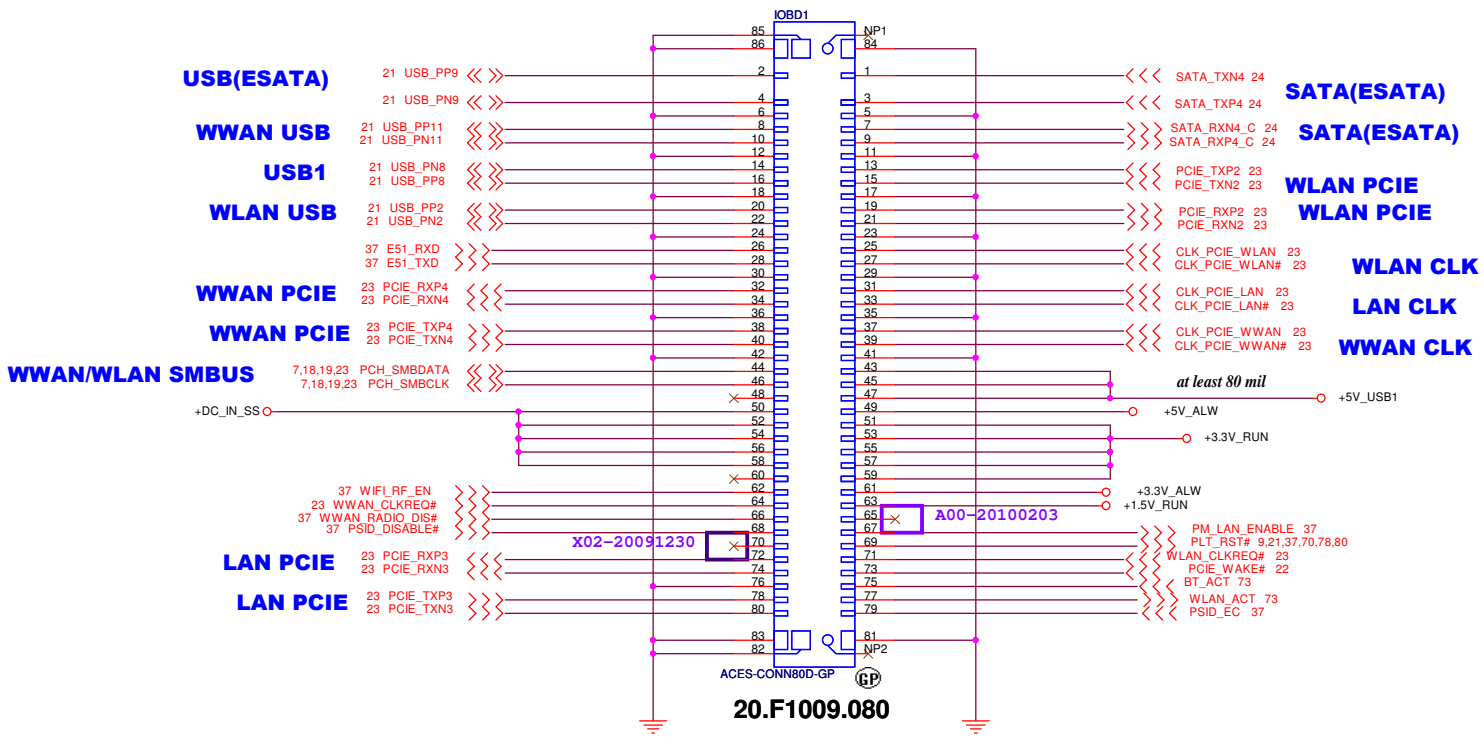
Berry

Rev

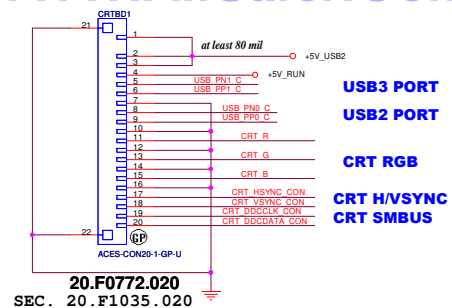
X01

Date: Wednesday, February 24, 2010

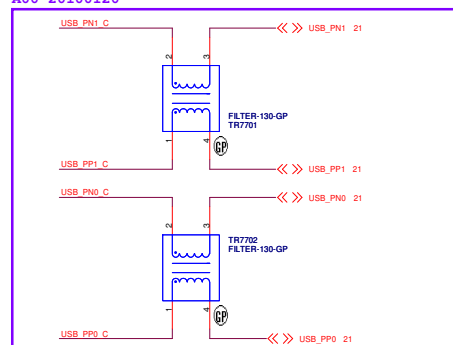
Sheet 75 of 92



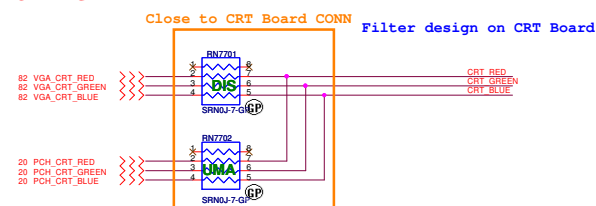
CRT Board Connector



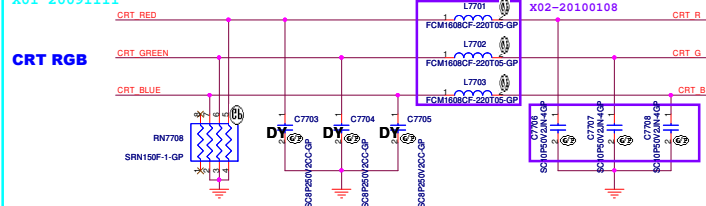
A00-20100120



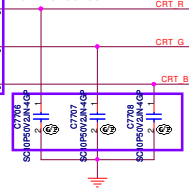
CRT RGB



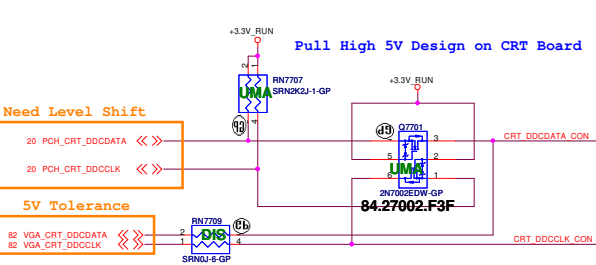
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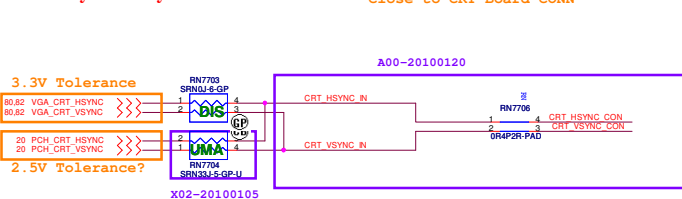
X02-20100108



CRT DDCDATA & DDCCLK level shift



CRT Hsync & Vsync level shift



<Core Design>

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CRT Board Connector			
File	Document Number	Rev	X01
Size	A2	Berry	
Date	Wednesday, February 24, 2010	Sheet	77 of 92

The diagram illustrates the electrical connections for the MLX-CON6-21-GP module. The module is a blue rectangular component with 8 pins. Pins 1 through 6 are connected to a USB cable, with labels for USB_PN4_C and USB_PP4_C. Pins 7 and 8 are connected to a power source labeled +3.3V_RUN. A red box highlights the label 'x01 20091121' in the top left corner. The module is also labeled '20.F1035.006'. A transformer (TR7801) and a filter (FILTER-130-GP) are shown in the bottom left corner, connected to the USB lines. The module is labeled 'A00-20100120' in the top center.

<Core Design>



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Title	Author	Year	Journal	Volume	Issue	Page
1. The Effect of Temperature on the Rate of Reaction	John Doe	2018	Journal of Chemical Education	95	3	456-462
2. Kinetics of the Reaction Between Hydrogen Peroxide and Potassium Iodide	Jane Smith	2017	Journal of Chemical Education	94	2	123-129
3. The Effect of Concentration on the Rate of Reaction	Michael Brown	2016	Journal of Chemical Education	93	1	78-84
4. The Effect of Surface Area on the Rate of Reaction	Sarah White	2015	Journal of Chemical Education	92	4	567-573
5. The Effect of Catalyst on the Rate of Reaction	David Green	2014	Journal of Chemical Education	91	5	678-684

CARD Reader CONN

Document Number

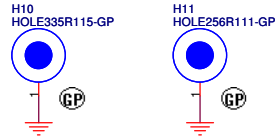
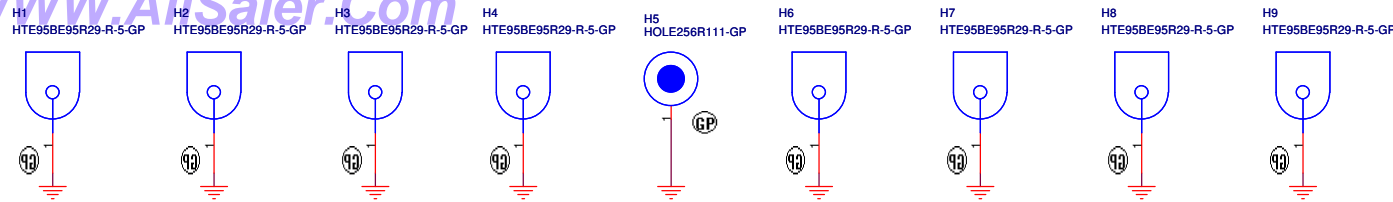
Berry

Rev

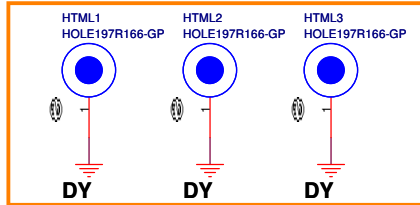
X01

Date: Wednesday, February 24, 2010

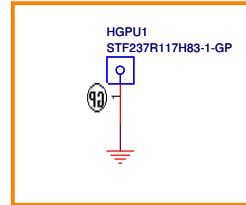
Sheet 78 of 92



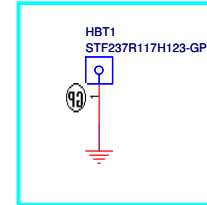
CPU Thermal module hole



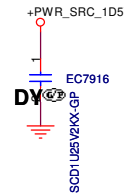
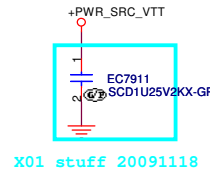
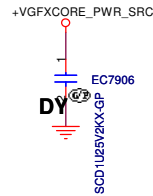
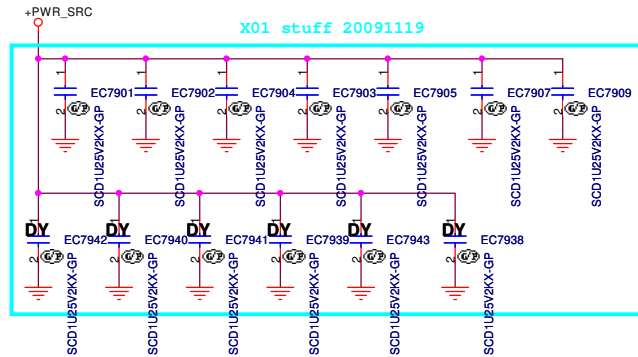
GPU Thermal module hole



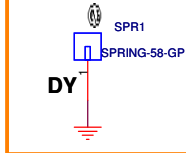
stand off



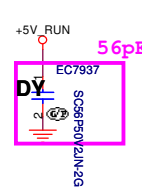
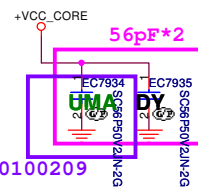
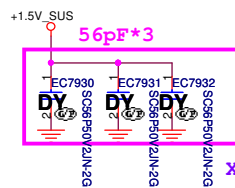
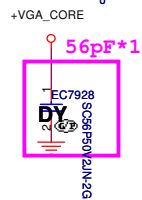
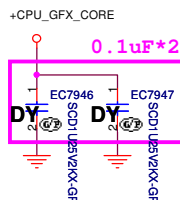
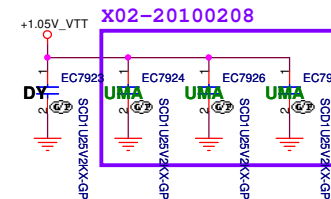
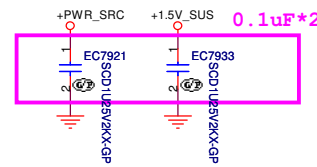
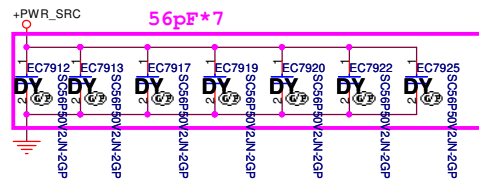
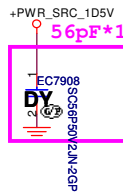
EMI Reserve



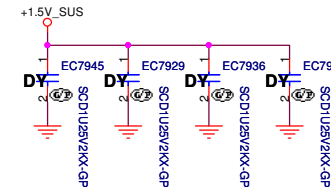
EMI Reserve



X01 RF Reserved-20091118



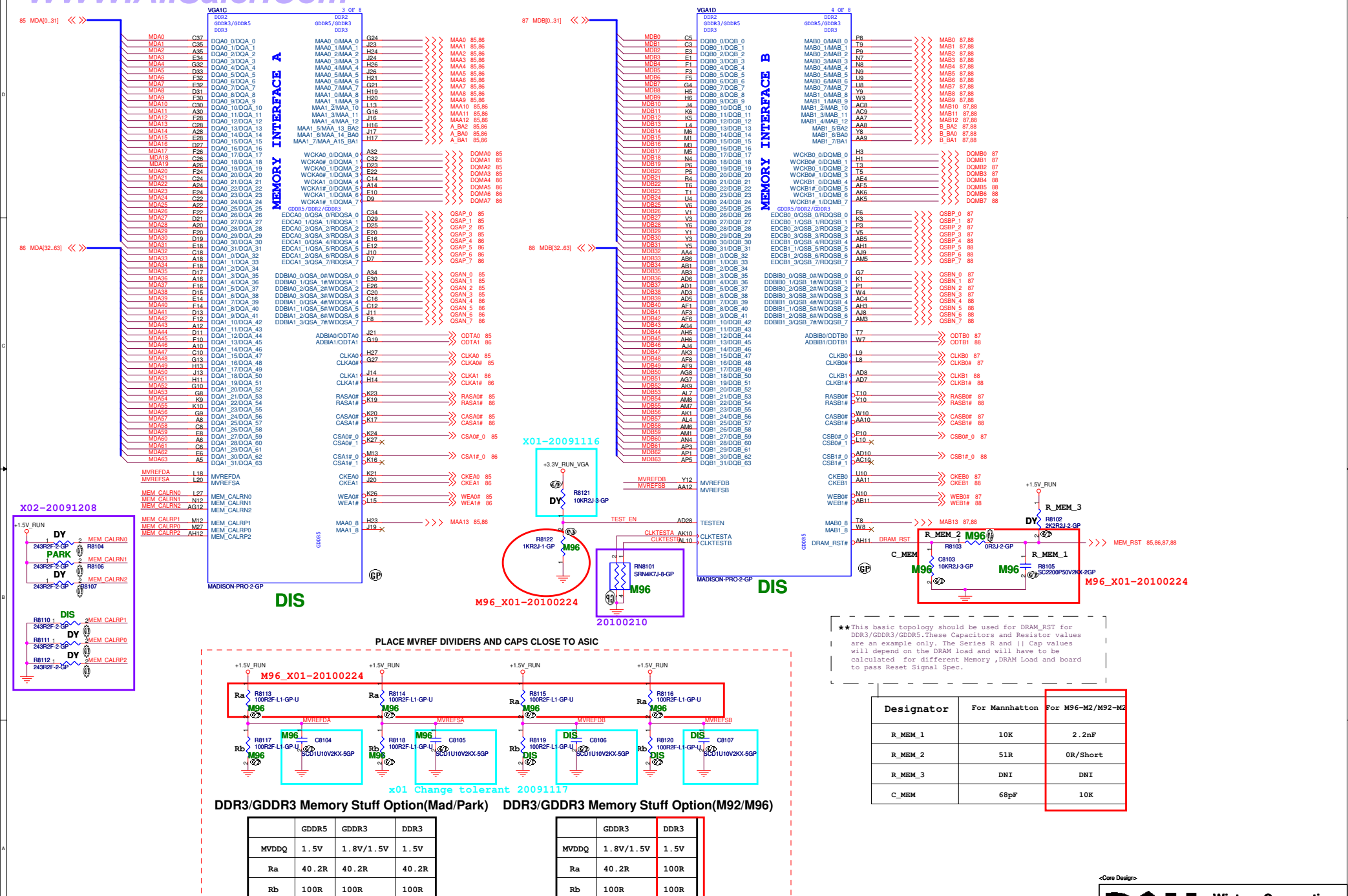
X02-20100209



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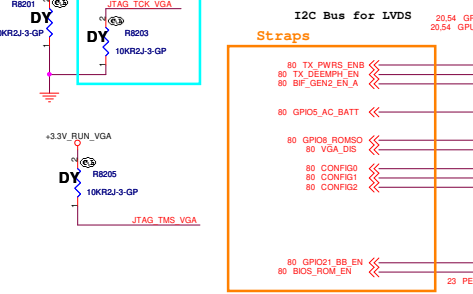
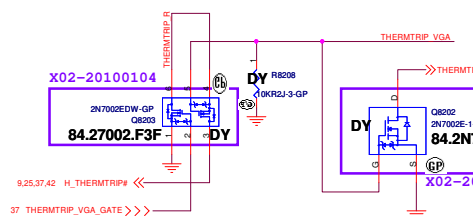
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Title	UNUSED PARTS/EMI Capacitors		
Size	Document Number	Rev	
A3	Berry	X01	
Date:	Wednesday, February 24, 2010	Sheet	79 of 92

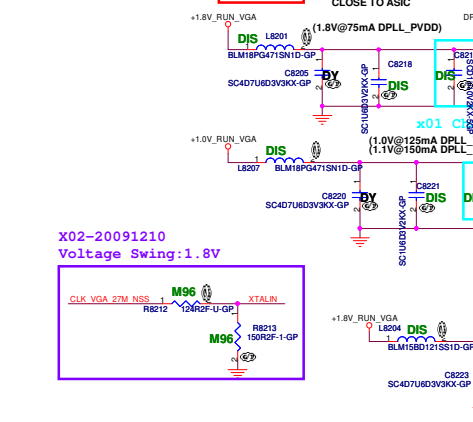


DVPDATA[0:3]	Description
0001	DDR3 Hynix-H5TQ1G63BFR-12C (800MHz) 64M*16
0011	DDR3 Hynix-H5TQ2G63BFR-12C (800MHz) 128M*16
0010	DDR3 SAMSUNG K4W2G1646B-HC12 (800MHz) 128M*16
0000	DDR3 SAMSUNG-K4W1G1646B-HC12 (800MHz) 64M*16

DVPDATA[0:3] Default: Pull down

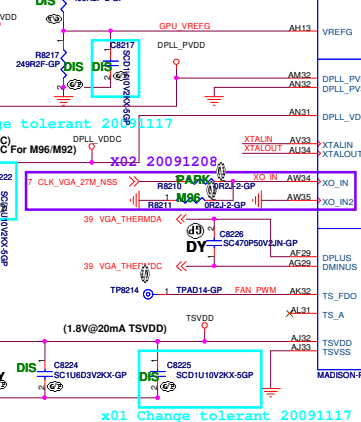
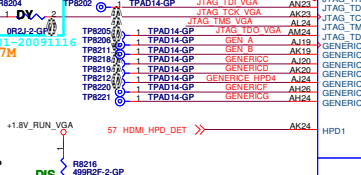
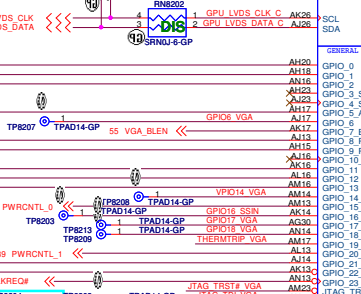
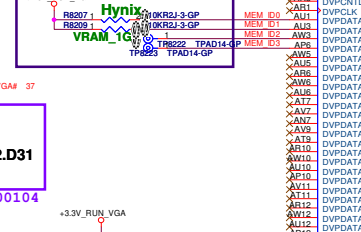


Signal	Normal mode	Debug mode	pilot run mode
JTAG_TRST#	"1" (PU)	"1" (PU)	"0" (PD)
JTAG_TCK	"0" (PD)	"1" (PU)	NC
JTAG_TMS	"1" (PU)	"1" (PU)	NC

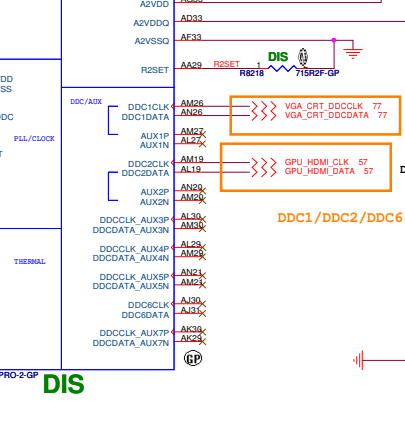
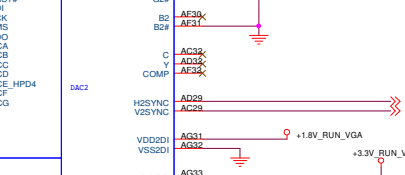
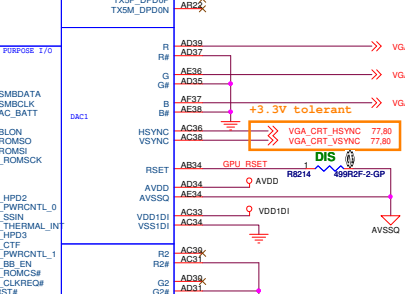
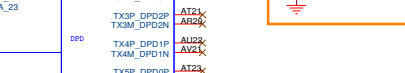
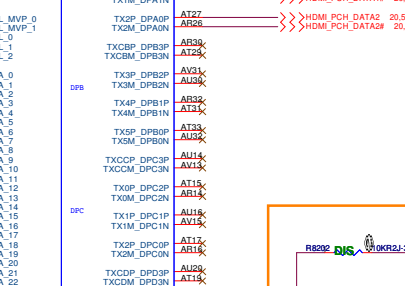


Clock Input Configuration - GDDR3/DDR3
a) 27MHz crystal connected to XTALIN or XTALOUT or
c) 27MHz (1.8V) oscillator connected to XTALIN or
c) 27MHz (3.3V) oscillator connected to XO_IN (Park, Madison, and Broadway only)

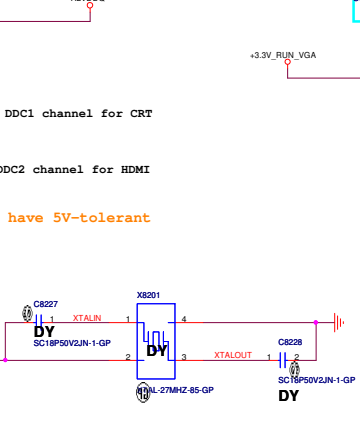
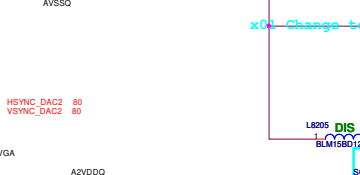
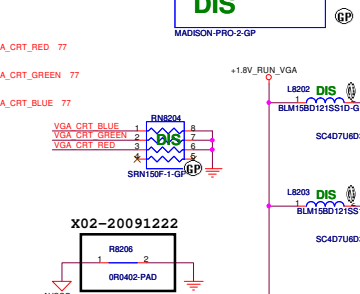
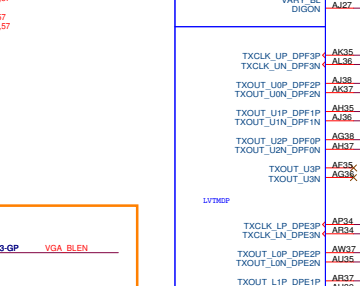
MEM ID Control



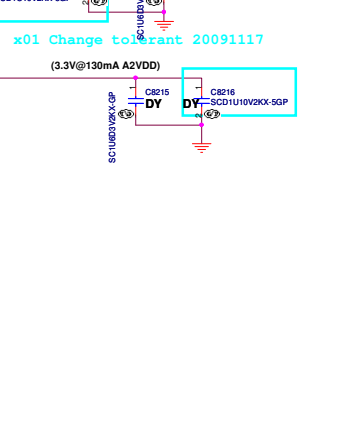
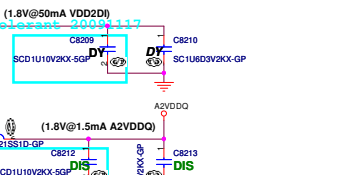
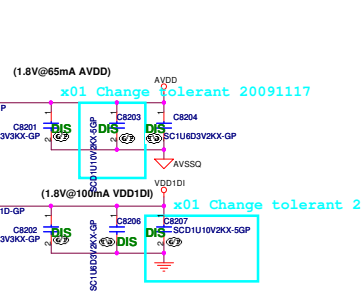
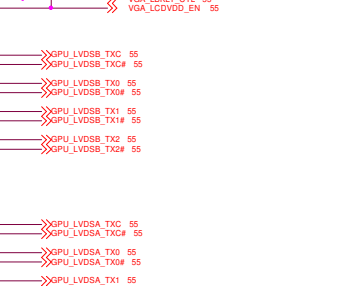
For new version no 27M



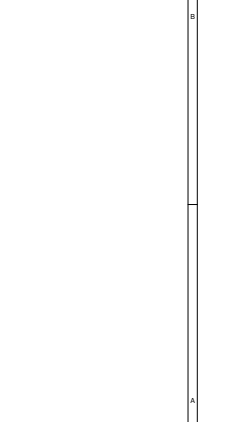
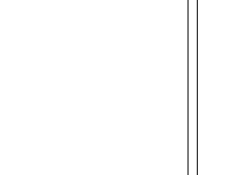
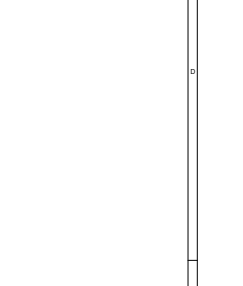
DIS



DIS

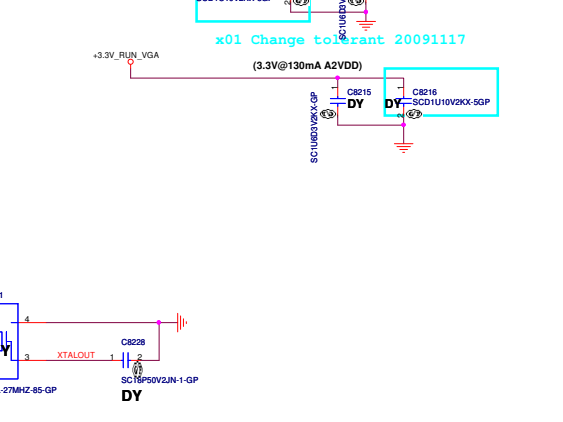
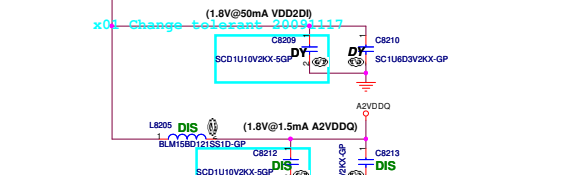
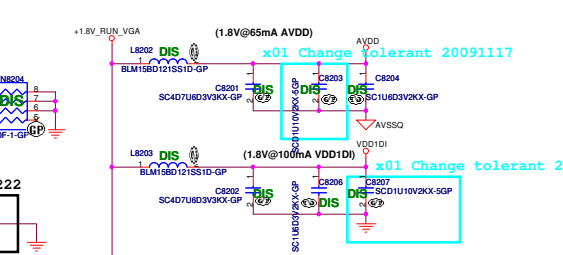
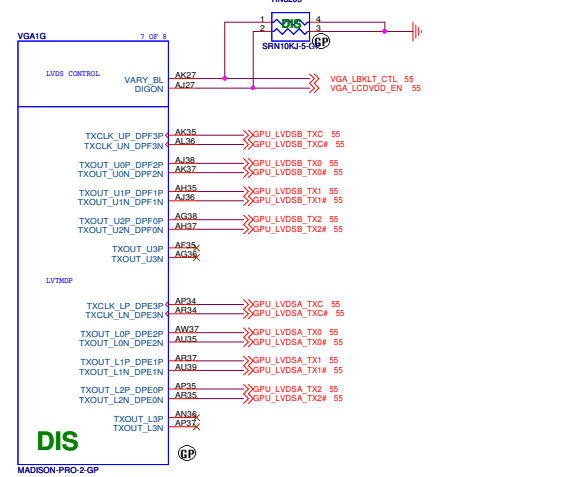


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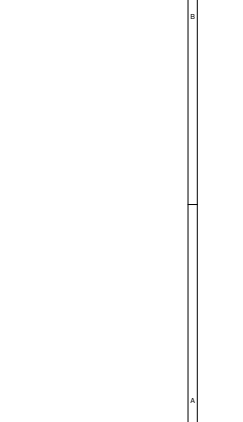
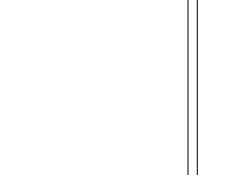
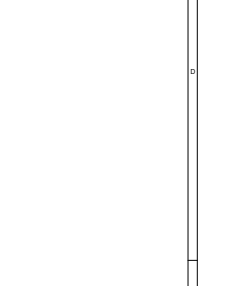


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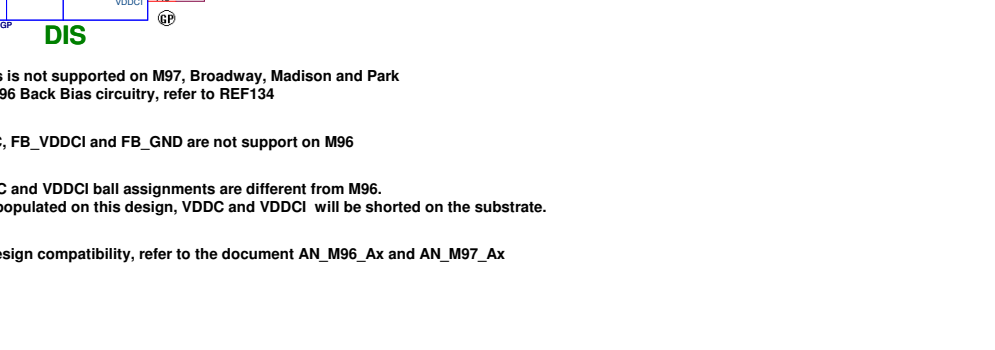
LVDS Interface

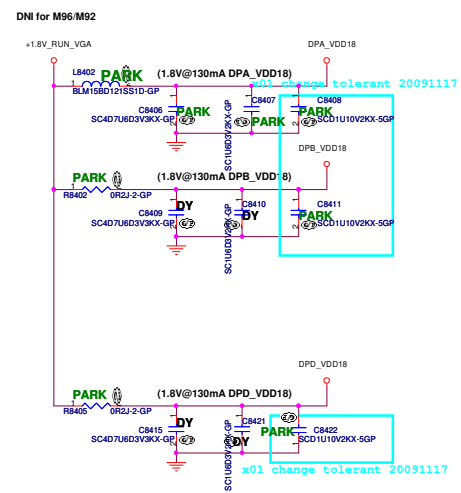
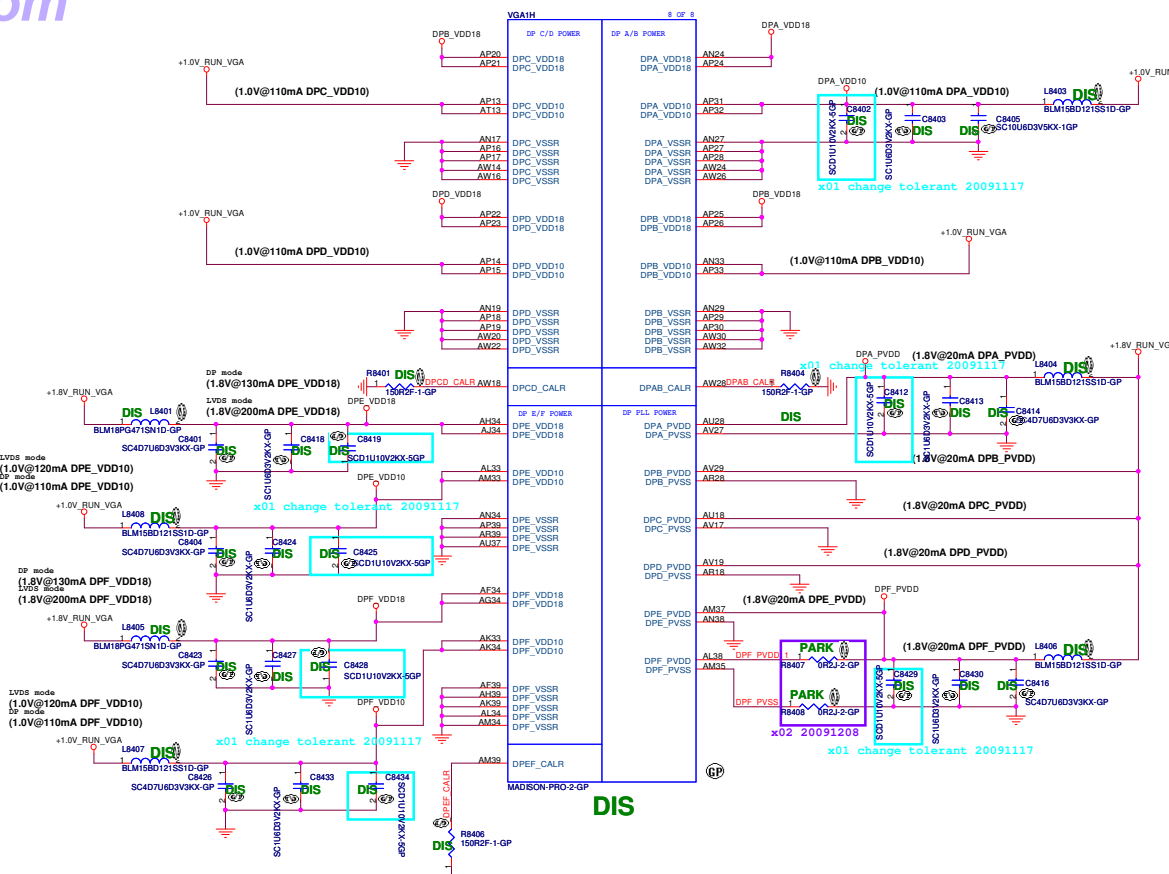
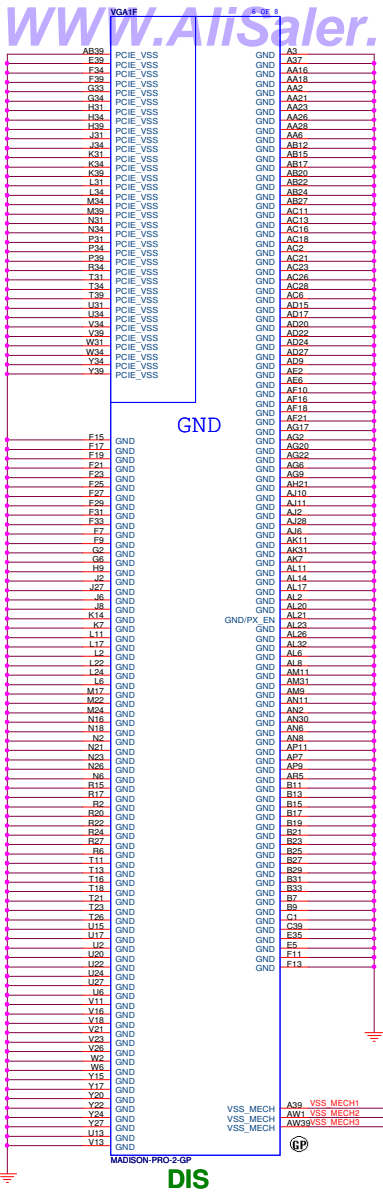


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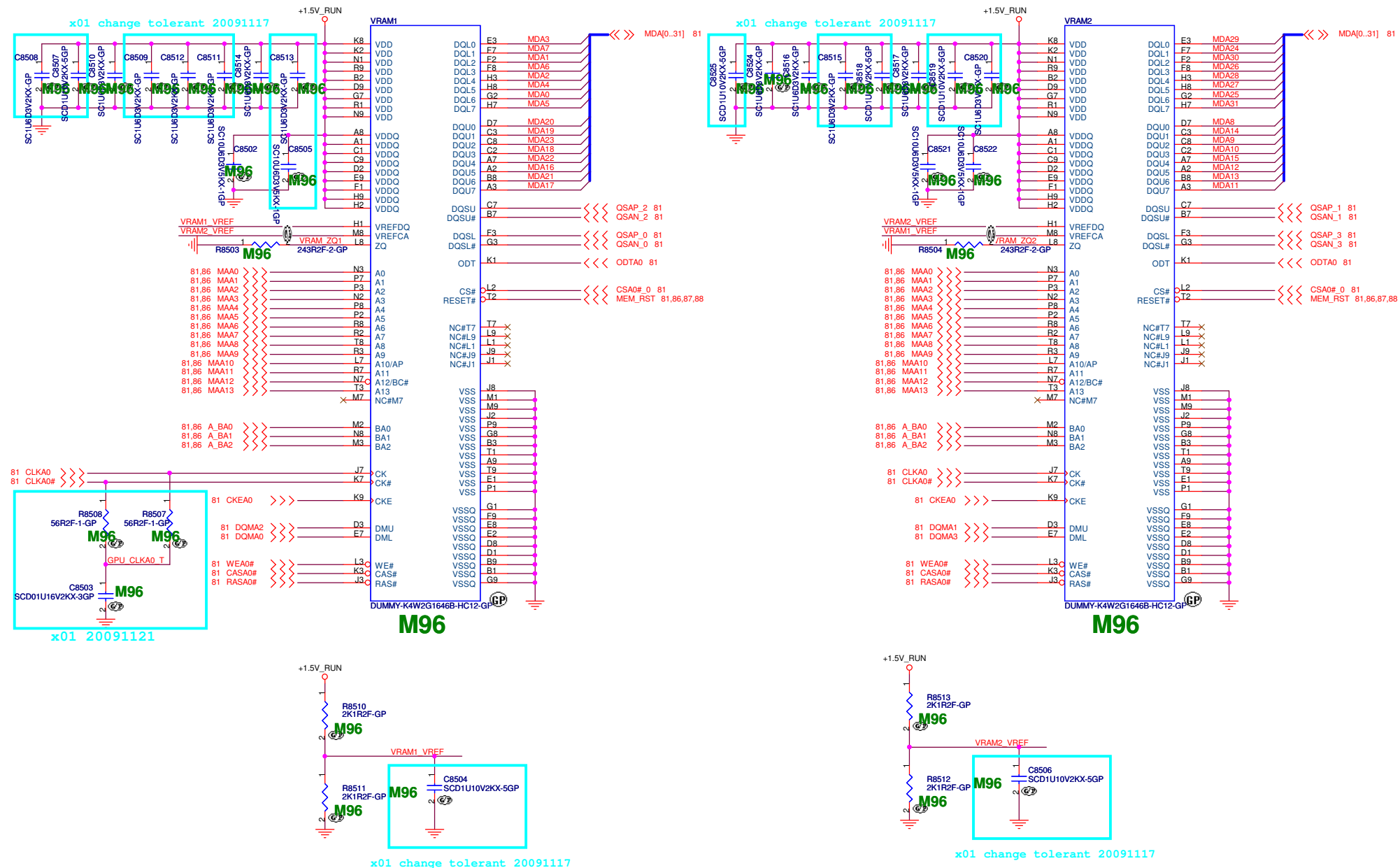


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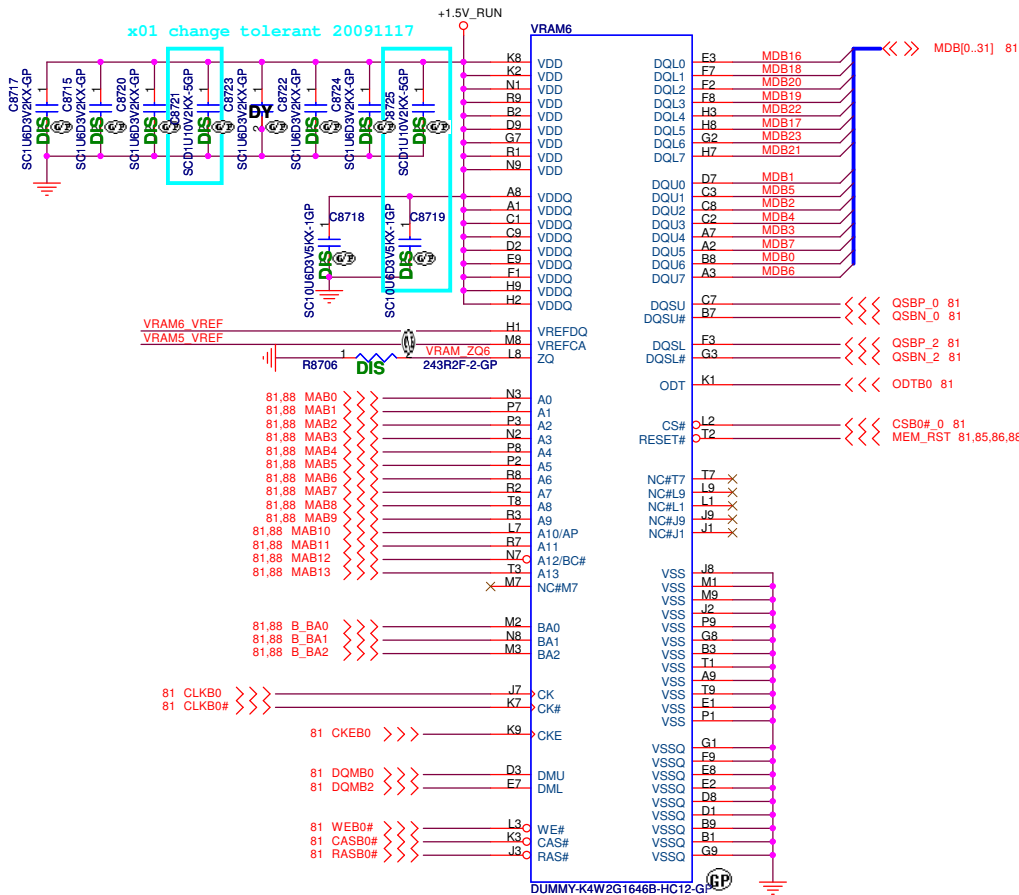
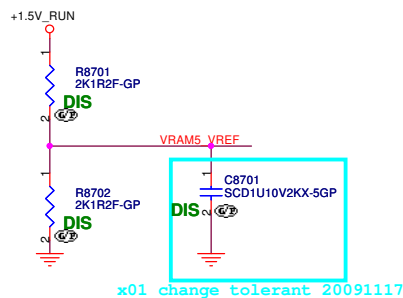
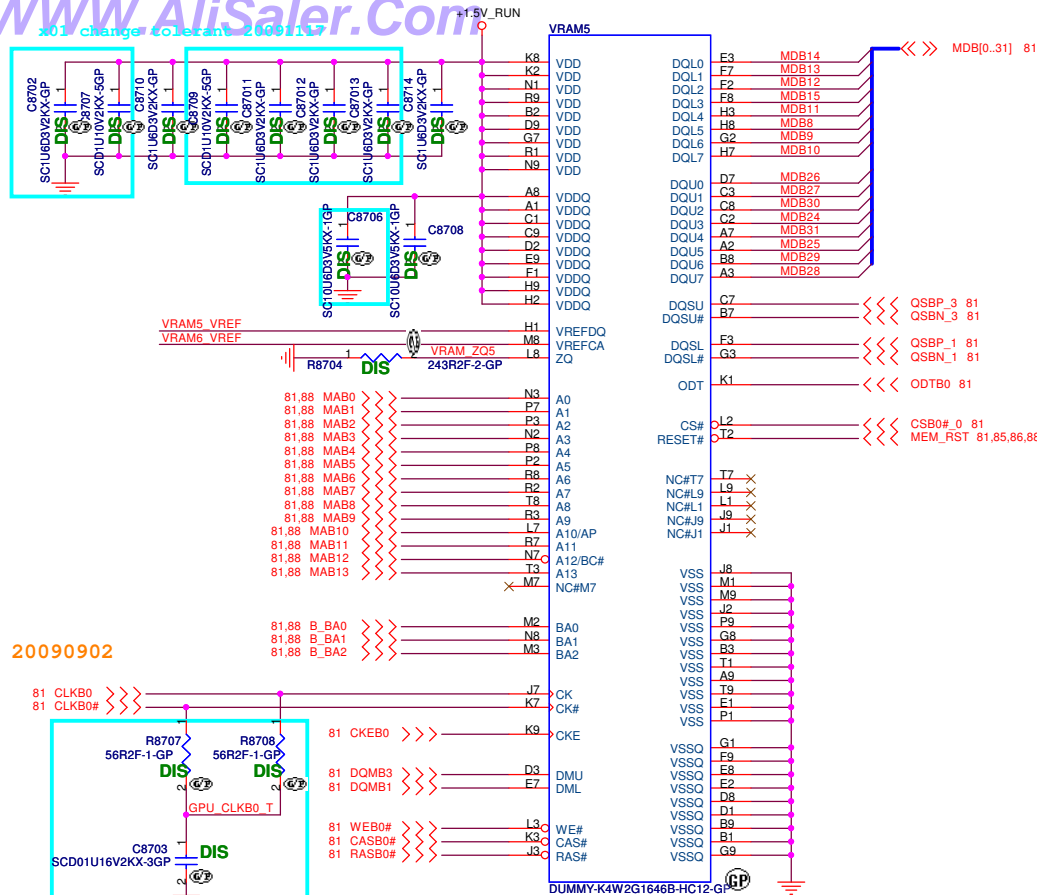
[illegible]



For M97/M96, DPF_VDD18 can be shared with DPE_VDD18
 For M97/M96, DPF_VDD10 can be shared with DPE_VDD10
 For dual link DVI using DPA AND DPB, DPA_VDDxx and DPB_VDDxx can be shared respectively
 For dual link DVI using DPC AND DPD, DPC_VDDxx and DPD_VDDxx can be shared respectively
 For dual link LVDS, DPE_VDDxx and DPF_VDDxx can be shared respectively



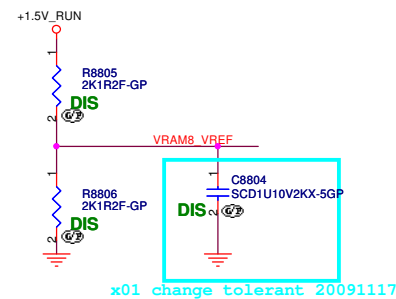
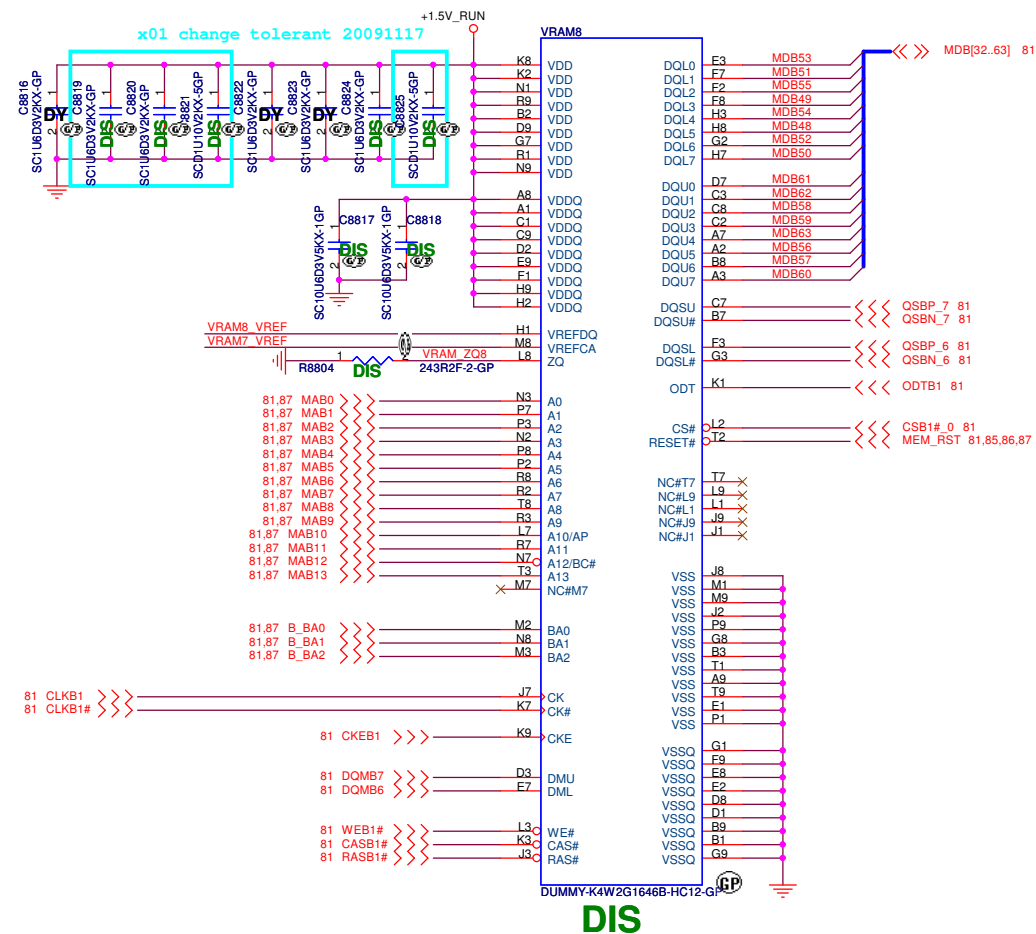
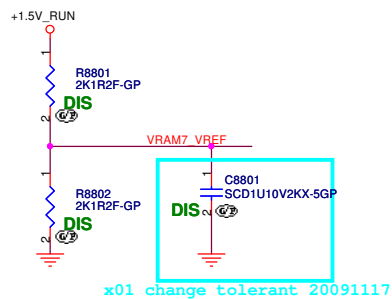
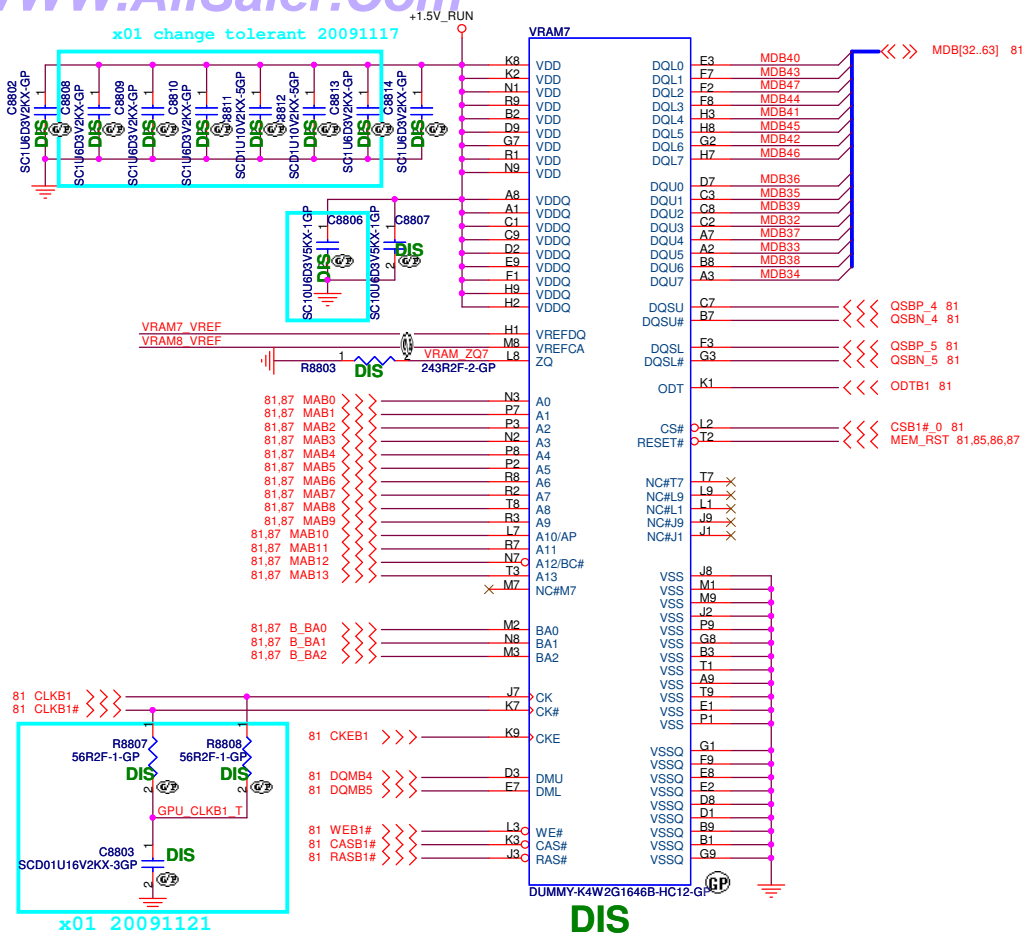




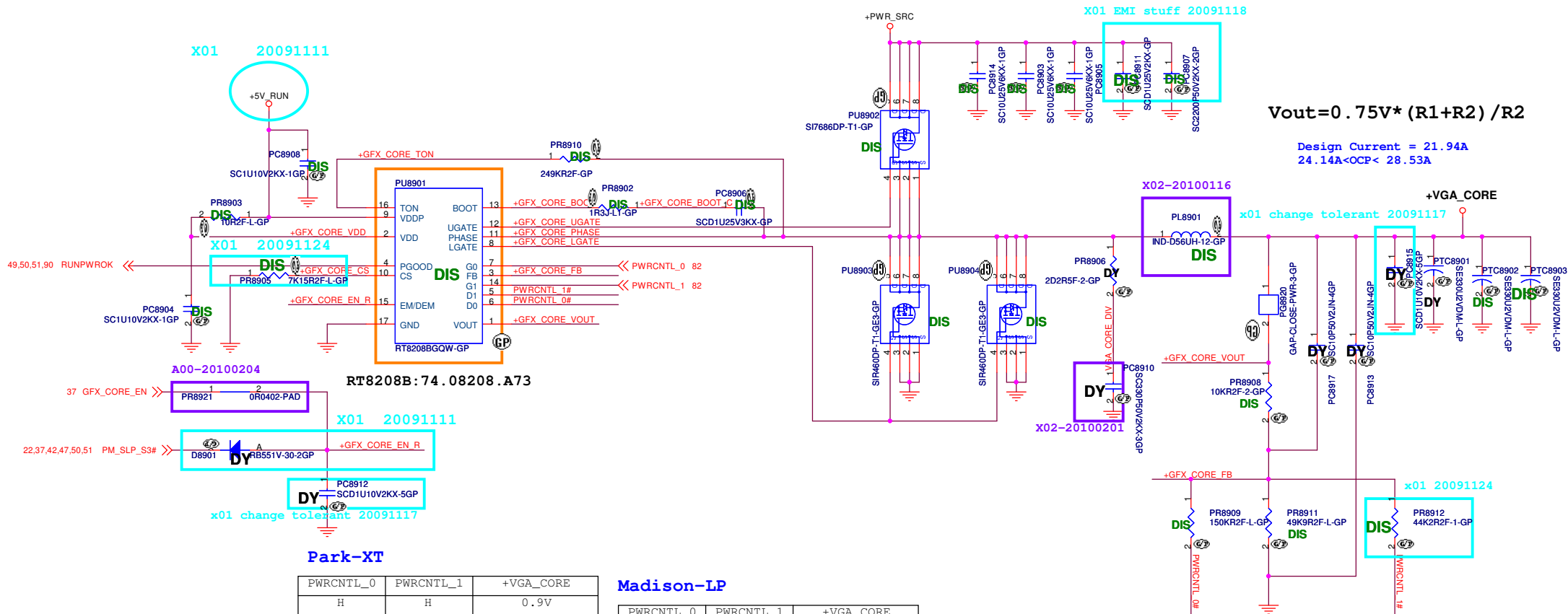
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Taipei Hsien 221, Taiwan, R.O.C.

Title			GPU-VRAM5,6 (3/4)	
Size	Document Number	Rev		
A3	Berry	X01		
Date: Wednesday, February 24, 2010		Sheet	87	of 92



RT8208BGQW for +VGA CORE



PWRCNTL_0	PWRCNTL_1	+VGA_CORE
H	H	0.9V
L	H	0.95V
H	L	1.05V
L	L	1.12V

Madison-LP

PWRCNTL_0	PWRCNTL_1	+VGA_CORE
H	H	0.9V
L	H	0.95V

A00-20100224

PWRCNTL_0	PWRCNTL_1	+VGA_CORE
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L	H	0.95V
L	L	1.0V

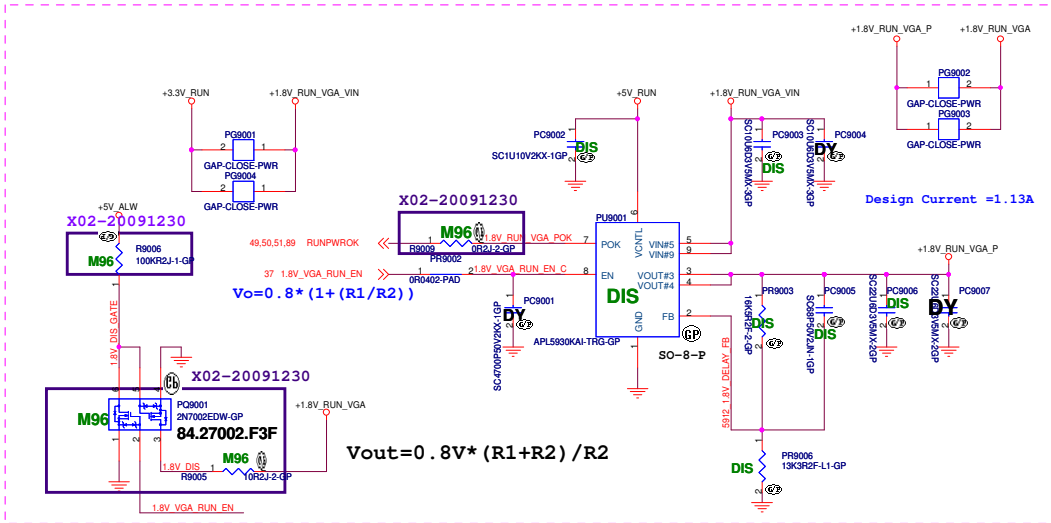
I/P cap: 10U 25V K1206 X5R/ 78.10622.52L
Inductor: 0.56uH PCMC104T-R56MN Cyntec DCR:1.6mohm/1.8mohm Isat=25Arms 68.R5610.10D
O/P cap: 330U 2.5V PSLV0E337M(15) 15mOhm 2.886Arms NEC_TOKIN/ 77.C3371.10L
H/S: SI7686DP/ POWERPAK-8/11mOhm/14mOhm@4.5Vgs/ 84.07686.037
L/S: SiR460DP/ POWERPAK-8/ 4.9mOhm/6.1mOhm@4.5Vgs/ 84.00460.037

<Core Design>

DELL

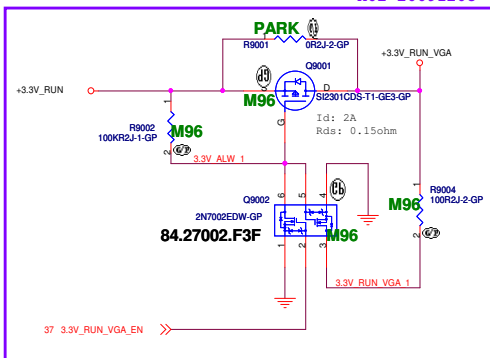
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
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Size	Document Number	Rev	
A3	Arsenal DJ1 Discrete	X01	
Date:	Wednesday, February 24, 2010	Sheet	89 of 92

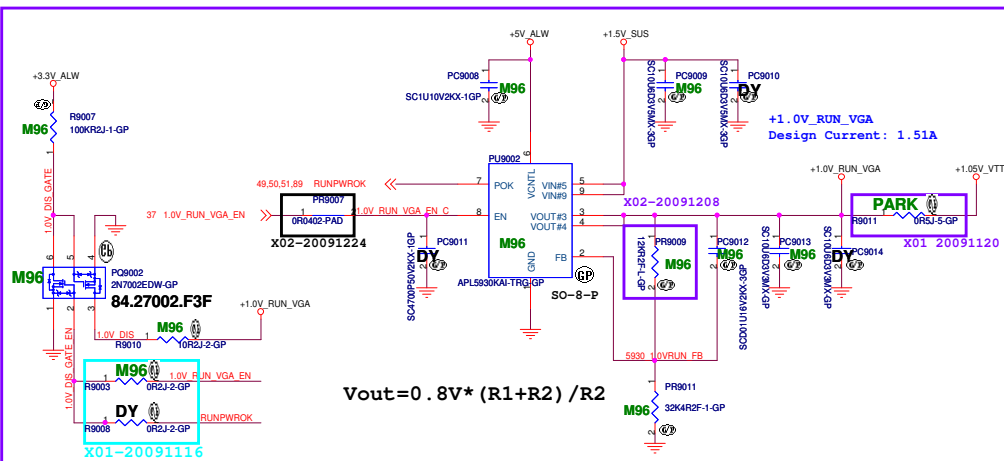


+3.3V_RUN_VGA

X02-20091208



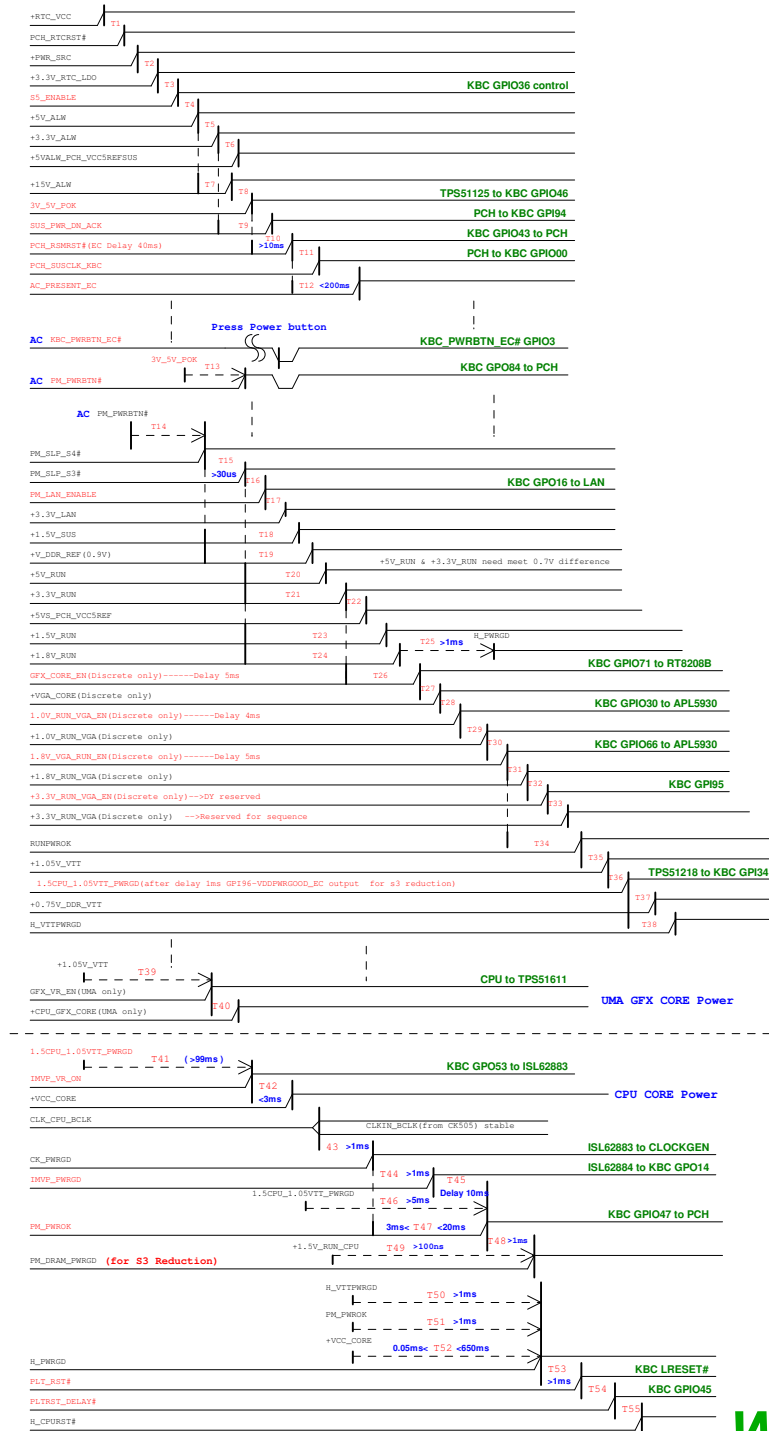
APL5930KAI for +1.0V_RUN_VGA



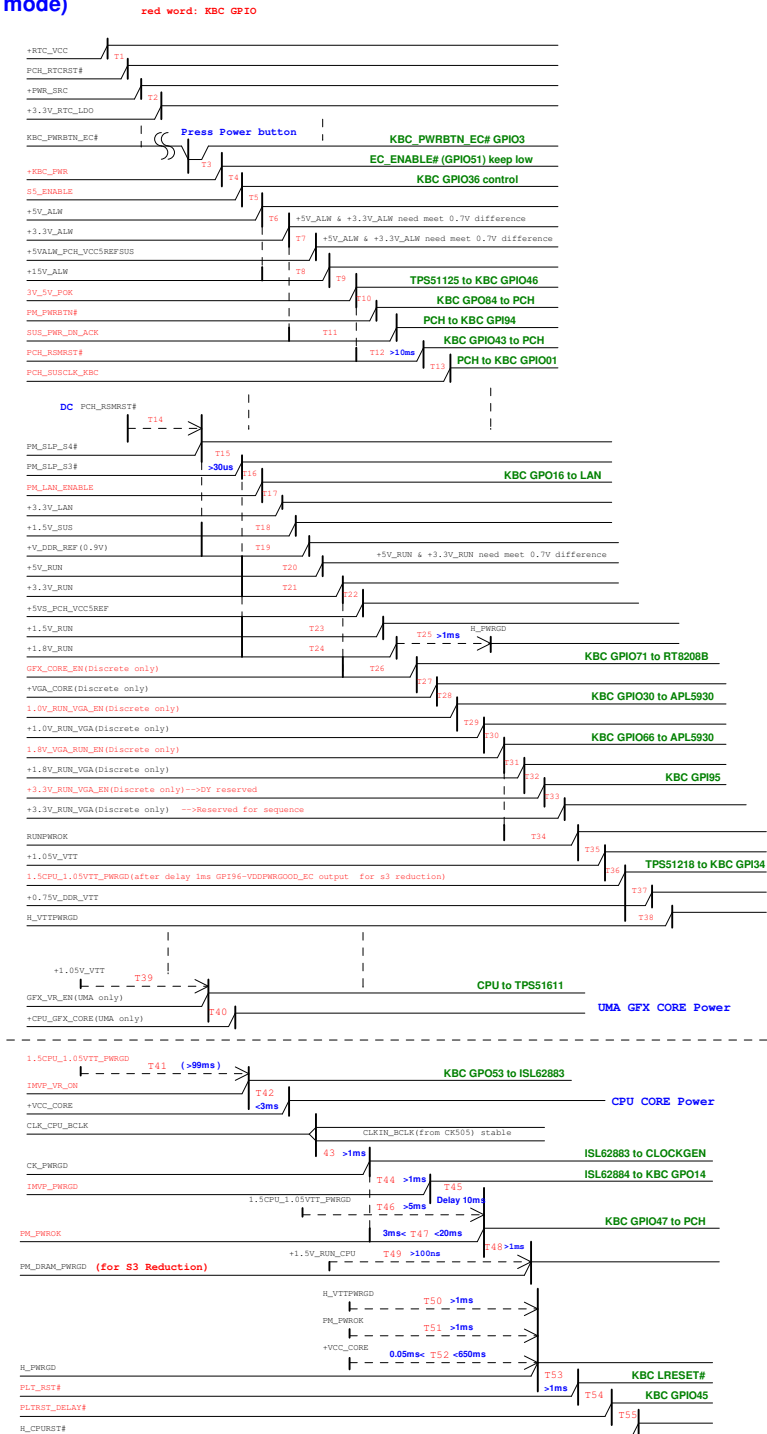
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DISCRETE VGA POWER			
Size	Document Number	Rev	
C	Berry	X01	
Date:	Wednesday, February 24, 2010	Sheet	90 of 92




(DC mode)



(Blanking)

<Core Design>



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Title

Change History

Size A3	Document Number Berry	Rev X01
Date: Wednesday, February 24, 2010	Sheet 92 of	92